INSTRUMENTS

## TMS320C4x General-Puroose Applications

## User's Guide

User's Guide

TMS320C4x GeneralPurpose Applications

# TMS320C4x General-Purpose Applications User's Guide 

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## Preface

## Read This First

## About This Manual

This user's guide serves as an applications reference book for the TMS320C40 and TMS320C44 digital signal processors (DSP). Throughout the book, all references to the TMS320C4x apply to both devices (exceptions are noted).

Specifically, this book complements the TMS320C4x User's Guide by providing information to assist managers and hardware/software engineers in application development. It includes example code and hardware connections for various applications.

The guide shows how to use the instruction set, the architecture, and the 'C4x interface. It presents examples for frequently used applications and discusses more involved examples and applications. It also defines the principles involved in many applications and gives the corresponding assembly language code for instructional purposes and for immediate use. Whenever the detailed explanation of the underlying theory is too extensive to be included in this manual, appropriate references are given for further information.

## How to Use This Manual

The following table summarizes the information contained in this user's guide:

| If you are looking for <br> information about: | Turn to these chapters: |
| :--- | :--- |
| Arithmetic | Chapter 3, Logical and Arithmetic Operations |
| Communication Ports | Chapter 8, Using the Communication Ports |
| Companding | Chapter 6, Applications-Oriented Operations <br> Development Support |
| Chapter 10, Development Support and Part Or- <br> der Information |  |


| If you are looking for <br> information about: | Turn to these chapters: |
| :--- | :--- |
| DMA Coprocessor | Chapter 7, Programming the DMA Coprocessor |
| FTTs | Chapter 6, Applications-Oriented Operations |
| Filters | Chapter 6, Applications-Oriented Operations |
| Ordering Parts | Chapter 10, Development Support and Part Or- <br> der Information |
| Repeat Modes | Chapter 2, Program Control <br> Reset |
| Stacks | Chapter 1, Processor Initialization 2, Program Control |
| Tips | Chapter 5, Programming Tips |
| Wait States | Chapter 4, Memory Interfacing |
| XDS510 Emulator | Chapter 11, XDS510 Emulator Design Consider- <br> ations |

## Style and Symbol Conventions

This document uses the following conventions:
$\square$ Program listings, program examples, file names, and symbol names are shown in a special font. Examples use a bold version of the special font for emphasis. Here is a sample program listing segment:

## *

LOOP 1 RPTB MAX
CMPF *ARO,R0 ; Compare number to the maximum
MAX LDFLT *ARO,RO ;If greater, this is a new max
B NEXT
LOOP2 RPTB MIN
CMPF *ARO++(1),RO ; Compare number to the minimum MIN LDFLT *-ARO (1),R0 ;If smaller, this is new minimum NEXT
.

- Throughout this book MSB indicates the most significant bit and LSB indicates the least significant bit. MS indicates the most significant byte and LS indicates the least significant byte.


## Information About Cautions and Warnings

This book may contain cautions and warnings.

This is an example of a caution statement.
A caution statement describes a situation that could potentially damage your software or equipment.

This is an example of a warning statement.
A warning statement describes a situation that could potentially cause harm to you.

The information in a caution or a warning is provided for your protection. Please read each caution and warning carefully.

## Related Documentation From Texas Instruments

The following books describe the TMS320 floating-point devices and related support tools. To obtain a copy of any of these TI documents, call the Texas Instruments Literature Response Center at (800) 477-8924. When ordering, please identify the book by its title and literature number.

TMS320C4x User's Guide (literature number SPRU063) describes the 'C4x 32-bit floating-point processor, developed for digital signal processing as well as parallel processing applications. Covered are its architecture, internal register structure, instruction set, pipeline, specifications, and operation of its six DMA channels and six communication ports.

TMS320C4x Parallel Processing Development System Technical Reference (literature number SPRU075) describes the TMS320C4x parallel processing system, a system with four C4xs with shared and distributed memory.

Parallel Processing with the TMS320C4x (literature number SPRA031) describes parallel processing and how the 'C4x can be used in parallel processing. Also provides sample parallel processing applications.

TMS320C3x/C4x Assembly Language Tools User's Guide (literature number SPRU035) describes the assembly language tools (assembler, linker, and other tools used to develop assembly language code), assembler directives, macros, common object file format, and symbolic debugging directives for the ' C 3 x and ' C 4 x generations of devices.
TMS320 Floating-Point DSP Optimizing C Compiler User's Guide (literature number SPRU034) describes the TMS320 floating-point C compiler. This C compiler accepts ANSI standard C source code and produces TMS320 assembly language source code for the 'C3x and 'C4x generations of devices.

TMS320C4x C Source Debugger User's Guide (literature number SPRU054) tells you how to invoke the 'C4x emulator and simulator versions of the C source debugger interface. This book discusses various aspects of the debugger interface, including window management, command entry, code execution, data management, and breakpoints. It also includes a tutorial that introduces basic debugger functionality.

TMS320C4x Technical Brief (literature number SPRU076) gives a condensed overview of the 'C4x DSP and its development tools. It also lists TMS320C4x third parties.

TMS320 Family Development Support Reference Guide (literature number SPRU011) describes the '320 family of digital signal processors and the various products that support it. This includes code-generation tools (compilers, assemblers, linkers, etc.) and system integration and debug tools (simulators, emulators, evaluation modules, etc.). This book also lists related documentation, outlines seminars and the university program, and gives factory repair and exchange information.
TMS320 Third-Party Support Reference Guide (literature number SPRU052) alphabetically lists over 100 third parties that supply various products that serve the family of '320 digital signal processors-software and hardware development tools, speech recognition, image processing, noise cancellation, modems, etc.
TMS320 DSP Designer's Notebook: Volume 1 (literature number SPRT125) presents solutions to common design problems using ' C 2 x , 'C3x, 'C4x, 'C5x, and other TI DSPs.

## Related Articles and Books

A wide variety of related documentation is available on digital signal processing. These references fall into one of the following application categories:
$\square$ General-Purpose DSP
$\square$ Graphics/Imagery
$\square$ Speech/Voice
$\square$ Control
$\square$ Multimedia
$\square$ Military
$\square$ Telecommunications
$\square$ Automotive
$\square$ Consumer
$\square$ Medical
$\square$ Development Support
In the following list, references appear in alphabetical order according to author. The documents contain beneficial information regarding designs, operations, and applications for signal-processing systems; all of the documents provide additional references. Texas Instruments strongly suggests that you refer to these publications.

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## If You Need Assistance. . .

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## Processor Initialization

Before you execute a DSP algorithm, it is necessary to initialize the processor. Initialization brings the processor to a known state. Generally, initialization takes place any time after the processor is reset. This chapter reviews the concepts explained in the user's guide and provides examples.
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### 1.1 Reset Process

After $\overline{\mathrm{RESET}}$ is applied, the 'C4x jumps to the address stored in the reset vector location and starts execution from that point.

In order to reset the 'C4x correctly, you need to comply with several hardware and software requirements:

- Select the reset vector location:
- The RESET vector of the ' C 4 x can be mapped to one of four different locations that are controlled by the value of the RESETLOC $(1,0)$ pins at RESET. Table $1-1$ shows possible reset vectors for the ' C 40 and 'C44.
- If the DSP is in microcomputer mode (ROMEN pin =1), RESET$\operatorname{LOC}(1,0)$ must be equal to 0,0 for the boot loader to operate correctly.
- If the DSP is in microcomputer mode, set the IIOFx pins as discussed in the bootloader chapter TMS320C4x User's Guide so that the bootloader works properly.
- Provide the correct reset vector value:

■ The RESET vector normally contains the address of the system initialization routine.

■ In microcomputer mode the reset vector is initialized automatically by the processor to point to the beginning of the on-chip boot loader code. No user action is required.

- In microprocessor mode, the reset vector is typically stored in an EPROM. Example 1-1 shows how you can initialize that vector.
- Apply a low level to the RESET input. (See section 1.2).

Table 1-1. RESET Vector Locations in the 'C40 and 'C44

| Value at RESETLOCx Pin |  | Get Reset Vector From <br> Hex Memory Address |  |
| :---: | :---: | :--- | :--- |
| RESETLOC1 | RESETLOC0 | Bus |  |
| 0 | 0 | 000000000 | Local |
| 0 | 1 | $07 F F F$ FFFF $\dagger$ | Local |
| 1 | 0 | $080000000 \dagger$ | Global |
| 1 | 1 | 0FFFF FFFF $\dagger$ | Global |

[^0]
### 1.2 Reset Signal Generation

Several aspects of ' C 4 x system hardware design are critical to overall system operation. One such aspect is reset signal generation.

The reset input controls initialization of internal 'C4x logic and execution of the system initialization software. For proper system initialization, the $\overline{R E S E T}$ signal must be applied for at least ten H 1 cycles, that is, 400 ns for a 'C 4 x operating at 50 MHz . Upon power up, however, it can take 20 ms or more before the system oscillator reaches a stable operating state. Therefore, the power-up reset circuit should generate a low pulse on the $\overline{\operatorname{RESET}}$ pin for 100 to 200 ms . Once a proper reset pulse has been applied, the processor fetches the reset vector from location zero, which contains the address of the system initialization routine. Figure $1-1$ shows a circuit that will generate an appropriate pow-er-up or push-button reset signal.

Figure 1-1. Reset Circuit


The voltage on the $\overline{\mathrm{RESET}}$ pin is controlled by the $\mathrm{R}_{1} \mathrm{C}_{1}$ network. After a reset, this voltage rises exponentially according to the time constant $R_{1} C_{1}$, as shown in Figure 1-2. In Figure 1-1, the 74ALS34 provides a clean RESET signal to the ' $C 4 x$.

Figure 1-2. Voltage on the $\overline{R E S E T}$ Pin


The duration of the low pulse on the RESET pin is approximately $\mathrm{t}_{1}$, which is the time it takes for the capacitor $\mathrm{C}_{1}$ to be charged to 1.5 V . This is approximately the voltage at which the reset input switches from a logic 0 to a logic 1. The capacitor voltage is expressed as

$$
\begin{equation*}
V=V_{c C}\left[1-e^{-\frac{t}{\tau}}\right] \tag{5}
\end{equation*}
$$

where $\tau=\mathrm{R}_{1} \mathrm{C}_{1}$ is the reset circuit time constant. Solving (5) for $t$ results in

$$
\begin{equation*}
t=-R_{1} C_{1} \ln \left[1-\frac{V}{V_{c c}}\right] \tag{6}
\end{equation*}
$$

Setting the following:
$\mathrm{R}_{1}=100 \mathrm{k} \Omega$
$\mathrm{C}_{1}=4.7 \mu \mathrm{~F}$
$\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}$
$\mathrm{V}=\mathrm{V}_{1}=1.5 \mathrm{~V}$
results in $\mathrm{t}=167 \mathrm{~ms}$. Therefore, the reset circuit of Figure 1-1 provides a low pulse for a long enough time to ensure the stabilization of the system oscillator upon powerup.

Note:
Reset does not have internal Schmidt hysteresis. To ensure proper reset operation, avoid low rise and fall times. Rise/fall time should not exceed one CLKIN cycle.

### 1.3 Multiprocessing System Reset Considerations

If synchronization of multiple 'C4x DSPs is required, all processors should be provided with the same input clock and the same reset signal. After powerup, when the clock has stabilized, set RESET high for a few $\mathrm{H} 1 / \mathrm{H} 3$ cycles and then set it low to synchronize their $\mathrm{H} 1 / \mathrm{H} 3$ clock phases. Following the falling edge, RESET should remain low for at least ten H 1 cycles and then be driven high. The circuit in Figure 1-1 can be used for RESET generation.

Pullup resistors are recommended at each end of the connection to avoid unintended triggering after reset when $\overline{\text { RESET going low is not received on all ' } \mathrm{C} 4 \mathrm{x}}$ devices at the same time.

It is recommended that you power up the system with RESET low. This prevents 'C4x asynchronous signals from driving unknown values before RESET goes low, which could create bus contention in communication-port pins, resulting in damage to the device.

### 1.4 How to Initialize the Processor

After reset, the C 4 x jumps to the address stored in the reset vector location and starts execution from that point. The RESET vector normally contains the address of the system initialization routine.
The initialization routine should typically perform several tasks:

- Set the DP register.
- Set the stack pointer.
- Set the interrupt vector table.
- Set the trap vector table.
- Set the memory control register.
- Clear/enable cache.


## Note:

When running under microcomputer mode (ROMEN =1). The address stored in the reset vector location points to the beginning of the bootloader code. The on-chip bootloader automatically initializes the memory-control register values from the bootloader table

The following examples illustrate how to initialize the ' C 4 x when using assembly language and when using C .

## Processor initialization under assembly language

If you are running under an assembly-only environment, Example 1-1 provides a basic initialization routine. This example shows code for initializing the ' C 4 x to the following machine state:

- Timer 0 interrupt is enabled.
- Trap 0 is initialized.
- The program cache is enabled.
- The DP is initialized to point to the .text section.
$\square$ The stack pointer is initialized to the beginning of the mystack section.
- The memory control registers are initialized.
- The 'C4x is initialized to run in microcontroller mode with the reset vector located at address 08000 0000h (RESETLOC( 1,0 )=1,0).
- The program has already been loaded into memory location at address = 0x4000 0000.

You need to allocate the section addresses using a linker command file (see the TMS320 Floating-Point DSP Assembly Language Tools User's Guide book for more information about linker command files) as shown in Example 1-2.

## Example 1-1.Processor Initialization Example

```
;
; Create Reset Vector
;
.sect "rst_sect" ;Named section for RESET vector
reset .word init ;RESET vector
;
; Create Interrupt Vector Table
;
_myvect .sect "myvect" ;Named section for int. vectors
    .space 2 ;Reserved space
    .word tint0 ;Timer 0 ISR address
;
; Create Trap Vector Table
;
mytrap .sect "mytrap" ; named section for trap vectors
    .word trap0 ;Trap 0 subroutine address
;
; Create Stack
_mystack.usect"mystack",500 ; reserve 500 locations for
                                    ; stack
    .text
stacka .word _mystack ; address of mystack section
ivta .word _myvect ; address of myvect section
tvta .word _mytrap ; address of mytrap section
ieval .word \overline{1} ; IE register value
gctrl .word ???????? ; target board specific
lctrl .word ???????? ; target board specific
mctrla .word 100000h ; address of the global memory
    ; control register
init:
;
Initialize the DP Register
    ldp stacka
; Set Expansion Register IVTP
;
    LDI @ivta,AR0
    LDPE ARO,IVTP
;
; Set Expansion Register TVTP
;
    LDI @tvta,AR0
```


## Example 1-1. Processor Initialization Example (Continued)

```
; Initialize global memory interface control
;
    ldi @mctrla,ar0
    LDI @gctrl,R0
    STI R0,*AR0
;
; Initialize local memory interface control
;
    LDI @lctrl,R0
    STI RO,* +ARO(4)
;
; Initialize the Stack Pointer
;
    LDI @stacka,SP
;
; Enable timer interrupt
        This is equivalent to ldi 1,iie
            LDI @ieval,IIE
        Clear/Enable Cache and Enable Global Interrupts
    OR 3800H,ST ;
;
; Global interrupt enable
;
    BR BEGIN ; Branch to the beginning of
                            ; the application
begin
< this is your application code>
trap0
    .. < this is your trap0 trap code>
tint0
    .. < this is your tint0 interrupt
    service routine>
    reti
    . end
```


## Example 1-2.Linker Command File for Linking the Previous Example

```
MEMORY
{
    EPROM: org = 0x80000000 len = 0x10 /* EPROM reset vector location */
    RAM: org = 0x40000000 len = 0x100 /* extend RAM */
}
    /* SPECIFY THE SECTIONS ALLOCATION INTO MEMORY */
    SECTIONS
    {
        rst_sect: > EPROM
        myvect: > RAM
        mystack: > RAM
        .text: > RAM
        mytrap: > RAM
    }
```


## Processor initialization under C language

If you are running under a C environment, your initialization routine is typically boot.asm (from the RTS40.LIB library that comes with the floating-point compiler). In addition to initializing global variables, boot.asm initializes the DP register (pointing to the .bss section) and the SP register (pointing to the .stack section). You need to enable the cache, as shown in Example 1-3, and setup your interrupts inside your main routine before you enable interrupts. See the Application Report, Setting Up TMS320 DSP Interrupts in C (SPRA036), for more information.

Example 1-3.Enabling the Cache

```
main() {
asm(" or 1800,st") ; enable cache
/* asm(" or 3800,st") */ ; enable cache and interrupts
}
```


## Program Control

Several ' C 4 x instructions provide program control and facilitate high-speed processing. These instructions directly handle:

- Regular and zero-overhead subroutine calls
- Software stack
- Interrupts
- Delayed branches
- Single- and multiple-instruction loops without overhead
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### 2.1 Subroutines

The 'C4x provides two ways to invoke subroutine calls: regular calls and zerooverhead calls. The regular and zero-overhead subroutine calls use the software stack and extended-precision register R11, respectively, to save the return address. The following subsections use example programs to explain how this works.

### 2.1.1 Regular Subroutine Calls

The 'C4x has a 32-bit program counter (PC) and a virtually unlimited software stack. The CALL and CALLcond subroutine calls increment the stack pointer and store the contents of the next value of the PC counter on the stack. At the end of the subroutine, RETScond performs a conditional return.

Example 2-1 illustrates the use of a subroutine to determine the dot product of two vectors. Given two vectors of length N , represented by the arrays a[0], $\mathrm{a}[1], \ldots, a[\mathrm{~N}-1]$ and $\mathrm{b}[0], \mathrm{b}[1], \ldots, \mathrm{b}[\mathrm{N}-1]$, the dot product is computed from the expression
$d=a[0] b[0]+a[1] b[1]+\ldots+a[N-1] b[N-1]$
Processing proceeds in the main routine to the point where the dot product is to be computed. It is assumed that the arguments of the subroutine have been appropriately initialized. At this point, a CALL is made to the subroutine, transferring control to that section of the program memory for execution, then returning to the calling routine via the RETS instruction when execution has completed. Note that for this particular example, it would suffice to save the register R2. However, a larger number of registers are saved for demonstration purposes. The saved registers are stored on the system stack, which should be large enough to accommodate the maximum anticipated storage requirements. Other methods of saving registers could be used equally well.

## Example 2-1.Regular Subroutine Call (Dot Product)

```
*
* TITLE REGULAR SUBROUTINE CALL (DOT PRODUCT)
* MAIN ROUTINE THAT CALLS THE SUBROUTINE 'DOT' TO COMPUTE THE
* DOT PRODUCT OF TWO VECTORS.
    .
    LDI @blk0,AR0 ;AR0 points to vector a
    LDI @blk1,AR1 ;AR1 points to vector b
    LDI N,RC ;RC contains the number of elements
    CALL DOT
    .
*
*SUBROUTINE DOT
**
*EQUATION: d = a(0) * b(0) + a(1) * b(1) + ... + a(N-1) * b (N-1)
*
*THE DOT PRODUCT OF a AND b IS PLACED IN REGISTER RO. N MUST
*BE GREATER THAN OR EQUAL TO 2.
*
* ARGUMENT ASSIGNMENTS:
* ARGUMENT | FUNCTION
* -------------- +-------------------------------
* AR0 ADDRESS OF a (0)
* AR1 ADDRESS OF b(0)
* RC LENGTH OF VECTORS (N)
* REGISTERS USED AS INPUT: AR0, AR1, RC
* REGISTER MODIFIED: RO
* REGISTER CONTAINING RESULT: R0
*
.global DOT
*
DOTPUSH ST ;Save status register
    PUSH R2 ;Use the stack to save R2's
    PUSHF R2 ;bottom 32 and top 32 bits
    PUSH ARO ; Save AR0
    PUSH AR1 ; Save AR1
    PUSH RC ; Save RC
    PUSH RS
    PUSH RE
*
* Initialize R0:
    MPYF3 *AR0,*AR1,R0;a(0) * b(0) -> R0
```


## Example 2-1.Regular Subroutine Call (Dot Product) (Continued)

| 11 | $\begin{aligned} & \text { SUBF } \\ & \text { SUBI } \end{aligned}$ | $\begin{aligned} & \mathrm{R} 2, \mathrm{R} 2, \mathrm{R} 2 \\ & 2, \mathrm{RC} \end{aligned}$ | ; Initialize R2. <br> ; Set $R C=N-2$ |
| :---: | :---: | :---: | :---: |
| * |  |  |  |
| * |  |  |  |
| * | DOT PRODUCT | $(1<=i<N)^{*}$ |  |
|  | RPTS | RC | ; Setup the repeat single. |
|  | MPYF 3 | *++AR0 (1) , *++AR1 (1) , R0 | ; a(i) * b (i) -> R0 |
| \| | ADDF 3 | R0,R2,R2 | ; $\mathrm{a}(\mathrm{i}-1) * \mathrm{~b}(\mathrm{i}-1)+\mathrm{R} 2->\mathrm{R} 2$ |
| * | ADDF 3 | R0, R2, R0 | ; $\mathrm{a}(\mathrm{N}-1) * \mathrm{~b}(\mathrm{~N}-1)+\mathrm{R} 2 \rightarrow \mathrm{R} 0$ |
| * |  |  |  |
| * | RETURN SEQU | ENCE |  |
|  | POP | RE |  |
|  | POP | RS |  |
|  | POP | RC | ; Restore RC |
|  | POP | AR1 | ; Restore AR1 |
|  | POP | AR0 | ; Restore AR0 |
|  | POPF | R2 | ; Restore top 32 bits of R2 |
|  | POP | R2 | ; Restore bottom 32 bits of R2 |
|  | POP | ST | ;Restore ST |
|  | RETS |  | ; Return |
| * |  |  |  |
|  | end |  |  |
| * |  |  |  |
| . end |  |  |  |

### 2.1.2 Zero-Overhead Subroutine Calls

Two instructions, link and jump (LAJ) and link and jump conditional (LAJcond), implement zero-overhead subroutine calls to be implemented on the 'C4x. Unlike CALL and CALLcond, which put the value of PC +1 into the software stack, LAJ and LAJcond put the value of PC +4 into extended-precision register R11. Three instructions following LAJ or LAJcond are executed before going to the subroutine. The restriction that applies to these three instructions is the same as that of the three instructions following a delayed branch. At the end of the subroutine, you can use a delayed branch conditional, BcondD, in the register addressing mode with R11 as source, to perform a zero-overhead subroutine return.

For comparison, the same dot product example with a zero-overhead subroutine call is given in the following example program.

Example 2-2.Zero-Overhead Subroutine Call (Dot Product)

```
* TITLE ZERO-OVERHEAD SUBROUTINE CALL (DOT PRODUCT)
*
* MAIN ROUTINE THAT CALLS THE SUBROUTINE 'DOT' TO COMPUTE THE
* DOT PRODUCT OF TWO VECTORS.
    .
    LAJ DOT
    LDI @blk0,AR0 ; AR0 points to vector a
    LDI @blk1,AR1 ; AR1 points to vector b
    LDI N,RC ; RC contains the number of elements
    •
```



```
*
*SUBROUTINE DOT
*
*EQUATION: d = a(0) * b (0) + a(1) * b(1) + ... + a(N-1) * b (N-1)
* THE DOT PRODUCT OF a AND b IS PLACED IN REGISTER RO. N MUST
* BE GREATER THAN OR EQUAL TO 2.
* ARGUMENT ASSIGNMENTS:
* ARGUMENT 
* RC LENGTH OF VECTORS (N)
*
* REGISTERS USED AS INPUT: AR0, AR1, RC
* REGISTER MODIFIED: RO
* REGISTER CONTAINING RESULT: R0
* *
*
    .global DOT
DOT PUSH ST ;Save status register
    PUSH R2 ;Use the stack to save R2's
    PUSHF R2 ;bottom 32 and top 32 bits
    PUSH ARO ; Save AR0
    PUSH AR1 ; Save AR1
    PUSH RC ; Save RC
    PUSH RS
    PUSH RE
```


## Example 2-2.Zero-Overhead Subroutine Call (Dot Product) (Continued)



### 2.2 Stacks and Queues

The 'C4x provides a dedicated stack pointer (SP) for building stacks in memory. Also, the auxiliary registers can be used to build user stacks and a variety of more general linear lists. This section discusses the implementation of the following types of linear lists:

Stack A linear list for which all insertions and deletions are made at one end of the list.

Queue A linear list for which all insertions are made at one end of the list, and all deletions are made at the other end.

Dequeue A double-ended queue linear list for which insertions and deletions are made at either end of the list.

### 2.2.1 System Stacks

A stack in the 'C4x fills from a low-memory address to a high-memory address, as is shown in Figure 2-1. A system stack stores addresses and data during subroutine calls, traps, and interrupts.

The stack pointer (SP) is a 32-bit register that contains the address of the top of the system stack. The SP always points to the last element pushed onto the stack. A push performs a preincrement, and a pop performs a postdecrement of the SP. Provisions should be made to accommodate your software's anticipated storage requirements.

The stack pointer (SP) can be read from as well as written to; multiple stacks can be created by updating the SP. The SP is not initialized by the hardware during reset; it is important to remember to initialize its value so that the it points to a predetermined memory location. Example 1-1 on page 1-7, shows how to initialize the SP. You must initialize the stack to a valid free memory space. Otherwise, use of the stack could corrupt data or program memory.

The program counter is pushed onto the system stack on subroutine calls, traps, and interrupts. It is popped from the system stack on returns. The PUSH, POP, PUSHF, and POPF instructions push and pop the system stack. The stack can be used inside of subroutines as a place of temporary storage of registers, as is the case shown in Example 2-1, on page 2-3.

Two instructions, PUSHF and POPF, are for floating-point numbers. These instructions can pop and push floating-point numbers to registers R0 - R11. This feature is very useful for saving the extended-precision registers (see Example 2-1 and Example 2-2). PUSH saves the lower 32 bits of an extendedprecision register, and PUSHF saves the upper 32 bits. To recover this exten-ded-precision number, execute a POPF followed by POP. It is important to perform the integer and floating-point PUSH and POP in the above order, since POPF forces the last eight bits of the extended-precision registers to zero.

Figure 2-1. System Stack Configuration


High Memory

### 2.2.2 User Stacks

User stacks can be built to store data from low-to-high memory or from high-tolow memory. Two cases for each type of stack are shown. You can build stacks by using the preincrement/decrement and postincrement/decrement modes of modifying the auxiliary registers (AR).

You can implement stack growth from high to low memory in two ways:
Case 1: Store to memory using *- -ARn to push data onto the stack, and read from memory using *ARn++ to pop data off the stack.

Case 2: Store to memory using *ARn-- to push data onto the stack, and read from memory using * ++ AR $n$ to pop data off the stack.

Figure 2-2 illustrates these two cases. The only difference is that in case 1 , the AR always points to the top of the stack, and in case 2, the AR always points to the next free location on the stack.

Figure 2-2. Implementations of High-to-Low Memory Stacks


You can implement stack growth from low to high memory in two ways:
Case 3: Store to memory using *++ARn to push data onto the stack, and read from memory using *ARn-- to pop data off the stack.

Case 4: Store to memory using *ARn++ to push data onto the stack, and read from memory using *--AR $n$ to pop data off the stack.

Figure 2-3 shows these two cases. In case 3, the AR always points to the top of the stack. In case 4, the AR always points to the next free location on the stack.

Figure 2-3. Implementations of Low-to-High Memory Stacks


### 2.2.3 Queues and Double-Ended Queues

The implementations of queues and double-ended queues is based upon the manipulation of the auxiliary registers for user stacks.

For queues, two auxiliary registers are used: one to mark the front of the queue from which data is popped and the other to mark the rear of the queue to where data is pushed.

For double-ended queues, two auxiliary registers are also necessary. One register marks one end of the double-ended queue, and the other register marks the other end. Data can be popped from or pushed onto either end.

### 2.3 Interrupt Examples

When using interrupts, you must consider several issues. This section offers examples of several interrupt-related topics:
$\square$ Interrupt Service Routines
$\square$ Context Switching
$\square$ Interrupt-Vector Table (IVTP)
$\square$ Interrupt Priorities

### 2.3.1 Correct Interrupt Programming

For interrupts to work properly you need to execute the following sequence of steps, as is shown in Example 1-1:

1) Set the interrupt-vector table in a 512-word boundary.
2) Initialize the IVTP register.
3) Create a software stack.
4) Enable the specific interrupt.
5) Enable global interrupts.
6) Generate the interrupt signal.

### 2.3.2 Software Polling of Interrupts

The interrupt flag register can be polled, and action can be taken, depending on whether an interrupt has occurred. This is true even when maskable interrupts are disabled. This can be useful when an interrupt-driven interface is not implemented. Example $2-3$ shows the case in which a subroutine is called when external interrupt 1 has not occurred.

## Example 2-3. Use of Interrupts for Software Polling



When interrupt processing begins, the program counter is pushed onto the stack, and the interrupt vector is loaded in the program counter. Interrupts are disabled when GIE is cleared to 0 and the program continues from the address loaded in the program counter. Because all maskable interrupts are disabled, interrupt processing can proceed without further interruption unless the interrupt service routine re-enables interrupts, or the NMI occurs.

### 2.3.3 Using One Interrupt for Two Services

The IVTP can be changed to point to alternate interrupt-vector tables. This relocatable feature of the table allows you to use a single interrupt signal for more than one service.

In Example 2-4, the IVTP is reset in the external INTO interrupt service routines EINTOA and EINTOB. After the value of the IVTP is changed, the CPU goes to a different interrupt service routine when the same interrupt signal reoccurs.

## Example 2-4.Use of One Interrupt Signal for Two Different Services

```
* TITLE USE OF ONE INTERRUPT SIGNAL FOR TWO DIFFERENT SERVICES
* IN THIS EXAMPLE, THE ADDRESS OF EINTOA AND EINTOB ARE IN
* MEMORY LOCATION 03H AND 1003H, RESPECTIVELY. ASSUME THE IVTP
* HAS NOT BEEN CHANGED AFTER DEVICE RESET AND THE EXTERNAL
* INTERRUPT IIOFO IS ENABLED. WHEN THE FIRST IIOFO INTERRUPT
* SIGNAL COMES IN, THE EINTOA ROUTINE WILL BE EXECUTED AND THEN
* IF THE NEXT IIOFO INTERRUPT SIGNAL OCCURS, THE EINTOB ROUTINE
* WILL BE EXECUTED, AND SO ON. THE EINTOA AND EINTOB ROUTINES
* WILL TAKE TURNS TO BE EXECUTED WHEN THE IIOFO INTERRUPT
* SIGNAL OCCURS.
* External IIOFO interrupt service routine A
*
    .global EINTOA
EINTOA:
    LDI 1000H,R0 ;Change IVTP to point to 1000H
    LDPE R0,IVTP
    .
    RETI ;Return and enable interrupts
*
* External IIOFO interrupt service routine A
*
EINT0B:
    •
        LDI 0,R0 ; Change IVTP to point to 0
        LDPE R0,IVTP
        .
        RETI
    ;Return and enable interrupts
```


### 2.3.4 Nesting Interrupts

In Example 2-5, the interrupt service routine for INT2 temporarily modifies the interrupt enable register (IIE) and interrupt flag register (IIF) to permit interrupt processing when an interrupt to INTO or NMI (but no other interrupt) occurs. When the routine finishes processing, the IIE register is restored to its original state. Notice that the RETIcond instruction not only pops the next program counter address from the stack, but also restores GIE and CF bits from the PGIE and PCF bits. This re-enables all interrupts that were enabled before the INT2 interrupt was serviced.

Example 2-5. Interrupt Service Routine

```
* TITLE INTERRUPT SERVICE ROUTINE
.global ISR2
ENABLE .set 2000h
MASK .set 9h
*
* INTERRUPT PROCESSING FOR EXTERNAL INTERRUPT INT2-
*
ISR2:
    PUSH ST ;Save status register
    PUSH DP ; Save data page pointer
    PUSH IIE ;Save interrupt enable register
    PUSH IIF ;
    PUSH RO ; Save lower 32 bits and
    PUSHF R0 ;upper 32 bits of R0
    PUSH R1 ; Save lower 32 bits and
    PUSHF R1 ;upper 32 bits of R1
    LDI 0,IIE ;Unmask all internal interrupts
    LDI MASK, R0
    MHO R0, IIF ;Enable INT2
    OR ENABLE,ST ;Enable all interrupts
*
* MAIN PROCESSING SECTION FOR ISR2
    .
    XOR ENABLE,ST ;Disable all interrupts
    POPF R1 ; Restore upper 32 bits and
    POP R1 ;lower 32 bits of R1
    POPF R0 ; Restore upper 32 bits and
    POP R0 ;lower 32 bits of R0
    POP IIF
    POP IIE ;Restore interrupt enable register
    POP DP ;Restore data page register
    POP ST ;Restore status register
    RETI ;Return and enable interrupts
```


### 2.4 Context Switching in Interrupts and Subroutines

Context switching is commonly required when a subroutine call or interrupt is processed. It can be extensive or simple, depending on system requirements. For the 'C4x, the program counter is automatically pushed onto the stack. Important information in other 'C4x registers, such as the status, auxiliary, or ex-tended-precision registers, must be saved in the stack with PUSH/PUSHF and recovered later with POP/POPF instructions.

You need to preserve only the registers that are modified inside of your subroutine or interrupt/trap service routine and that could potentially affect the previous context environment.

## Note:

The status register should be saved first and restored last to preserve the processor status without any further change caused by other context-switching instructions.

If the previous context environment was in C , then your program must perform one of two tasks:

- If the program is in a subroutine, it must preserve the dedicated $C$ registers:

| Save as integers |  |  |
| :--- | :--- | :--- |
| R4 | RS | R6e as floating-point |
| AR4 | AR5 | R7 |
| AR6 | AR7 |  |
| FP | DP (small model only) |  |
| SP | R8 ('C4x only) |  |

- If the program is in an interrupt service routine, it must preserve all of the 'C4x registers, as Example 2-6 shows.

If the previous context environment was in assembly language, you need to determine which registers you must save based on the operations of your as-sembly-language code.

Example 2-6. Context Save and Context Restore

```
* .global ISR1
* TOTAL CONTEXT SAVE ON INTERRUPT.
*
ISRI: PUSH ST ;Save status register
*
* SAVE THE EXTENDED PRECISION REGISTERS
\begin{tabular}{lll} 
PUSH & R0 & ; Save the lower 32 bits of R0 \\
PUSHF & R0 & ; and the upper 32 bits \\
PUSH & R1 & ; Save the lower 32 bits of R1
\end{tabular}
PUSHF R1 ; and the upper 32 bits
PUSH R2 ; Save the lower 32 bits of R2
PUSHF R2 ; and the upper 32 bits
PUSH R3 ; Save the lower 32 bits of R3
PUSHF R3 ; and the upper 32 bits
PUSH R4 ; Save the lower 32 bits of R4
PUSHF R4 ; and the upper 32 bits
PUSH R5 ; Save the lower 32 bits of R5
PUSHF R5 ; and the upper 32 bits
PUSH R6 ;Save the lower 32 bits of R6
PUSHF R6 ; and the upper 32 bits
PUSH R7 ; Save the lower 32 bits of R7
PUSHF R7 ; and the upper 32 bits
PUSH R8 ; Save the lower 32 bits of R8
PUSHF R8 ; and the upper 32 bits
PUSH R9 ; Save the lower 32 bits of R9
PUSHF R9 ; and the upper 32 bits
PUSH R10 ; Save the lower 32 bits of R10
PUSHF R10 ; and the upper 32 bits
PUSH R11 ; Save the lower 32 bits of R11
PUSHF R11 ; and the upper 32 bits
*
* SAVE THE AUXILIARY REGISTERS
*
\begin{tabular}{lll} 
PUSH & AR0 & ; Save AR0 \\
PUSH & AR1 & ; Save AR1 \\
PUSH & AR2 & ; Save AR2 \\
PUSH & AR3 & ; Save AR3 \\
PUSH & AR4 & ; Save AR4 \\
PUSH & AR5 & ;Save AR5 \\
PUSH & AR6 & ; Save AR6 \\
PUSH & AR7 & ;Save AR7
\end{tabular}
*
```


## Example 2-6.Context Save and Context Restore (Continued)

```
* SAVE THE REST OF THE REGISTERS FROM THE REGISTER FILE
PUSH DP ;Save data page pointer
    PUSH IRO ;Save index register IRO
    PUSH IR1 ;Save index register IR1
    PUSH BK ;Save block-size register
    PUSH IIE ;Save interrupt enable register
    PUSH IIF ;Save interrupt flag register
    PUSH DIE ; Save DMA interrupt enable register
    PUSH RS ;Save repeat start address
    PUSH RE ; Save repeat end address
    PUSH RC ; Save repeat counter
*
SAVE IS COMPLETE
*
* YOUR INTERRUPT SERVICE ROUTINE CODE GOES HERE*
    .global RESTR
* CONTEXT RESTORE AT THE END OF A SUBROUTINE CALL OR
    INTERRUPT.
RESTR:
*
* RESTORE THE REST REGISTERS FROM THE REGISTER FILE
*
    POP RC ;Restore repeat counter
    POP RE ;Restore repeat end address
    POP RS ; Restore repeat start address
    POP DIE ;Restore DMA interrupt enable register
    POP IIF ;Restore interrupt flag register
    POP IIE ; Restore interrupt enable register
    POP BK ;Restore block-size register
    POP IR1 ;Restore index register IR1
    POP IRO ;Restore index register IR0
    POP DP ;Restore data page pointer
*
* RESTORE THE AUXILIARY REGISTERS
    POP AR7 ;Restore AR7
    POP AR6 ; Restore AR6
    POP AR5 ;Restore AR5
    POP AR4 ; Restore AR4
    POP AR3 ; Restore AR3
    POP AR2 ;Restore AR2
    POP AR1 ;Restore AR1
    POP AR0 ;Restore AR0
*
```


## Example 2-6. Context Save and Context Restore (Continued)

```
* RESTORE THE EXTENDED PRECISION REGISTERS
    POPF R11 ;Restore the upper 32 bits and
POP R11 ; the lower 32 bits of R11
POPF R10 ;Restore the upper 32 bits and
POP R10 ;the lower 32 bits of R10
POPF R9 ;Restore the upper 32 bits and
POP R9 ;the lower 32 bits of R9
POPF R8 ;Restore the upper 32 bits and
POP R8 ; the lower 32 bits of R8
POPF R7 ;Restore the upper 32 bits and
POP R7 ; the lower 32 bits of R7
POPF R6 ;Restore the upper 32 bits and
POP R6 ;the lower 32 bits of R6
POPF R5 ;Restore the upper 32 bits and
POP R5 ;the lower 32 bits of R5
POPF R4 ;Restore the upper 32 bits and
POP R4 ;the lower 32 bits of R4
POPF R3 ;Restore the upper 32 bits and
POP R3 ; the lower 32 bits of R3
POPF R2 ;Restore the upper 32 bits and
POP R2 ; the lower 32 bits of R2
POPF R1 ;Restore the upper 32 bits and
POP R1 ; the lower 32 bits of R1
POPF RO ;Restore the upper 32 bits and
POP RO ;the lower 32 bits of R0
POP ST ;Restore status register
* RESTORE IS COMPLETE
*
    RETI
```


### 2.5 Repeat Modes

The RPTB, RPTBD, and RPTS instructions support looping without overhead. Loop execution parameters are specified by three registers, as can be seen in the following examples:

- RS (Repeat start address)
- RE (Repeat end address)
- RC (Repeat counter)

In principle, it is possible to nest repeat blocks. However, there is only one set of control registers: RS, RE, and RC. It is, therefore, necessary to save these registers before entering an inside loop and to restore these registers after completing the inside loop. It takes four cycles of overhead to save and restore these registers. Hence, sometimes it may be more economical to implement a nested loop by the more traditional method of using a register as a counter and then using a delayed branch, rather than by using the nested repeat block approach. Often, implementing the outer loop as a counter and the inner loop as a RPTB/RPTBD instruction produces the fastest execution.

### 2.5.1 Block Repeat

Example 2-7 shows the use of the block repeat to find the maximum or the minimum value of 147 numbers. The elements of the array are either all positive or all negative numbers. Because the loop cannot be predetermined, the RPTBD instruction is not suitable here.
Example 2-7.Use of Block Repeat to Find a Maximum or a Minimum

```
* TITLE USE OF BLOCK REPEAT TO FIND A MAXIMUM OR A MINIMUM
* THIS ROUTINE FINDS MAXIMUM OR MINIMUM OF N=147 NUMBERS
    .
        LDI 146,RC ;Initialize repeat counter to 147-1
        LDI @ADDR,AR0 ;AR0 points to beginning of array
        LDF *ARO++(1),R0 ;Initialize MAX or MIN to first value
        BLT LOOP2 ;If negative array, find minimum
LOOP1 RPTB MAX
    CMPF *ARO,RO ;Compare number to the maximum
MAX LDFLT *AR0,R0 ;If greater, this is a new maximum
IOOP2 RPTB MIN
LOOP2 RPTB MIN
    CMPF *AR0++(1),R0 ;Compare number to the minimum
MIN LDFLT *-ARO(1),R0 ;If smaller, this is new minimum
NEXT .
```


### 2.5.2 Delayed Block Repeat

Example 2-8 shows an application of the delayed block-repeat construct. In this example, an array of 64 elements is flipped over by exchanging the elements that are equidistant from the end of the array. In other words, if the original array is:
$a(1), a(2), \ldots, a(31), a(32), \ldots, a(63), a(64)$;
then the final array after the rearrangement is:
$a(64), a(63), \ldots, a(32), a(31), \ldots, a(2), a(1)$.
Because the exchange operation is performed on two elements at the same time, it requires 32 operations. The repeat counter ( RC ) is initialized to 31. In general, if $R C$ contains the number $N$, the loop is executed $N+1$ times. In the example, the loop begins at the fourth instruction following the RPTBD instruction (at the EXCH label). RC should not be initiated in the next three instructions following the RPTBD.

## Example 2-8.Loop Using Delayed Block Repeat



### 2.5.3 Single-Instruction Repeat

Example 2-9 shows an application of the repeat-single construct. In this example, the sum of the products of two arrays is computed. The arrays are not necessarily different. If the arrays are $a(i)$ and $b(i)$, and if each is of length $N=512$, register R2 contains the following quantity:
$a(1) b(1)+a(2) b(2)+\ldots+a(N) b(N)$.
The value of the repeat counter ( RC ) is specified to be 511 in the instruction.

## Example 2-9.Loop Using Single Repeat



### 2.6 Computed GOTOs to Select Subroutines at Runtime

Occasionally, it is convenient to select during runtime, not during assembly, the subroutine to be executed. The 'C4x's computed GOTO supports this selection. You can implement the computed GOTO by using the CALLcond instruction in the register addressing mode. This instruction uses the contents of the register as the address of the call. Example 2-10 shows the case of a task controller.

Example 2-10. Computed GOTO


## Logical and Arithmetic Operations

The 'C4x instruction set supports both integer and floating-point arithmetic and logical operations. The basic functions of such instructions can be combined to form more complex operations. This chapter contains the following operations examples:

- Bit manipulation
- Block moves
- Byte and half-word manipulation
- Bit-reversed addressing
- Integer and floating-point division
- Square root
- Extended-precision arithmetic
- Floating-point format conversion between IEEE and 'C4x formats
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### 3.1 Bit Manipulation

Instructions for logical operations, such as AND, OR, NOT, ANDN, and XOR, can be used together with shift instructions for bit manipulation. A special instruction, TSTB, tests bits. TSTB does the same operation as AND, but the result of the TSTB is used only to set the condition flags and is not written anywhere. Example 3-1 and Example 3-2 demonstrate the use of several instructions for bit manipulation and testing.

## Example 3-1.Use of TSTB for Software-Controlled Interrupt

```
* TITLE USE OF TSTB FOR SOFTWARE-CONTROLLED INTERRUPT
*
* IN THIS EXAMPLE, ALL INTERRUPTS HAVE BEEN DISABLED BY
* RESETTING THE GIE BIT OF THE STATUS REGISTER. WHEN AN
* INTERRUPT ARRIVES, IT IS STORED IN THE IF REGISTER. THE
* PRESENT EXAMPLE ACTIVATES THE INTERRUPT SERVICE ROUTINE INTR
* WHEN IT DETECTS THAT INT2- HAS OCCURRED.
```



## Example 3-2. Copy a Bit from One Location to Another

```
* TITLE COPY A BIT FROM ONE LOCATION TO ANOTHER
* BIT I OF R1 NEEDS TO BE COPIED TO BIT J OF R2. ARO POINTS TO A LOCATION
* HOLDING I, AND IT IS ASSUMED THAT THE NEXT MEMORY LOCATION HOLDS THE VALUE J.
    LDI 1,R0
    LSH *ARO,RO ;Shift 1 to align it with bit I
    TSTB R1,R0 ;Test the I-th bit of R1
    BZD CONT ;If bit = 0, branch delayed
    LDI 1,R0
    LSH *+ARO(1),R0 ;Align 1 with J-th location
    ANDN RO,R2 ;If bit = 0, reset J-th bit of R2
    OR R0,R2 ;If bit = 1, set J-th bit of R2
        CONT
    .
```


### 3.2 Block Moves

Because the 'C4x directly addresses a large amount of memory, blocks of data or program code can be stored off-chip in slow memories and then loaded on-chip for faster execution. Data can also be moved from on-chip memory to off-chip memory for storage or for multiprocessor data transfers.

The DMA can transfer data efficiently in parallel with CPU operations. Alternatively, you can use the load and store instructions in a repeat mode to perform data transfers under program control. Example 3-3 shows how to transfer a block of 512 floating-point numbers from external memory to block 1 of on-chip RAM.

## Example 3-3.Block Move Under Program Control

```
* TITLE BLOCK MOVE UNDER PROGRAM CONTROL
*
extern .word 01000H
block1 .word 02FFC00H
    .
    .
    LDI @extern,AR0 ; Source address
    LDI @block1,AR1 ;Destination address
    LDF *AR0++,R0 ;Load the first number
    RPTS 510 ;Repeat following instruction 511 times
    LDF *AR0++,R0 ;Load the next number, and...
    STF R0,*AR1++ ;store the previous one
    STF R0,*AR1 ; Store the last number
    .
    .
```


### 3.3 Byte and Half-Word Manipulation

A set of instructions for byte and half-word accessibility, such as $\operatorname{LB}(3,2,1,0)$, $\operatorname{LBU}(3,2,1,0), \operatorname{LH}(1,0), \operatorname{LHU}(1,0), \operatorname{LWL}(0,1,2,3), \operatorname{LWR}(0,1,2,3), \operatorname{MB}(3,2,1,0)$, and $\mathrm{MH}(1,0)$, is available on the ' $\mathrm{C} 4 x$. In an application such as image processing, it is often important to be able to manipulate packed data. For example, the pixels in color images are often represented by four 8 -bit unsigned quantities - red, green, blue and alpha - which are packed into a single 32-bit word. The byte and half-word instruction makes it very easy to manipulate this packed data.

Example 3-4 shows the packing of data from a half-word FIFO to 32-bit data memory, and Example 3-5 shows the unpacking of a 32-bit data array into a 4 -byte-wide data array (assuming the 32 -bit data array contains four 8 -bit unsigned numbers).

Example 3-4.Use of Packing Data From Half-Word FIFO to 32-Bit Data Memory

```
* TITLE USE OF PACKING DATA FROM HALF-WORD FIFO
* TO 32-BIT DATA MEMORY
* IN THIS EXAMPLE, EVERY TWO INPUT 16 BITS DATA HAS BEEN
* PACKED INTO ONE 32-BIT DATA MEMORY. THE LOOP SIZE
* USED HERE IS ARRAY SIZE, NOT THE INPUT DATA LENGTH.
    LDI size-1,RC ;Load array size
    RPTBD PACK
    LDI @fifo_adr,AR1 ;Load fifo address
    LDI @array,AR2 ;Load data array address
    NOP
* >>>>>>>>>>>>>>>>>> *AR1,R9 
    LWLO *AR1,R9 *AR1,R9 %Pack 16 LSBS
    LWL1 *AR1,R9 
```

Example 3-5. Use of Unpacking 32-Bit Data Into Four-Byte-Wide Data Array

```
* TITLE USE OF UNPACKING 32-BIT DATA INTO FOUR BYTE-WIDE
* DATA ARRAY
* THIS EXAMPLE ASSUMED THAT THE 32-BIT DATA CONTAINS FOUR 8-BIT
* UNSIGNED DATA.
    . LDIsize-1,RC ; Load array size
    LDI @input_adr,AR0 ;Load RPTBD UNPACK input address
        LDI @array1,AR1 ;Load output data array 1 address
        RPTBD UNPACK
        LDI @array2,AR2 ;Load output data array 2 address
        LDI @array3,AR3 ;Load output data array 3 address
        LDI @array4,AR4 ;Load output data array 4 address
* >>>>>>>>>>>>>>>>
        LBU0 *AR0,R8
        STI R8,*AR1++(1)
        LBU1 *AR0,R8 ;Unpack second byte
        STI R8,*AR2++(1)
        LBU2 *AR0,R8 ;Unpack third byte
        STI R8,*AR3++(1)
        LBU3 *AR0++(1),R8 ;Unpack fourth byte
UNPACK STI R8,*AR4++(1)
    •
    .
```


### 3.4 Bit-Reversed Addressing

The 'C4x can implement fast Fourier transforms (FFT) with bit-reversed addressing. If the data to be transformed is in the correct order, the final result of the FFT is scrambled in bit-reversed order. To recover the frequency-domain data in the correct order, certain memory locations must be swapped. The bit-reversed addressing mode makes swapping unnecessary. The next time data is accessed, the access is bit-reversed rather than sequential. In 'C4x, this bit-reversed addressing can be implemented through both the CPU and DMA.

For correct CPU or DMA bit-reversed operation, the base address of bit-reversed addressing must be located on a boundary of the size of the table. To clarify this point, assume an FFT of size $\mathrm{N}=2^{\mathrm{n}}$. When real and imaginary data are stored in separate arrays, the $n$ LSBs of the base address must be zero, $(0)$ and IR0 must be initialized to $2^{\text {n-1 }}$ (half of the FFT size). When real and imaginary data are stored in consecutive memory locations (Re-Im-Re-Im) the $n+1$ LSBs of the base address must be zero (0), and IRO must be equal to $\operatorname{IRO}=2^{n}=\mathrm{N}$ (FFT size).

### 3.4.1 CPU Bit-Reversed Addressing

One auxiliary register (ARO, in this case) points to the physical location of a data value. When you add IR0 to the auxiliary register by using bit-reversed addressing, addresses are generated in a bit-reversed fashion (reverse carry propagation). The largest index (IR0, in this case) for bit reversing is 00FF FFFFh.

Example 3-6 illustrates how to move a 512-point complex FFT from the place of computation (pointed at by ARO) to a location pointed at by AR1. Reads are executed in a bit-reversed fashion and writes in a linear fashion. In this example, real and imaginary parts XR (i) and $\mathrm{XI}(\mathrm{i})$ of the data are not stored in separate arrays, but they are interleaved with $\mathrm{XR}(0), \mathrm{XI}(0), \mathrm{XR}(1), \mathrm{XI}(1), \ldots, \mathrm{XR}(\mathrm{N} 1)$, $\mathrm{XI}(\mathrm{N} 1)$. Because of this arrangement, the length of the array is 2 N instead of N , and IRO is set to 512 instead of 256 .

Example 3-6. CPU Bit-Reversed Addressing


### 3.4.2 DMA Bit-Reversed Addressing

In DMA bit-reversed addressing, two bits in the DMA control register enable bit-reversed addressing on DMA reads (READ BIT REV) and DMA writes (WRITE BIT REV). The source address index register and destination address index register define the size of the bit-reversed addressing. Their function is similar to the CPU index register IR0 described in the previous subsection. Two DMA block transfers are required when the DMA is used for bit-reversed transfer of complex numbers: one to transfer the real ports and one to transfer the imaginary ports.

Figure 3-1 illustrates the DMA settings required for a DMA operation equivalent to Example 3-6. Unified-autoinitialization mode and bit-reversed read are used. For more detailed information about DMA operation, refer to The DMA Coprocessor in the TMS320C4x User's Guide.

Figure 3-1. DMA Bit-Reversed Addressing


### 3.5 Integer and Floating-Point Division

You can use the single-cycle instruction, RCPF, to generate an estimate of the reciprocal of a floating-point number. This estimate has the correct exponent, and the mantissa is accurate to the eighth binary place (the error of the mantissa is $<2^{-8}$ ). Often, this is a satisfactory estimate of the reciprocal of a floatingpoint number. In other cases, this estimate can be used as a seed for an algorithm that computes the reciprocal to even greater accuracy. The NewtonRaphson algorithm described later is one such case.

Although it provides no special instruction for integer division, the instruction set can perform an efficient division routine. Additionally, the FLOAT, RCPF, and FIX instructions can produce a rough estimate.

### 3.5.1 Integer Division

You can implement division on the 'C4x by repeating SUBC, a special conditional subtract instruction. Consider the case of a 32 -bit positive dividend with $i$ significant bits (and 32-i sign bits), and a 32-bit positive divisor with $j$ significant bits (and $32-j$ sign bits). The repetition of the SUBC command $i-j+1$ times produces a 32-bit result in which the lower $i-j+1$ bits are the quotient, and the upper $31-i+j$ bits are the remainder of the division.

SUBC implements binary division in the same manner as long division. The divisor (assumed to be smaller than the dividend) is shifted left $i-j$ times to align with the dividend. Then, using SUBC, the shifted divisor is subtracted from the dividend. For each subtract that does not produce a negative answer, the dividend is replaced by the difference. It is then shifted to the left, and the LSB is set to 1 . If the difference is negative, the dividend is simply shifted left by one. This operation is repeated $i-j+1$ times.

As an example, consider the division of 33 by 5 using both long division and the SUBC method. In this case, $i=6, j=3$, and the SUBC operation is repeated $6-3+1=4$ times.

LONG DIVISION:


## SUBC METHOD:



When the SUBC command is used, both the dividend and the divisor must be positive. Example 3-7 shows a realization of the integer division in which the sign of the quotient is properly handled. The last instruction before returning modifies the condition flag, in case subsequent operations depend on the sign of the result.

Example 3-7. Integer Division

```
* TITLE INTEGER DIVISION
* SUBROUTINE DIVI
INPUTS: SIGNED INTEGER DIVIDEND IN R0,
* SIGNED INTEGER DIVISOR IN R1.
OUTPUT: R0/R1 into R0.
REGISTERS USED: R0-R3, IR0, IR1
OPERATION: 1. NORMALIZE DIVISOR WITH DIVIDEND
    2. REPEAT SUBC
    3. QUOTIENT IS IN LSBS OF RESULT
* CYCLES: 31-62 (DEPENDS ON AMOUNT OF NORMALIZATION)
* .globl DIVI
SIGN .set R2
TEMPF .set R3
TEMP .set IR0
COUNT .set IR1
* DIVI - SIGNED DIVISION
DIVI:
*
* DETERMINE SIGN OF RESULT. GET ABSOLUTE VALUE OF OPERANDS.
*
    XOR R0,R1,SIGN ;Get the sign
    ABSI R0
    ABSI R1
    CMPI R0,R1 ;Divisor > dividend ?
    BGTD ZERO ;If so, return 0
*
* NORMALIZE OPERANDS. USE DIFFERENCE IN EXPONENTS AS SHIFT COUNT
* FOR DIVISOR, AND AS REPEAT COUNT FOR 'SUBC'.
\begin{tabular}{lll} 
FLOAT RO,TEMPF & ;Normalize dividend \\
PUSHF & TEMPF & ;PUSH as float
\end{tabular}
    POP COUNT MOP as int
    POP COUNT ;POP as int
    LSH -24,COUNT ;Get dividend exponent
    FLOAT R1,TEMPF ;Normalize divisor
    PUSHF TEMPF ;PUSH as float
    POP TEMP ;POP as int
    LSH -24,TEMP ;Get divisor exponent
    SUBI TEMP,COUNT ;Get difference in exponents
    LSH COUNT,R1 ;Align divisor with dividend
* DO COUNT+1 SUBTRACT & SHIFTS.
    RPTS COUNT
    SUBC R1,R0
```


## Example 3-7.Integer Division (Continued)

```
* MASK OFF THE LOWER COUNT+1 BITS OF R0
*
    SUBRI 31,COUNT ;Shift count is (32 - (COUNT+1))
    LSH COUNT,R0 ;Shift left
    NEGI COUNT
    LSH COUNT,R0 ;Shift right to get result
*
* CHECK SIGN AND NEGATE RESULT IF NECESSARY.
* RO, R1
    ASH -31,SIGN ;Check sign
    LDINZ R1,R0 ;If set, use negative result
    CMPI 0,R0 ;Set status from result RETS
*
* RETURN ZERO.
ZERO:
    LDI 0,R0
    RETS
    .end
```

If the dividend is less than the divisor and you want fractional division, you can perform a division after you determine the desired accuracy of the quotient in bits. If the desired accuracy is $k$ bits, start by shifting the dividend left by $k$ positions. Then apply the algorithm described above, and replace with $i+k$. It is assumed that $i+k$ is less than 32 .

### 3.5.2 Computation of Floating-Point Inverse and Division

When you use the RCPF (reciprocal of a floating-point number) instruction to generate an estimate of the reciprocal of a floating-point number, you can also use Newton-Raphson algorithm to extend the precision of the mantissa of the reciprocal of a floating-point number that the instruction generates. The floa-ting-point division can be obtained by multiplying the dividend and the reciprocal of the divisor.

The input to RCPF is assumed to be $v=v(m a n) \times 2 v(\exp )$. The output is $x=$ $x($ man $) \times 2^{x(e x p)}$. The value $v($ man $)$ (or $x(m a n)$ ) is composed of three fields: the sign bit $v(s i g n)$, an implied nonsign bit, and the fraction field $v(f r a c)$.
Four rules apply to generating the reciprocal of a floating-point number:

1) If $v>0$, then $x(\exp )=-v(\exp )-1$, and $x($ man $)=2 / v($ man $)$.

For the special case in which the 10 MSBs of $\mathrm{v}($ man $)=01.00000000 \mathrm{~b}$, then $x(m a n)=2-2-8=01.11111111 \mathrm{~b}$. In both cases, the 23 LSBs of $x(f r a c)=0$.
2) If $v<0$, then $x(\exp )=-v(\exp )-1$, and $x($ man $)=2 / v($ man $)$.

For the special case in which the 10 MSBs of $\mathrm{v}($ man $)=10.00000000 \mathrm{~b}$,
then $x(\operatorname{man})=-1-2^{-8}=10.11111111 b$. In both cases, the 23 LSBs of $x(f r a c)=0$.
3) If $v=0(v(\exp )=-128)$, then $x(\exp )=127$, and $x(\operatorname{man})=01.1111111111111111111111111111111 \mathrm{~b}$.
In other words, if $v=0$, then $x$ becomes the largest positive number representable in the extended-precision floating-point format. The overflow flag $(\mathrm{V})$ is set to 1 .
4) If $v(\exp )=127$, then $x(\exp )=-128$, and $x($ man $)=0$.

The zero flag $(Z)$ is set to 1 .
The Newton-Raphson algorithm is:
$x[n+1]=x[n](2.0-v x[n])$
In this algorithm, $v$ is the number for which the reciprocal is desired. $x[0]$ is the seed for the algorithm and is given by RCPF. At every iteration of the algorithm, the number of bits of accuracy in the mantissa doubles. Using RCPF, accuracy starts at eight bits. With one iteration, accuracy increases to16 bits in the mantissa, and with the second iteration, accuracy increases to 32 bits in the mantissa. Example 3-8 shows the program for implementing this algorithm on the 'C4x.

## Example 3-8.Inverse of a Floating-Point Number With 32-Bit Mantissa Accuracy



### 3.6 Calculating a Square Root

In many applications, normalization of data values is necessary. Often, the normalizing factor is the square root of another quantity. For example, given a vector, the unit vector in the same direction as the original vector can be found by normalizing the original vector by its length. This involves a division by a square root. The 'C4x single-cycle instruction RSQRF generates an estimate of the reciprocal of the square root of a positive floating-point number. This estimate has the correct exponent, and the mantissa is accurate to the eighth binary place (the error of the mantissa is < 2-8). Three rules apply to this algorithm:

1) If $v(\exp )$ is even, then $x(\exp )=-(v(\exp ) / 2)-1$, and $x($ man $)=2 / s q r t(v(m a n))$.

For the special case where the 10 MSBs of $y(m a n)=01.00000000 \mathrm{~b}$, then $x(\operatorname{man})=2-2^{-8}=01.11111111$ b. In both cases, the 23 LSBs of $x(f r a c)=0$.
2) If $v(\exp )$ is odd, then $x(\exp )=-((v(\exp )-1) / 2)-1$ and $x($ man $)=\operatorname{sqrt}(2 / v(\operatorname{man}))$. The 23 LSBs of $x(f r a c)=0$.
3) If $v=0(v(\exp )=-128)$, then $x(\exp )=127$, and $x(\operatorname{man})=01.11111111111111111111111111111 \mathrm{~b}$.
In other words, if $\mathrm{v}=0$, then $x$ becomes the largest positive number representable in the extended-precision floating-point format. The overflow flag $(\mathrm{V})$ is set to 1 .

If you need larger precision than the RSQRF instruction gives for the estimate of the reciprocal of the square root, you can use the Newton-Raphson algorithm to further extend the precision of the mantissa. The algorithm is:
$x[n+1]=x[n](1.5-(v / 2) x[n] \times[n])$
In this equation, $v$ is the number for which the reciprocal is desired. $x[0]$ is the seed for the algorithm and is given by RSQRF. At every iteration of the algorithm, the number of bits of accuracy in the mantissa doubles. Using RSQRF, accuracy starts at eight bits. With one iteration, accuracy increases to16 bits, and with the second iteration, accuracy increases to 32 bits in the mantissa. Example 3-9 shows the program for implementing this algorithm on the ' C 4 x .

## Example 3-9.Reciprocal of the Square Root of a Positive Floating Point

* TITLE RECIPROCAL OF THE SQUARE ROOT OF A POSITIVE


## FLOATING-POINT

SUBROUTINE RCPSQRF
THE FLOATING-POINT NUMBER $v$ IS STORED IN RO. AFTER THE COMPUTATION IS COMPLETED, 1/SQRT(v) IS STORED IN R1.

TYPICAL CALLING SEQUENCE:
LDF $\quad \mathrm{V}$, R0
LAJU RCPSQRF

ARGUMENT ASSIGNMENTS:

```
ARGUMENT | FUNCTION 
    R0
                        v = NUMBER TO FIND THE RECIPROCAL OF
                                (UPON THE CALL)
                                1/sqrt(v) (UPON THE RETURN)
```

    REGISTER USED AS INPUT: RO
    REGISTERS MODIFIED: R1, R2
    REGISTER CONTAINING RESULT: R1
    REGISTER FOR SUBROUTINE CALL: R11
    CYCLES: 10 (not including subroutine overhead)
    WORDS: 10 (not including subroutine overhead)
    .global RCPSQRF
    * 

RCPSQRF: RSQRF R0,R1 ;Get $x[0]=$ the estimate of $1 /$ sqrt(v), $R 0=v$
MPYF $0.5, R 0 \quad ; R 0=v / 2$
MPYF3 R1,R1,R2 ;First iteration
MPYF R0,R2
SUBRF 1.5,R2
MPYF R2,R1 ;End of first iteration (16 bits accuracy)
MPYF3 R1,R1,R2 ; Second iteration
BRD R11 ;Delayed return to caller
MPYF R0,R2
SUBRF 1.5,R2
MPYF R2,R1 ;End of second iteration (32 bits accuracy)
R1 $=1 / \operatorname{SQRT}(v)$, Return to caller
.end

You can find the square root by a simple multiplication: $\operatorname{sqrt}(\mathrm{v})=\mathrm{vx}[\mathrm{n}]$ in which $\mathrm{x}[\mathrm{n}]$ is the estimate of $1 / \mathrm{sqrt}(\mathrm{v})$ as determined by the Newton-Raphson algorithm or another algorithm.

### 3.7 Extended-Precision Arithmetic

The 'C4x offers 32 bits of precision in the mantissa for integer arithmetic, and 24 bits of precision in the mantissa for floating-point arithmetic. For higher precision in floating-point operations, the twelve extended-precision registers, R0 to R11, contain eight more bits of accuracy. Because no comparable extension is available for fixed-point arithmetic, this section discusses how to achieve fixed-point double precision. The technique consists of performing the arithmetic by parts and is similar to the way in which longhand arithmetic is done.

The instructions, ADDC (add with carry) and SUBB (subtract with borrow) use the status carry bit for extended-precision arithmetic. The carry bit is affected by the arithmetic operations of the ALU and by the rotate and shift instructions. You can also manipulate it directly by setting the status register to certain values. For proper operation, the overflow mode bit should be reset ( $O V M=0$ ) so that the accumulator results are not loaded with the saturation values. Example 3-10 and Example 3-11 show 64-bit addition and 64-bit subtraction, respectively. The first operand is stored in the registers R0 (low word) and R1 (high word). The second operand is stored in registers R2 and R3, respectively. The result is stored in R0 and R1.

Example 3-10. 64-Bit Addition

```
* TITLE 64-BIT ADDITION
*
TWO 64-BIT NUMBERS ARE ADDED TO EACH OTHER PRODUCING
A 64-BIT RESULT. THE NUMBERS X (R1,R0) AND Y (R3,R2)
    ARE ADDED, RESULTING IN W (R1,R0).
    R1 R0
    + R3 R2
        -------
        R1 R0
    ADDI R2,R0
    ADDC R3,R1
```


## Example 3-11. 64-Bit Subtraction

```
* TITLE 64-BIT SUBTRACTION
TWO 64-BIT NUMBERS ARE SUBTRACTED FROM EACH OTHER
PRODUCING A 64-BIT RESULT. THE NUMBERS X (R1,R0) AND
Y (R3,R2) ARE SUBTRACTED, RESULTING IN W (R1,R0).
    R1 R0
    - R3 R2
        -------
        R1 R0
    SUBI R2,R0
    SUBB R3,R1
```

When two 32-bit numbers are multiplied, a 64-bit product results. To do this, 'C4x provides a 32 bit x 32-bit multiplier and two special instructions, MPYSHI (multiply signed integer and produce 32 MSBs ) and MPYUHI (multiply unsigned integer and produce 32 MSBs). Example 3-12 shows the implementation of a 32-bit x 32-bit multiplication.

Example 3-12. 32-Bit by 32-Bit Multiplication

```
TITLE 32 BIT × 32-BIT MULTIPLICATION
MULTIPLIES 2 32-BIT NUMBERS, PRODUCING A 64-BIT RESULT.
THE TWO NUMBERS RO AND R1 ARE MULTIPLIED, RESULTING
IN W (R3,R2).
        R0
    < R1
        ----
            R3 R2
        MPYI3 R0,R1,R2
        MPYSHI3 R0,R1,R3
```


### 3.8 Floating-Point Format Conversion: IEEE to/From 'C4x

In fixed-point arithmetic, the binary point that separates the integer from the fractional part of the number is fixed at a certain location. Therefore, if the binary point of a 32-bit number is fixed after the most significant bit (which is also the sign bit), only a fractional number (a number with an absolute value less than 1), can be represented. In other words, there is a number with 31 fractional bits. All operations assume that the binary point is fixed at this location. The fixed-point system, although simple to implement in hardware, imposes limitations in the dynamic range of the represented number. This causes scaling problems in many applications. You can avoid this difficulty by using floa-ting-point numbers.

A floating-point number consists of a mantissa $m$ multiplied by base $b$ raised to an exponent e:

```
m\timesbe
```

In current hardware implementations, the mantissa is typically a normalized number with an absolute value between 1 and 2 , and the base is $b=2$. Although the mantissa is represented as a fixed-point number, the actual value of the overall number floats the binary point because of the multiplication by be. The exponent $e$ is an integer whose value determines the position of the binary point in the number. IEEE has established a standard format for the representation of floating-point numbers.

To achieve higher efficiency in the hardware implementation, the 'C4x uses a floating-point format that differs from the IEEE standard. However, 'C4x has two single-cycle instructions, TOIEEE and FRIEEE, for the format conversion. These two instructions can also be used with the STF instruction, which allows the data format to be converted within memory-to-memory transfer. Here are descriptions of both formats and an example program to convert between them.

## 'C4x floating-point format:

8 bits 123 bits

| $e$ | $s$ | $f$ |
| :--- | :--- | :--- |

In a 32-bit word representing a floating-point number, the first 8 bits correspond to the exponent expressed in twos-complement format. One bit is for sign, and 23 bits are for the mantissa. The mantissa is expressed in twos-complement form with the binary point after the most significant nonsign bit. Because this bit is the complement of the sign bit $s$, it is suppressed. In other words, the mantissa actually has 24 bits. One special case occurs when
$\mathrm{e}=-128$. In this case, the number is interpreted as zero, independently of the values of $s$ and $f$ (which are, by default, set to zero). To summarize, the values of the represented numbers in the 'C4x floating-point format are as follows:

```
2e*}(01.f)\quad\mathrm{ if }s=
2e*(10.f) if }s=
0 if e==-128
```


## IEEE floating-point format:



The IEEE floating-point format uses sign-magnitude notation for the mantissa. In a 32-bit word representing a floating-point number, the first bit is the sign bit. The next 8 bits correspond to the exponent, expressed in an offset-by-127 format (the actual exponent is $e-127$ ). The following 23 bits represent the absolute value of the mantissa with the most significant 1 implied. The binary point is fixed after this most significant 1 . In other words, the mantissa actually has 24 bits. Several special cases are summarized below.

These are values of the represented numbers in the IEEE floating-point format:
$(-1)^{\text {* }} 2^{e-127 *}$ (01.f)
if $0<e<255$

Special cases:

| $(-1)^{s * 0.0}$ | if $e=0$ and $\mathrm{f}=0$ (zero) |
| :--- | :--- |
| $(-1)^{s * 2-126 *}(0 . \mathrm{f})$ | if $e=0$ and $\mathrm{f}<>0$ (denormalized) |
| $(-1) s *$ infinity | if $e=255$ and $\mathrm{f}=0$ (infinity) |
| NaN (not a number) | if $e=255$ and $\mathrm{f}<>0$ |

The 'C4x performs the conversion according to these definitions of the formats. It assumes that the source data for the IEEE format is in memory only and that the source data for the 'C4x floating-point format is in either memory or an extended-precision register. The destination for both conversions must be in an extended-precision register. In the case of block memory transfer, the no-penalty data-format conversion can be executed by parallel instruction with STF. Example 3-13 and Example 3-14 show the data-format conversion within the data transformation between communication port and internal RAM.

Example 3-13. IEEE to 'C4x Conversion Within Block Memory Transfer

```
* TITLE IEEE TO 'C4x CONVERSION WITHIN BLOCK MEMORY
* TRANSFER
* PROGRAM ASSUMES THAT INPUT FIFO OF COMMUNICATION PORT 0
* IS FULL OF IEEE FORMAT DATA. EIGHT DATA WORDS ARE
* TRANSFERRED FROM COMMUNICATION PORT O TO INTERNAL RAM
* BLOCK O AND THE DATA FORMAT IS CONVERTED FROM IEEE FORMAT
* TO 'C4x FLOATING-POINT FORMAT.
    .
    LDI @CPO_IN,ARO ;Load comm port0 input FIFO address
    LDI @RAMO,AR1 ;Load internal RAM block O address
    FRIEEE *ARO,RO ; Convert first data
    RPTS 6
    FRIEEE *AR0,R0 ; Convert next data
|| STF R0,*AR1++(1) ; Store previous data
    STF R0,*AR1++(1) ;Store last data
    •
.
```


## Example 3-14. 'C4x to IEEE Conversion Within Block Memory Transfer

```
* TITLE 'C4x TO IEEE CONVERSION WITHIN BLOCK MEMORY
* TRANSFER
*
* PROGRAM ASSUMES THAT OUTPUT FIFO OF COMMUNICATION PORT O
* IS EMPTY. EIGHT DATA WORDS ARE TRANSFERRED FROM INTERNAI
* RAM BLOCK O TO COMMUNICATION PORT O AND THE DATA FORMAT
* IS CONVERTED FROM 'C4x FLOATING-POINT FORMAT TO
* IEEE FORMAT.
*
    •
    LDI @CPO_OUT,ARO ;Load comm port0 output FIFO address
    LDI @RAMO,AR1 ;Load internal RAM block 0 address
    TOIEEE *AR1++(1),R0 ;Convert first data
    RPTS 6
    TOIEEE *AR1++(1),R0 ; Convert next data
|| STF R0,*AR0 ;Store previous data
    STF R0,*AR0 ;Store last data
    .
    .
```

    .
    
## Memory Interfacing

The 'C4x's advanced interface design can be used to implement a wide variety of system configurations. Its two external buses and DMA capability provide a flexible parallel 32 -bit interface to byte-or word-wide devices.

This chapter describes how to use the 'C4x's memory interfaces to connect to various external devices. Specific discussions include implementation of a parallel interface to devices with and without wait states and implementing system control functions.
4.1 System Configuration ..... 4-2
4.2 External Interfacing ..... 4-3
4.3 Global and Local Bus Interfaces ..... 4-4
4.4 Zero Wait-State Interfacing to RAMs ..... 4-5
4.5 Wait States and Ready Generation ..... 4-11
4.6 Parallel Processing Through Shared Memory ..... 4-21

### 4.1 System Configuration

Figure 4-1 illustrates an expanded configuration of a ' $\mathrm{C} 4 x$ system with different types of external devices and the interfaces to which they are connected.

Figure 4-1. Possible System Configurations


In your design, you can use any subset or superset of the illustrated components.

### 4.2 External Interfacing

The 'C4x interfaces connect to a wide variety of device types. Each of these interfaces is tailored to a particular type of device such as memory, DMA, parallel and serial peripherals, and I/O. In addition, 'C4x devices can interface directly with each other, without external logic, through their communication ports or their external flag pins $\overline{I I O F}(0-3)$. Each interface comprises one or more signal lines, which transfer information and control its operation. Figure 4-2 shows the signal groups for these interfaces.

Figure 4-2. External Interfaces


Note: $\mathrm{n}=0$ for communication port $0, \mathrm{n}=1$ for communication port 1 , etc.
The global and local buses implement the primary memory-mapped interfaces to the device. These interfaces allow external devices such as DMA controllers and other microprocessors to share resources with one or more 'C4x devices through a common bus.

### 4.3 Global and Local Bus Interfaces

The 'C4x uses the global and local buses to access the majority of its memory-mapped locations. Since these two memory interfaces are identical in every way, except for their positions in the memory map, each example in this memory interface section focuses on only one of the two interfaces. However, all of the examples are applicable to either the local or global bus. The buses have identical but mutually exclusive sets of control signals:

Table 4-1. Local/Global Bus Control Signals

| Global Bus | Local Bus |
| :---: | :---: |
| $\overline{\text { STRB0 }}$ | $\overline{\text { LSTRB0 }}$ |
| $\overline{\text { STRB1 }}$ | $\overline{\text { LSTRB1 }}$ |
| $\overline{\mathrm{CE}} 0$ | LCE0 |
| $\overline{\mathrm{CE}} 1$ | LCE1 |
| $\overline{\mathrm{RDY}}$ | $\overline{\text { LRDY0 }}$ |
| $\overline{\mathrm{RDY}} 1$ | $\overline{\mathrm{LRDY}} 1$ |
| $\overline{\text { AE }}$ | $\overline{\text { LAE }}$ |
| $\overline{\text { DE }}$ | $\overline{\text { LDE }}$ |
| PAGE0 | LPAGE0 |
| $\overline{\text { PAGE1 }}$ | LPAGE1 |
| $\mathrm{R} \overline{\mathrm{W}} 0$ | LR/W0 |
| $\mathrm{R} / \overline{\mathrm{W}} 1$ | LR/W1 |

While both the global bus and the local bus can interface to a wide variety of devices, they most commonly interface to memories.

### 4.4 Zero Wait-State Interfacing to RAMs

A memory-read access time is normally defined as the time between address valid and data valid. This time can be determined by:

Read access time $=\mathrm{t}_{\mathrm{C}(\mathrm{H})}-\left(\mathrm{t}_{\mathrm{d}(\mathrm{H} 1 \mathrm{~L}-\mathrm{A})}+\mathrm{t}_{\mathrm{su}(\mathrm{D}) \mathrm{R})}\right.$
where:
$\mathrm{t}_{\mathrm{c}(\mathrm{H})}=\mathrm{H} 1 / \mathrm{H} 3$ cycle time
$\mathrm{t}_{\mathrm{d}(\mathrm{H} 1 \mathrm{~L}-\mathrm{A})}=\quad \mathrm{H} 1$ low to address valid
$\mathrm{t}_{\text {su( } \mathrm{D}) \mathrm{R}}=$ Data valid before next H 1 low (read)
For a full-speed, zero wait-state interface to any device, a $50-\mathrm{MHz}$ ' C 4 x (40-ns instruction cycle time) requires a read access time of 21 ns from address stable to data valid. For most memories, the access time from chip enable is the same as access time from address; thus, it is possible to use 20-ns memories at full speed with a $50-\mathrm{MHz}$ ' C 4 x . However, to use $20-\mathrm{ns}$ memories properly, you must avoid long delays between the processor and the memories.

Avoiding these delays is not always possible, because interconnections and gating for chip-enable generation can cause them. In addition, if you choose a memory device with an output enable, the output enable must become active quickly enough to ensure that the memory can meet the data valid timing requirements of the 'C4x. For memories with 20 -ns access times, the output enable active to data valid timing parameter is typically less than 10 ns .

Currently available RAMs without output-enable (OE) control lines include the 1 -bit wide organized RAMs and most of the 4 -bit wide RAMs. Those with OE controls include the byte-wide and a few of the 4 -bit wide RAMs. Many of the fastest RAMs do not provide OE control; they use chip-enable (CE) controlled write cycles to ensure that data outputs do not turn on for write operations. In CE-controlled write cycles, the write control line ( $\overline{\mathrm{WE}})$ goes low before CE goes low, and internal logic holds the outputs disabled until the cycle is completed. Using CE-controlled write cycles is an efficient way to interface fast RAMs without OE controls to the 'C4x at full speed.

## Note:

You can find timing parameters for CLKIN, H1, H3, and memory in the TMS320C40 and TMS320C44 data sheets.

### 4.4.1 Consecutive Reads Followed by a Write Interface Timing

Figure $4-3$ shows the timing of consecutive reads followed by a write. For consecutive reads, $\overline{\text { LSTRB } 0 ~ s t a y s ~ a c t i v e ~(l o w), ~ a n d ~ L R / W ~ s t a y s ~ h i g h ~ a s ~ l o n g ~ a s ~}$ read cycles continue. For back-to-back reads, the 'C4x requires zero-waitstate memories to have an address-valid to data-valid time of less than 21 ns .

For most memory devices, this time is the same as the memory access time, which is $\mathrm{t}_{1}=20 \mathrm{~ns}$. Thus, memories with access times of 25 ns or more cannot meet this timing.

Memory device timing is not as critical for zero-wait-state as for nonzero-waitstate write cycles, because of the two H1 cycle writes of the 'C4x. The extra cycle gives $\overline{\text { LSTRB0 }}$ enough time to frame LR/W, preventing memories that go into high impedance slowly at the end of a read cycle from driving the bus during the subsequent write cycle. For the memory device used in this design (Figure 4-3), the data lines are guaranteed to into high impedance ( $\mathrm{t}_{2}=10 \mathrm{~ns}$ ) after $\overline{\mathrm{CS}}$ goes inactive, which gives more than 23 ns of margin before the ' C 4 x starts driving the bus with write data. Also, the extra cycle with $\overline{\text { LSTRB }} 0$ inactive prevents writes to random locations in memory while the address is changing between consecutive writes.
For the write cycles shown in Figure 4-3 and Figure 4-4, the RAM requires 15 ns of write data setup before $\overline{\mathrm{CS}}$ goes high, and this design provides at least $24 \mathrm{~ns}\left(\mathrm{t}_{3}\right)$. A data hold time of $0 \mathrm{~ns}\left(\mathrm{t}_{4}\right)$ is required by the RAM, and this design provides greater than 13 ns. Finally, the RAM's 20 -ns setup and 0 -ns hold times for address (with respect to $\overline{\mathrm{CS}}$ high) ensure a clear margin.

Figure 4-3. Consecutive Reads Followed by a Write


Figure 4-4. Consecutive Writes Followed by a Read


### 4.4.2 Consecutive Writes Followed by a Read Interface Timing

Figure $4-4$ shows the timing of consecutive writes followed by a read. Notice that between consecutive writes, LR/W stays low, but $\overline{\text { STRB } 0 ~ g o e s ~ i n a c t i v e ~ t o ~}$ frame the write cycles. Although 'C4x zero-wait-state writes take two H1 cycles, writes appear to take one cycle internally (from the perspective of the CPU and DMA) if no access to the interface is already in progress.

In the read cycle following the writes in Figure 4-4, the 'C4x requires zero-waitstate memories to have a $\overline{\text { LSTRB-active to data-valid time of less than } 21 \mathrm{~ns}}$ (one H 1 cycle minus ( H 1 low to LSTRB active plus data setup before H 1 low)). For most memory devices, this time is the same as the memory access time, which is $t_{1}=20 \mathrm{~ns}$ in this design. Thus, a margin of only 1 ns exists, leaving little allowance for STRB gating if desired.

### 4.4.3 RAM Interface Using One Local Strobe

Figure 4-5 shows the 'C4x's local bus interfaced to eight Integrated Device Technology IDT71258 20-ns 64K $\times 4$-bit CMOS static RAMs with zero wait states using chip-enable controlled write cycles. The SRAMs are arranged to implement the first 64K, 32-bit words in external memory, located at addresses 00000h thru 0FFFFh (internal ROM is assumed to be disabled). If these 64 K words of SRAM are the only memory controlled by $\overline{\text { LSTRB } 0 \text {, the LSTRB AC- }}$ TIVE field of the local memory interface control register (LMICR) should be set to its minimum value of $01111_{2}$, allowing $\overline{\text { LSTRBO }}$ to be active for only the first

64 K words of the 'C4x's memory space. In addition, if this memory is the only memory interfaced to LSTRB0, LSTRB0 requires only one page, and the PAGESIZE field of the LMICR should be set to $01111_{2}$. Also note that in Figure 4-5, the $\overline{\text { LRDY0 input is tied low, selecting zero wait states for all }}$ $\overline{\text { LSTRB } 0 ~ a c c e s s e s ~ o n ~ t h e ~ l o c a l ~ b u s . ~ W i t h ~ a l l ~ o f ~ t h e ~ z e r o-w a i t-s t a t e ~ m e m o r y ~}$ controlled by $\overline{\text { LSTRB0 }} 0, \overline{\text { LSTRB1 }}$ can be used to control accesses to slower read-only memory devices or other types of memory.

Figure 4-5. 'C4x Interface to Eight Zero-Wait-State SRAM


In this circuit implementation, no external logic is necessary to interface the 'C4x to the memory device. Typically, memory devices must be held inactive ( $\overline{\mathrm{CS}}$ inactive) during changes in $\overline{\mathrm{WE}}$; this avoids undesired memory accesses while the address changes. The ' C 4 x ensures this glueless interface because $\overline{\text { LSTRB }}$ always frames changes in LR/W.

### 4.4.4 RAM Interface Using Both Local Strobes

Figure 4-6 shows the 'C4x's local bus interfaced to HM6708 - 20-ns 64K × 4 -bit CMOS static RAMs with zero wait states using $\overline{\mathrm{CS}}$ controlled write cycles.

These RAMs are arranged to allow 128K 32-bit words of local memory, which are implemented as two $64 \mathrm{~K} \times 32$-bit banks. One bank is controlled by each of the two sets of control signals on the local bus. To map these memory devices properly in the 'C4x's memory space, you must use the local-memory-interface control register (LMICR) to define which part of the local bus's memory space is mapped to each of the two strobes. In this implementation with internal ROM disabled, $\overline{\text { LSTRB } 0} 0$ is mapped to the first 64 K words of the local space (addresses Oh through OFFFFh), and $\overline{\text { LSTRB1 }}$ is mapped to the rest of the local space (addresses 10000h through 7FFF FFFFh). For this memory configuration, the LSTRB ACTIVE field of the local-memory-interface control register (LMICR) should be set to $01111_{2}$. Also, each LSTRB requires only one page. The PAGESIZE field of the LMICR should be set to 011112. Note that in Figure 4-6, the LRDY inputs are tied low, selecting zero wait states for all accesses on the local bus.

Hence, through the use of the 'C4x's four strobes (two each on the local and global buses), four different banks of memory can be decoded. In addition, through program control, you can change the address decoding under program control by changing the LSTRB active field (bits 24-28) of the LMICR or the global-memory-interface control register (GMICR). If you must decode more than four banks of memory or if the chosen memory device cannot meet the read cycle timing requirements for the 'C4x at zero wait states, you should use page switching (discussed in subsection 4.5.6 on page 4-18) to add an extra cycle to read accesses outside the current bank boundary.

Figure 4-6. 'C4x Interface to Zero-Wait-State SRAMs, Two Strobes


### 4.5 Wait States and Ready Generation

Using wait states can greatly increase a system's flexibility and reduce its hardware requirement. The 'C4x is capable of generating wait states on either the global bus or the local bus, and both buses have independent sets of ready control logic. The buses' wait-state configuration is determined by the SWW and WTCNT fields of the local and global-bus-interface control registers.

This section discusses ready generation from the perspective of the globalbus interface; however, wait-state operation on the local bus is the same as on the global bus, so this discussion pertains equally well to both (local and global). Also, the local and global buses each have two sets of control signals — R/Wे $0, \overline{\mathrm{STRB}} 0, \overline{\mathrm{RDY}} 0, \overline{\mathrm{PAGE}} 0, \overline{\mathrm{CE}} 0$ and R/W $1, \overline{\mathrm{STRB}} 1, \overline{\mathrm{RDY}} 1, \overline{\mathrm{PAGE}} 1$, $\overline{\mathrm{CE}} 1$ — with each set of control signals having its own ready signal, providing for more flexibility in support of external devices with different speeds. Since both strobes' ready signals share the same electrical characteristics, the following discussion focuses on one of the global bus's set of control signals.

Wait states are generated by:
$\square$ The internal wait-state generator
$\square$ The external ready inputs ( $\overline{\mathrm{RDY}} 0$ or $\overline{\mathrm{RDY}} 1$ )
$\square$ The logical AND or OR of the two ready signals
When enabled, internally generated wait states affect all external cycles, regardless of the address accessed. If different numbers of wait states are required for various external devices, the external $\overline{R D Y}$ input can be used to customize wait-state generation to specific system requirements.

If either the logical OR or electrical AND (since the signals are true low) of the external and wait-count ready signals is selected, the earlier of the two signals will generate a ready condition and allow the cycle to be completed. It is not required that both signals be present.

### 4.5.1 ORing of the Ready Signals ( $\overline{\text { STRBx }}$ SWW $=10$ )

You can use the OR of the two ready signals to implement wait states for devices that require more wait states than internal logic can implement (up to seven). This feature is useful, for example, if a system contains some fast and some slow devices. In this case:
$\square$ Fast devices can generate ready externally with a minimum of logic. When fast devices are accessed, the external hardware responds promptly with ready, which terminates the cycle.

- Slow devices can use the internal wait counter for larger numbers of wait states. When slow devices are accessed, the external hardware does not respond, and the cycle is appropriately terminated after the internal wait count.

The OR of the two ready signals can also terminate the bus cycle before the number of wait states implemented with external logic allows termination. In this case, a shorter wait count is specified internally than the number of wait states implemented with the external ready logic, and the bus cycle is terminated after the wait count. Also, this feature can be used as a safeguard against inadvertent accesses to nonexistent memory that would never respond with ready and would, therefore, lock up the 'C4x.

If the OR of the two ready signals is used, however, and the internal wait-state count is less than the number of wait states implemented externally, the external ready generation logic must be able to reset its sequencing to allow a new cycle to begin immediately following the end of the internal wait count. Also, the consecutive cycles must be from independently decoded areas of memory (or from different pages in memory). Otherwise, the external ready generation logic may lose synchronization with bus cycles and generate improperly timed wait states.

### 4.5.2 ANDing of the Ready Signals ( $\overline{\mathrm{STRB}} \mathrm{SWW}=11$ )

If the logical AND (electrical OR) of the wait count and external ready signals is selected, the later of the two signals will control the internal ready signal, but both signals must be asserted. Accordingly, external ready control must be implemented for each wait-state device, and the wait count ready signal must be enabled.

This feature is useful if devices in a system are equipped to provide a ready signal but cannot respond quickly enough to meet the 'C4x's timing requirements. If these devices normally indicate a ready condition and, when accessed, respond with a wait until they become ready, the logical AND of the
two ready signals can be used to save hardware in the system. In this case, the internal wait counter can provide wait states initially, and then the external ready can provide wait states after the external device has had time to send a not-ready indication. The internal wait counter then remains ready until the external device also becomes ready, which terminates the cycle.

Additionally, the AND of the two ready signals can be used for extending the number of wait states for devices that already have external ready logic implemented, but require additional wait states under certain unique circumstances.

### 4.5.3 External Ready Generation

The optimum technique for implementing external ready generation hardware depends on the specific characteristics of the system, including the relative number of wait-state and nonwait-state devices in the system and the maximum number of wait states required for any one device. The approaches discussed here are intended to be general enough for most applications and are easily modifiable to comprehend many different system configurations.

In general, ready generation involves the following three functions:

1) Segmentation of the address space to distinguish fast and slow devices
2) Generation of properly timed ready indications
3) Logical ORing of all the separate ready timing signals together to connect to the physical ready input

Segmentation of the address space is required to obtain a unique indication of each particular area within the address space that requires wait states. This segmentation is commonly implemented in the form of chip-select generation. Chip-select signals can initiate wait states in many cases; however, occasionally, chip-select decoding considerations may provide signals that do not allow ready input timing requirements to be met. In this case, you can segment coarse address space on the basis of a small number of address lines, where simpler gating allows signals to be generated more quickly. In either case, the signal that indicates that a particular area of memory is being addressed also normally initiates the ready or wait-state signal.

When address space to be accessed has been established, a timing circuit is normally used to provide a ready indication to the processor at the appropriate point in the cycle to satisfy each device's unique requirements.

Finally, since indications of ready status from multiple devices are typically present, you should logically OR the signals by using a single gate to drive the RDY input.

### 4.5.4 Ready Control Logic

You can take one of two basic approaches to implement ready control logic, depending on the state of the ready input between accesses. If $\overline{R D Y}$ is low between accesses, the processor is always ready unless a wait state is required; if $\overline{\mathrm{RDY}}$ is high between accesses, the processor will always enter a wait state unless a ready indication is generated.

If $\overline{R D Y}$ is low between accesses, control of devices that are zero-wait-state at full speed is straightforward; no action is necessary, because ready is always active unless otherwise required. Devices requiring wait states, however, must drive ready high fast enough to meet the input timing requirements. Then, after an appropriate delay, a ready indication must be generated. This can be difficult in many circumstances because wait-state devices are inherently slow and often require complex select decoding.

If $\overline{R D Y}$ is high between accesses, zero-wait-state devices, which tend to be inherently fast, can usually respond immediately with a ready indication. Waitstate devices can simply delay their select signals appropriately to generate a ready. Typically, this approach results in the most efficient implementation of ready control logic. Figure 4-7 shows a circuit of this type, which can be used to generate 0,1 , or 2 wait states for multiple devices in a system.

Figure 4-7. Logic for Generation of 0, 1, or 2 Wait States for Multiple Devices


### 4.5.5 Example Circuit

Figure 4-7 shows how a single, 7-ns 16R4 programmable logic device (PLD) can be used to generate 0,1 , and 2 wait states for multiple devices that are interfaced to a 'C4x. In this example, distinct address bits are used to select the different wait-state devices. Here, each of the three address lines input to the 16R4 corresponds to a different speed device. For a single 16R4 implementation, up to nine different address bits can be used to select different speed devices.

The single output, 4 Q , of the PLD is connected directly to the $\overline{\mathrm{RDY}} 0$ input of the ' C 4 x to signal the completion of a bus access for external wait-state generation. Because $\overline{\mathrm{RDY}}$ is sampled on the falling of H 1 , the H 3 output clock is used as the PLD clock input.

Example 4-1 shows the ready logic equations for programming the 16R4 PLD. The PLD language used is ABEL. $\overline{\text { STRB } 0} 0$ is an input into the PLD that indicates that a valid ' C 4 x bus cycle is occurring. Also, a delayed version of $\overline{\text { STRB0 }} 0$ (synchronized with H1 going high) is provided as the strb_syn_ input signal. This delayed signal is needed to avoid problems with a race condition that may exist between $\overline{\mathrm{STRB}} 0$ going low and H 3 rising. $\overline{\text { RESET }}$ can be used to bring the state machine back to the idle state.

Notice that the $\overline{\operatorname{RDY}} 0$ output of the PLD is not registered. An asynchronous $\overline{\mathrm{RDY}} 0$ signal is necessary to generate a ready signal for zero-wait-state devices. When a zero-wait-state device is selected (ahi1 high in Example 4-1) and $\overline{\mathrm{STRB}} 0$ is low, the PLD asserts $\overline{\mathrm{RDY}} 0$ low within 7 ns . Hence, $\overline{\mathrm{RDY}} 0$ goes active fast enough to satisfy the 20 -ns setup time of $\overline{\mathrm{RDY}} 0$ low before H 1 low.

For generation of $\overline{\mathrm{RDY}} 0$ for one and two wait states, the device select address bits and strb_syn_ are delayed one and two cycles, respectively, by the PLD before a $\overline{\mathrm{RDY}} 0$ is brought active low. The one H 3 -cycle delay, required for one-wait-state device ready generation, corresponds to state wait_one in Example 4-1 and the two H3-cycle delay required for two-wait-state devices corresponds to state wait_twoa and wait_twob.

This 16R4 PLD-based design can be used to implement different numbers of wait states for multiple devices. More devices can be selected with 'C4x address lines, and a higher number of wait states can be produced with a PLD logic. Furthermore, this approach can be used in conjunction with the 'C4x's internal wait-state generator.

## Example 4-1.PLD Equations for Ready Generation

| 0001 | module ready_generation |
| :---: | :---: |
| 0002 | title' ready generation logic for 0,1 and 2 wait state devices interfaced |
| 0003 | to TMS320C4x' |
| 0004 |  |
| 0005 | C40u5 device 'P16R4'; |
| 0006 |  |
| 0007 | "inputs |
| 0008 | h3 Pin 1; |
| 0009 |  |
| 0010 |  |
| 0011 | "The following are TMS320C40 address bits used to |
| 0012 | "select the different speed devices. More can be used if |
| 0013 | "necessary. In this example, a zero wait state, a one wait |
| 0014 | "state, and a two wait state device are decoded with these <br> "three address bits |
| 0015 |  |
| 0016 | ahil Pin 2; "when high selects zero wait state device |
| 0017 | ahi2 Pin 3; "when high selects one wait state device |
| 0018 | ahi3 Pin 4; "when high selects two wait state device |
| 0019 | strb0_ Pin 5; "indicates valid TMS320C40 bus cycle |
| 0020 | reset_ Pin 6; "reset signal from TMS320c40 |
| 0021 | strb_syn_ Pin 7; "reset strb0_ synchronized with H1 rising edge. |
| 0022 | "output |
| 0023 | rdy0_ Pin 12; "ready signal to TMS320C40 |
| 0024 |  |
| 0025 | one_wait Pin 14; "internal flip-flop signal for 1 wait state |
| 0026 | "device ready signal generation |
| 0027 | two_waita Pin 15; "internal flip-flop signal for first of the two |
| 0028 | "wait states for 2 wait state devices |
| 0029 | two_waitb Pin 16; "internal flip-flop signal for second |
| 0030 | "of the two wait states for 2 wait |
| 0031 | "state devices |
| 0032 |  |
| 0033 | "name substitutions for test vectors |
| 0034 | $\mathrm{C}, \mathrm{H}, \mathrm{L}, \mathrm{X}=. \mathrm{C}, 1,0, \mathrm{X}$. ; |
| 0035 |  |
| 0036 |  |
| 0037 | "state bits |
| 0038 | outstate = [one_wait, two_waita, two_waitb]; |
| 0039 |  |
| 0040 | idle $\quad={ }^{\text {¢ b }}$ 111; |
| 0041 | wait_one = ^b011; |
| 0042 | wait_twoa = ^b101; |
| 0043 | wait_twob = ^b110; |
| 0044 |  |
| 0045 |  |
| 0046 | state_diagram outstate |
| 0047 |  |
| 0048 | state idle: |
| 0049 | if (reset_ \& ahi2 \& !strb_syn_) then wait_one |
| 0050 | else if (reset_ \& ahi3 \& !strb_syn_) then wait_twoa |

Example 4-1.PLD Equations for Ready Generation (Continued)


### 4.5.6 Page Switching Techniques

The 'C4x's programmable page-switching feature can greatly ease system design when large amounts of memory or slow external peripheral devices are required. This feature provides a time period for disabling all device selects. During the interval, slow devices are allowed time to turn off before other devices have the opportunity to drive the data bus, thus avoiding bus contention.

When page switching is enabled, any time a portion of the high-order address lines changes, as defined by the contents of the $\overline{\text { STRB }} 0$ and $\overline{\text { STRB }} 1$ PAGESIZE fields (in the global and local memory interface control registers), the corresponding $\overline{\text { STRB }}$ and PAGE go high for one full H 1 cycle. Provided that $\overline{\text { STRB }}$ is included in chip-select decodes, this causes all devices selected by that $\overline{\text { STRB }}$ to be disabled during this period. The next page of devices is not enabled until $\overline{\text { STRB }}$ and PAGE go low again.

If the high-order address lines remain constant during a read cycle, the memory access time with page switching is the same as memory access time without page switching. In addition, page switching is not required during writes, because these write cycles exhibit an inherent one-half H 1 cycle setup of address information before $\overline{\text { STRB }}$ goes low. Thus, when you use page switching for read/write devices, a minimum of half of one H 1 cycle of address setup is provided for all accesses outside a page boundary. Therefore, large amounts of memory can be implemented without wait states or extra hardware required for isolation between pages. Also, note that access time for cycles during page switching is the same as that of cycles without page switching, and, accordingly, full-speed accesses may still be accomplished within each page.

The circuit shown in Figure 4-8 illustrates page switching with the CY7B185 15 -ns $8 \mathrm{~K} \times 8$ BiCMOS static RAM. This circuit implements 32 K 32 -bit words of memory with full-speed zero wait-state accesses within each page.

Figure 4-8. Page Switching for the CY7B185


A 5-ns, 16L8 PLD decodes lines A15-A13. These lines along with $\overline{\text { STRB }} 0$ select each of the four pages in this circuit. With the PAGESIZE field of STRB0 of the global memory interface control register set to 0 Ch , the pages are selected on even 8 K -word boundaries, starting at location zero in external memory space.

This circuit cannot be implemented without page switching, because the data output's turn-on and turn-off delays cause bus conflicts, and full-speed accesses do not allow enough time for chip-select decoding for the four pages. Here, the propagation delay of the 16 L 8 is involved only during page switches, where there is sufficient time between cycles to allow new chip-selects to be decoded.

The timing of this circuit for read operations with page switching is shown in Figure 4-9. When a page switch occurs, the page address on address lines A30 - A13 is updated during the extra H 1 cycle while STRB0 is high. Then, after chip-select decodes have stabilized and the previously selected page has disabled its outputs, STRB goes low for the next read cycle. Further accesses occur at full speed with the normal bus timings, as long as another page switch is not necessary. Write cycles do not require page switching, because of the inherent address setup provided in their timings.

This timing is summarized in Table 4-2.

Figure 4-9. Timing for Read Operations Using Bank Switching


Table 4-2. Page Switching Interface Timing

| Time <br> Interval | Event | Time <br> Period |
| :---: | :--- | :---: |
| $\mathrm{t}_{1}$ | H1 falling to address/ $\overline{\text { STRB }}$ valid | 7 ns |
| $\mathrm{t}_{2}$ | $\overline{\text { STRB to select delay }}$ | 5 ns |
| $\mathrm{t}_{3}$ | Memory disable from select | 8 ns |
| $\mathrm{t}_{4}$ | H1 falling to $\overline{\text { STRB }}$ | 7 ns |
| $\mathrm{t}_{5}$ | $\overline{\text { STRB to select delay }}$ | 5 ns |
| $\mathrm{t}_{6}$ | Memory output enable delay | 3 ns |

### 4.6 Parallel Processing Through Shared Memory

The 'C4x's two memory interfaces allow flexibility to design shared-memory interfaces for parallel processing. Many processors can be linked together in a wide variety of network configurations through these ports. In this section, Figure 4-10 illustrates 'C4x shared-memory networks that you can use to fulfill many signal processing system needs.

Figure 4-10. 'C4x Shared/Distributed-Memory Networks


Shared-memory architecture

### 4.6.1 Shared Global-Memory Interface

One of the most common multiprocessor configurations is the sharing of memory by all processors in a system. Shared memory is typically implemented by tying the processors' data and address lines together. However, the shared memory interface must guarantee that no more than one processor is driving the shared bus at any one time; it must also allow all processors sharing the bus to have a chance to access shared resources.

The 'C4x supports shared memory multiprocessing with its identical globaland local-port interfaces. Both interfaces have four status output signals, (L)STAT3-0, which identify what type of access is beginning on the bus. These signals identify whether the 'C4x port is idle, a DMA read is occurring, a $\overline{\text { STRB1 }}$ write is occurring, a $\overline{\text { LOCKed access to memory is pending, etc. The signals }}$ can be interpreted by the interface to issue single access or locked access bus requests to a shared bus arbiter.

The $\overline{(\mathrm{L}) \mathrm{CE}}, \overline{(\mathrm{L}) \mathrm{AE}}$, and (L)DE input signals support shared address control and data lines. When the signals are disabled (high), they put the port's control
signals, address lines, and data lines, respectively, in the high-impedance state. These bus enable lines are asynchronous inputs to the ' C 4 x , which can quickly turn off bus drivers when another processor is accessing a shared resource. However, these signals asynchronously turn off the 'C4x's local and global buses, without memory accesses being suspended. To ensure that data written is seen externally and data read is valid, you should use the external $\overline{(L) R D Y}$ should be used for wait-state generation in shared memory designs. An (L)RDY signal should not be sent to the 'C4x until the processor has regained access to the bus ( $\overline{\mathrm{CE}}, \overline{\mathrm{AE}}, \overline{\mathrm{DE}}$ enabled) and has had enough time to complete its access. Hence, with bus enable and status signals, the 'C4x flexible bus interfaces easily implement high-speed shared bus configurations.

### 4.6.2 Shared-Memory Interface Design Example

For an example of a 'C4x shared-memory interface, see the TMS320C4x Parallel Processing Development System Technical Reference (SPRU075). In the example in that text, four ' C 4 x devices share SRAM with their global buses tied together. A bus arbitrator implemented as a programmable logic device provides a fair scheme for processor access to the shared bus. The design uses high-speed parts but employs a fully asynchronous handshake protocol that allows 'C4x devices of various speeds and also processors other than 'C4x devices to be added to this bus configuration.

The shared-memory interface in the PPDS works for 'C4x devices running at a speed of up to 32 MHz . For higher speeds, the arbitrator incorrectly takes away bus master privileges from a 'C4x between back-to-back reads to the same page (the page size is determined by the page size field in the global bus control register. The default page size for the PPDS global memory is 64 K ). If this occurs while two or more 'C4x devices are requesting the bus to perform write cycles, random shared memory locations can be corrupted.

To fix this problem for higher speeds, the busenable_signal of each 'C4x local interface can be used to generate gmce0_ and gmce1_ to prevent these signals from going low (active) if all the processors busenable_ signals are high (inactive). The busenable_signal is shown in the PLD equations in the Global Bus Interface Logic section the of the TMS320C4x Parallel Processing Development System Technical Reference). The gmce0 and gmce1 signals are shown in the Global Memory Control section of the same book.

## Programming Tips

Programming style is highly personal and reflects each individual's preferences and experiences. The purpose of this chapter is not to impose any particular style. Instead, it emphasizes some of the features of the 'C4x that can help in producing faster and/or shorter programs. The tips in this chapter cover both C and assembly language programming.

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5.2 Hints for Optimizing Assembly-Language Code ................... 5-5

### 5.1 Hints for Optimizing C Code

The 'C4x's large register file, software stack, and large memory space easily support the 'C4x C Compiler. The C compiler translates standard ANSI C programs into assembly language source. It also increases the portability and decreases the porting time of applications.

The suggested methodology for developing your application follows five steps:

1) Write the application in $C$.
2) Debug the program.
3) Estimate if the program runs in real-time.
4) If the program does not run in real time:

- Use the -o2 or -o3 option when compiling

■ Use registers to pass parameters (-mr compiling option)

- Use inlining ( $-x$ compiling option)
- Remove the $-g$ option when compiling
- Follow some of the efficient code generation tips listed below.

5) Identify places where most of the execution time is spent and optimize these areas by writing assembly language routines that implement the functions.

The efficiency of the code generated by the floating point compiler depends to a large extent on how well you take advantage of the compiler strengths described above when writing your C code. There are specific constructs that can vastly improve the compiler's effectiveness:
$\square$ Use register variables for often-used variables. This is particularly true for pointer variables. Example 5-1 shows a code fragment that exchanges one object in memory with another.

## Example 5-1.Exchanging Objects in Memory


$\square$ Pre-compute subexpressions, especially array references in loops. Assign commonly used expressions to register variables where possible.
$\square$ Use *++ to step through arrays, rather than using an index to recalculate the address each time through a loop.

As an example of the previous 2 points, consider the loops in Example 5-2:

Example 5-2. Optimizing a Loop

```
/* loop 1 */
    main()
    {
        float a[10], b[10];
            int i;
            for (i = 0; i < 10; ++i)
                a[i] = (a[i] * 20) + b[i];
    }
/* loop 2 */
    main()
    {
        float a[10], b[10];
        int i;
        register float *p = a, *q = b;
        for (i = 0; i < 10; ++i)
        *p++ = (*p * 20) + *q++;
    }
```

Loop 1 executes in 19 cycles. Loop 2, which is the equivalent of loop 1, executes in 12 cycles.
$\square$ Use structure assignments to copy blocks of data. The compiler generates very efficient code for structure assignments, so nest objects within structures and use simple assignments to copy them.
$\square$ Avoid large local frames and declare the most often used local variables first. The compiler uses indirect addressing with an 8-bit offset to access local data. To access objects on the local frame with offsets greater than 255, the compiler must first load the offset into an index register. This causes 1 extra instruction and incurs 2 cycles of pipeline delay.
$\square$ Avoid the large model. The large model is inefficient because the compiler reloads the data-page pointer (DP) before each access to a global or static variable. If you have large array objects, use "malloc()" to dynamically allocate them and access them via pointers rather than declaring them globally. Example 5-3 illustrates two methods for allocating large array objects:

## Example 5-3.Allocating Large Array Objects

```
/* Bad Method */
int a[100000]; /* BAD */
    a[i] = 10;
/* Good Method */
    int *a \(=(\) int *) malloc(100000); /* GOOD */
    a[i] = 10;
```


### 5.2 Hints for Optimizing Assembly-Language Code

Each program has particular requirements. Not all possible optimizations make sense in every case. The suggestions presented in this section can be used as a checklist of available software tools.
$\square$ Use delayed branches. Delayed branches execute in a single cycle; regular branches execute in four. The three instructions that follow the delayed branch are executed whether the branch is taken or not. If fewer than three instructions are used, use the delayed branch and append NOPs. Machine cycles (time) are still being saved.
$\square$ Use delayed subroutine call and return. Regular subroutine CALL and RETS execute in four cycles. You can implement a delayed subroutine call by using link and jump (LAJ) and delayed branches with R11 register mode (BUD R11) instructions. Both LAJ and BUD instructions execute in a single cycle. Guidelines for using the LAJ instruction are the same as for delayed branches.
$\square$ Use the repeat single/block construct. This method produces loops with no overhead. Nesting such constructs will not normally increase efficiency, so try to use the feature on the most often performed loop. The RPTBD is a single-cycle instruction, and the RPTS and RPTB are fourcycle instructions. RPTBD and delayed branches are used in similar ways. Note that RPTS is not interruptible, and the executed instruction is not refetched for execution. This frees the buses for operands.

- Use parallel instructions. You can have a multiply in parallel with an add (or subtract) and stores in parallel with any multiply or ALU operation. This increases the number of operations executed in a single cycle. For maximum efficiency, observe the addressing modes used in parallel instructions and arrange the data appropriately. You can have loads in parallel with any multiply or add (or subtract). The result of a multiply by one or an add of zero is the same as a load. Therefore, to implement parallel instructions with a data load, you can substitute a multiply or an add instruction, with one extra register containing a one or zero, in place of the load instruction.
- Maximize the use of registers. The registers are an efficient way to access scratch-pad memory. Extensive use of the register file facilitates the use of parallel instructions and helps avoid pipeline conflicts when you use register addressing.
$\square$ Use the cache. The cache speeds instruction fetches and enables sim-ple-cycle access, even with slow external memory. The cache is transparent to the user, so make sure that it is enabled.
$\square$ Use internal memory instead of external memory. The internal memory ( $2 \mathrm{~K} \times 32$ bits RAM and $4 \mathrm{~K} \times 32$ bits ROM) is considerably faster to access than external memory. In a single cycle, two operands can be brought from internal memory. You can maximize performance if you use the DMA coprocessor in parallel with the CPU to transfer data you want to operate on to internal memory.
$\square$ Avoid pipeline conflicts. For time-critical operations, make sure that cycles are not missed because of pipeline conflicts. If there is no problem with program speed, ignore this suggestion.
- Plan your linker command file in advance. Memory allocation for code and data sections can have a big impact on your algorithm performance. One of the 'C4x's strengths is its sustained bandwidth achieved by having two external busses. By carefully dividing data and program between the two busses, you can minimize pipeline conflicts. You need to apply the same concept to minimize DMA/CPU access conflicts.

The above checklist is not exhaustive, and it does not address some features in detail. To learn how to exploit the full power of the ' C 4 x , carefully study its architecture, hardware configuration, and instruction set, which are all described in the TMS320C4x User's Guide (SPRU063).

## Applications-Oriented Operations

The 'C4x architecture and instruction set features facilitate the solution of numerically intensive problems. This chapter presents examples of applications that use these features, such as companding, filtering, matrix arithmetic, and fast Fourier transforms (FFT).
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### 6.1 Companding

In telecommunications, one of the primary concerns is to conserve the channel bandwidth and, at the same time, to preserve high speech quality. This is achieved by quantizing the speech samples logarithmically. It has been demonstrated that an 8 -bit logarithmic quantizer produces speech quality equivalent to that of a 13-bit uniform quantizer. The logarithmic quantization is achieved by companding (COMpress/exPANDing). Two international standards have been established for companding: the $\mu$-law (used in the United States and Japan), and the A-law (used in Europe). Detailed descriptions of $\mu$-law and A-law companding are presented in an application report on companding routines included in the book Digital Signal Processing Applications with the TMS320 Family (literature number SPRA012A).

During transmission, logarithmically compressed data in sign-magnitude form are transmitted along the communications channel. If any processing is necessary, these data should be expanded to a 14-bit (for $\mu$-law) or 13-bit (for A-law) linear format. This operation occurs when data is received at the digital signal processor. After processing, and in order to continue transmission, the result is compressed back to 8 -bit format and transmitted through the channel.

Example 6-1 and Example 6-2 show $\mu$-law compression and expansion (such as linear to $\mu$-law and $\mu$-law to linear conversion), while Example 6-3 and Example 6-4 show A-law compression and expansion. For expansion, using a look-up table is an alternative approach. It trades memory space for speed of execution. Because the compressed data is 8 bits long, a table with 256 entries can be constructed to contain the expanded data. If the compressed data is stored in the register AR0, the following two instructions put the expanded data in register R0:

```
ADDI @TABL,ARO ; @TABL = BASE ADDRESS OF TABLE
LDI *ARO,RO ; PUT EXPANDED NUMBER IN RO
```

The same look-up table approach could be used for compression, but the required table length would then be 16,384 words for $\mu$-law or 8,192 words for A-law. If this memory size is not acceptable, you should use the subroutines presented in Example 6-1 or Example 6-3.

## Example 6-1. $\mu$-Law Compression



## Example 6-2. $\mu$-Law Expansion

```
*TITLE `\mu-LAW EXPANSION'
*
* SUBROUTINE MUXPND
* TYPICAL CALLING SEQUENCE:
* LAJU MUXPND
* LDI v, R0
* NOP <---- can be other non-pipeline-break
* NOP <---- instructions
* ARGUMENT ASSIGNMENTS:
* ARGUMENT | FUNCTION
* --------- +--------------------------------
* REGISTERS USED AS INPUT: R0
* REGISTERS MODIFIED: R0, R1, R2
* REGISTER CONTAINING RESULT: R0
* BENCHMARKS: CYCLES: 11/10 (worst/best, not including subroutine overhead)
* WORDS: 11 (not including subroutine overhead)
*
*
\begin{tabular}{|c|c|c|c|}
\hline \multirow[t]{14}{*}{MUXPND} & NOT & R0, R0 & ; Complement bits \\
\hline & AND 3 & OFH, R0, R1 & ; Isolate quantization bin \\
\hline & LSH & 1, R1 & \\
\hline & ADDI & 33, R1 & ; Add bias to introduce 1xxxx1 \\
\hline & LSH3 & -4, R0 & ; Isolate segment code \\
\hline & TSTB & 08H, R0 & ; Test sign \\
\hline & BZD & R11 & ; If positive, delayed return \\
\hline & AND & 7, R0 & \\
\hline & LSH3 & R0, R1, R0 & ; Shift and put result in R0 \\
\hline & SUBI & 33, R0 & ; Subtract bias \\
\hline & BUD & R11 & ; Delayed return \\
\hline & NEGI & R0 & ; Negate if a negative number \\
\hline & NOP & & \\
\hline & NOP & & \\
\hline
\end{tabular}
```


## Example 6-3.A-Law Compression

```
* TITLE A-LAW COMPRESSION
SUBROUTINE ACMPR
TYPICAL CALLING SEQUENCE:
LAJ ACMPR
LDI v, R0
NOP <---- can be other non-pipeline-break
NOP <---- instructions
ARGUMENT ASSIGNMENTS:
ARGUMENT | FUNCTION
R0 | v = NUMBER TO BE CONVERTED
REGISTERS USED AS INPUT: RO
REGISTERS MODIFIED: R0, R1
REGISTER CONTAINING RESULT: R0
BENCHMARKS: CYCLES: 16/10 (worst/best, not including subroutine overhead)
WORDS: 16 (not including subroutine overhead)
    .global ACMPR
ACMPR LSH3 -5,R0,R1 ; Save sign of number
    ABSI RO,RO
    CMPI 1FH,R0 ;If R0<0x20
    BLED END ;do linear coding
    CMPI OFFFH,RO ;If R0>0xFFF,
    LDIGT OFFFH,RO ; saturate the result
    LSH -1,R0 ;Eliminate rightmost bit
    FLOAT RO ;Normalize: (seg+3)0WXYZx...x
    MPYF 0.125,R0 ;Adjust segment number by 2**(-3)
    LSH 1,R0 ; (seg)WXYZx...x
    PUSHF R0
    POP 
    LSH -20,R0 ;Right-justify
    AND 080H,R1 ;Set sign bit
    ADDI R1,R0 ;R0 = compressed number
    XOR OD5H,R0 ;Invert even bits for transmission
```


## Example 6-4.A-Law Expansion



### 6.2 FIR, IIR, and Adaptive Filters

Digital filters are a common requirement for digital signal processing systems. There are two types of digital filters: finite impulse response (FIR) and infinite impulse response (IIR). Each of these types can have either fixed or adaptable coefficients. In this section, the fixed-coefficient filters are presented first, and then the adaptive filters are discussed.

### 6.2.1 FIR Filters

If the FIR filter has an impulse response $h[0], h[1], \ldots, h[\mathrm{~N}-1]$, and $x[\mathrm{n}]$ represents the input of the filter at time $n$, the output $y[n]$ at time $n$ is given by this equation:
$y[n]=h[0] x[n]+h[1] x[n-1]+\ldots+h[N-1] x[n-(N-1)]$
Two features of the 'C4x that facilitate the implementation of the FIR filters are parallel multiply/add operations and circular addressing. The first permits the performance of a multiplication and an addition in a single machine cycle, while the second makes a finite buffer of length N sufficient for the data x .

Figure 6-1 shows the arrangement of the memory locations to implement circular addressing, while Example 6-5 presents the 'C4x assembly code for an FIR filter.

Figure 6-1. Data Memory Organization for an FIR Filter


To set up circular addressing, initialize the block-size register BK to block length $N$. Also, the locations for signal $x$ should start from a memory location whose address is a multiple of the smallest power of 2 that is greater than N . For instance, if $\mathrm{N}=24$, the first address for x should be a multiple of 32 (the lower 5 bits of the beginning address should be zero). To understand see Circular Addressing in the TMS320C4x User's Guide.

In Example 6-5, the pointer to the input sequence $x$ is incremented and assumed to be moving from an older input to a newer input. At the end of the subroutine, AR1 will point to the position for the next input sample.

## Example 6-5.FIR Filter

```
TITLE FIR FILTER
    SUBROUTINE FIR
    EQUATION: y (n) = h(0) * x(n) +h(1) * x(n-1) +
                ... + h(N-1) * x(n-(N-1))
    TYPICAL CALLING SEQUENCE:
    LOAD ARO
    LAJU FIR
    LOAD AR1
    LOAD RC
    LOAD BK
    ARGUMENT ASSIGNMENTS:
    ARGUMENT | FUNCTION
        -------- +---------------------------------
        AR0 ADDRESS OF h(N-1)
        AR1 ADDRESS OF x (N-1)
        RC IENGTH OF FILTER - 2 (N-2)
    REGISTERS USED AS INPUT: AR0, AR1, RC, BK
    REGISTERS MODIFIED: R0, R2, AR0, AR1, RC
    REGISTER CONTAINING RESULT: R0
    BENCHMARKS: CYCLES: 3 + N (not including subroutine overhead)
        WORDS: 6 (not including subroutine overhead)
FIR .global FIR
* RPTBD CONV ; Set up the repeat cycle
    Initialize R0:
        MPYF3 *AR0++(1),*AR1++(1)%,R0 ;h(N-1) *x(n-(N-1)) ->R0
        LDF 0.0,R2 ;Initialize R2
        NOP
* FILTER (1 <= i < N)
* 
CONV MPYF3 *AR0++(1),*AR1++(1)%,R0 ;h(N-1-i)*x(n-(N-1-i))->R0
| ADDF3 R0,R2,R2 ;Multiply and add operation
BUD R11
        ADDF RO,R2,RO 
        NOP
        NOP
* end
```

* 
* 
* 
* 

.end

### 6.2.2 IIR Filters

The transfer function of the IIR filters has both poles and zeros. Its output depends on both the input and the past output. As a rule, the filters need less computation than an FIR with similar frequency response, but the filters have the drawback of being sensitive to coefficient quantization. Most often, the IIR filters are implemented as a cascade of second-order sections called biquads. Example 6-6 and Example 6-7 show the implementation for one biquad and for any number of biquads, respectively.
$y[n]=a 1 y[n-1]+a 2 y[n-2]+b 0 x[n]+b 1 x[n-1]+b 2 x[n-2]$
However, the following two equations are more convenient and have smaller storage requirements:
$d[n]=a 2 d[n-2]+a 1 d[n-1]+x[n]$
$y[n]=b 2 d[n-2]+b 1 d[n-1]+b 0 d[n]$
Figure 6-2 shows the memory organization for this two-equation approach to the implementation of a single biquad on the 'C4x.

Figure 6-2. Data Memory Organization for a Single Biquad

| $\begin{array}{r} \text { low } \\ \text { address } \end{array}$ | filter coefficients | newest delay <br> oldest delay | newest delay node values | newest delay node values | circular queue$\qquad$ |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  | a2 |  | $\mathrm{d}(\mathrm{n})$ | $\mathrm{d}(\mathrm{n}-1)$ |  |
|  | b2 |  | $\mathrm{d}(\mathrm{n}-1)$ | $\mathrm{d}(\mathrm{n}-2)$ |  |
|  | a1 |  | $\mathrm{d}(\mathrm{n}-2)$ | $\mathrm{d}(\mathrm{n})$ |  |
|  | b1 |  |  |  |  |
| high | b0 |  |  |  |  |

As in the case of FIR filters, the address for the start of the values d must be a multiple of 4 ; that is, the last two bits of the beginning address must be zero. The block-size register BK must be initialized to 3 .

## Example 6-6.IIR Filter (One Biquad)

```
TITLE IIR FILTER
    SUBROUTINE IIR1
    IIR1 == IIR FILTER (ONE BIQUAD)
EQUATIONS: d(n) = a2 * d(n-2) + a1 * d(n-1) + x(n)
    y(n)=b2 * d(n-2) + b1 * d(n-1) + b0 * d(n)
OR y(n) = a1*y(n-1) + a2*y(n-2) + b0*x(n) + b1*x(n-1)
    +b2*x(n-2)
    TYPICAL CALLING SEQUENCE:
    load R2
LAJU IIR1
load AR0
load AR1
    load BK
ARGUMENT ASSIGNMENTS:
        ARGUMENT 
        R2
                                    SAMPLE X(N)
        AR0 友 ADDRESS OF FILTER COEFFICIENTS (A2)
        BK BK = 3
    REGISTERS USED AS INPUT: R2, AR0, AR1, BK
    REGISTERS MODIFIED: R0, R1, R2, AR0, AR1
    REGISTER CONTAINING RESULT: RO
    BENCHMARKS: CYCLES: 7 (not including subroutine overhead)
            WORDS: 7 (not including subroutine overhead)
        .global IIR1
IIR1 MPYF3 *AR0,*AR1,R0 ;a2 * d(n-2) -> R0
* end
.end
```

* 

$\left|{ }_{\star}\right|$
||
*
*
| $\mid$
*

Generally, the IIR filter contains $\mathrm{N}>1$ biquads. The equations for its implementation are given by the following pseudo-C language code:

```
\(y[0, n]=x[n]\)
for ( \(\mathrm{i}=0\); \(\mathrm{i}<\mathrm{N}\); \(\mathrm{i}++\) ) \(\{\)
    \(d[i, n]=a 2[i] d[i, n-2]+a 1[i] d[i, n-1]+y[i-1, n]\)
    \(y[i, n]=b 2[i] d[i-2]+b 1[i] d[i, n-1]+b 0[i] d[i, n]\)
\}
\(y[n]=y[N-1, n]\)
```

Figure 6-3 shows the memory organization, and Example 6-7 shows the corresponding 'C4x assembly-language code.

Figure 6-3. Data Memory Organization for $N$ Biquads


The block size register BK should be initialized to 3 , and each set of $d$ values (i.e., $d[i, n], i=0 \ldots, N-1$ ) should begin at an address that is a multiple of 4 (the last two bits zero), as stated in the case of a single biquad.

## Example 6-7.IIR Filter ( $N$ > 1 Biquads)

```
TITLE IIR FILTER (N > BIQUADS)
SUBROUTINE IIR2
EQUATIONS: y (0,n) = x(n)
FOR (i = 0; i < N; i++)
{
d(i,n) = a2(i) * d(i,n-2) + a1(i) * d(i,n-1) * y(i-1,n)
y(i,n) = b2(i) * d(i,n-2) + b1(i) * d(i,n-1) * b0(i) * d(i,n)
}
Y(n)}=\textrm{Y}(\textrm{N}-1,n
TYPICAL CALLING SEQUENCE:
load R2
load AR0
load AR1
load IR0
LAJU IIR2
load IR1
load BK
load RC
ARGUMENT ASSIGNMENT:
    ARGUMENT | FUNCTION*
--------- + +-----------------------------------------------
        ARO
        AR1
        BK
                ADDRESS OF FILTER COEFFICIENTS (a2(0))
                ADDRESS OF DELAY NODE VALUES (d(0,n-2))
                BK = 3
                IRO = 4
                    IR1 = 4*N-4
        IR1
                                NUMBER OF BIQUADS (N) -2
REGISTERS USED AS INPUT; R2, AR0, AR1, IR0, IR1, BK, RC
REGISTERS MODIFIED; R0, R1, R2, AR0, AR1, RC
REGISTERS CONTAINING RESULT: R0
BENCHMARKS: CYCLES: 2 + 6N (not including subroutine overhead)
                WORDS: 15 (not including subroutine overhead)
    .global IIR2
IIR2 MPYF3 *AR0,*AR1,R0 ;a2(0) * d(0,n-2) -> R0
* MPYF3 *AR0++(1),*AR1--(1)%,R1;b2(0) * d(0,n-2) -> R1
* LPTBD LOOP ; Set loop for 1 <= i < n
\begin{tabular}{lll} 
MPYF3 & \(\star++\) AR0 (1) , *AR1,R0 & ;a1 (0) * \(D(0, n-1)->R 0\) \\
ADDF & R0,R2,R2 & ;First sum term of \(d(0, n)\)
\end{tabular}
```

* 


## Example 6-7.IIR Filter ( $N>1$ Biquads) (Continued)



### 6.2.3 Adaptive Filters (LMS Algorithm)

In some applications in digital signal processing, a filter must be adapted over time to keep track of changing conditions. The book Theory and Design of Adaptive Filters by Treichler, Johnson, and Larimore (Wiley-Interscience, 1987) presents the theory of adaptive filters. Although in theory, both FIR and IIR structures can be used as adaptive filters, the stability problems and the local optimum points that the IIR filters exhibit make them less attractive for such an application. Hence, until further research makes IIR filters a better choice, only the FIR filters are used in adaptive algorithms of practical applications.

In an adaptive FIR filter, the filtering equation takes this form:
$y[n]=h[n, 0] \times[n]+h[n, 1] x[n-1]+\ldots+h[n, N-1] \times[n-(N-1)]$
The filter coefficients are time-dependent. In a least-mean-squares (LMS) algorithm, the coefficients are updated by an equation in this form:
$h[n+1, i]=h[n, 1]+b x[n-i], i=0,1, \ldots, N-1$
$b$ is a constant for the computation. The updating of the filter coefficients can be interleaved with the computation of the filter output so that it takes 3 cycles per filter tap to do both. The updated coefficients are written over the old filter coefficients. Example 6-8 shows the implementation of an adaptive FIR filter on the 'C4x. The memory organization and the positioning of the data in memory should follow the same rules as the above FIR filter with fixed coefficients.

## Example 6-8.Adaptive FIR Filter (LMS Algorithm)

```
TITLE ADAPTIVE FIR FILTER (LMS ALGORITHM)
SUBROUTINE LMS
LMS == LMS ADAPTIVE FILTER
EQUATIONS: }\quad\textrm{y}(\textrm{n})=\textrm{h}(\textrm{n},0)\mp@subsup{*}{x}{}(\textrm{n})+h(n,1)*x(n-1)+
+h(n,N-1)*x(n-(N-1))
FOR (i = 0; i < N; i++) h(n+1,i) = h(n,i)
+ tmuerr * x(n-i)
TYPICAL CALLING SEQUENCE:
load R4
load AR0
LAJU LMS
load AR1
load RC
load BK
ARGUMENT ASSIGNMENTS:
    ARGUMENT 
        R4
                                SCALE FACTOR (2 * mu * err)
        AR0
        AR1
        ADDRESS OF h(n,N-1)
        ADDRESS OF x(n-(N-1))
        RC LENGTH OF FILTER - 2 (N-2)
        BK
                            LENGTH OF FILTER (N)*
REGISTERS USED AS INPUT: R4, AR0, AR1, RC, BK
REGISTERS MODIFIED: R0, R1, R2, AR0, AR1, RC
REGISTER CONTAINING RESULT: RO
BENCHMARKS: CYCLES: 4 + 3N (not including subroutine overhead)
                PROGRAM SIZE: }9\mathrm{ words (not including subroutine overhead)
SETUP (i = 0)
LMS .global LMS [STBD LOOP ; Setup the delayed repeat block
Initialize R0:
    MPYF3 *AR0,*AR1,R0 ;h(n,N-1) * x(n-(N-1)) -> R0
    SUBF3 R2, R2, R2
;Initialize R2
Initialize R1:
    MPYF3 *AR1++(1)%,R4,R1 ;x(n-(N-1)) * tmuerr -> R1
    ADDF3 *AR0++(1),R1,R1 ;h(n,N-1) + x (n-(N-1)) *
;tmuerr -> R1
FILTER AND UPDATE (1 <= I < N)
Filter:
    MPYF3 *AR0--(1),*AR1,R0 ;h(n,N-1-i) * x(n-(N-1-i)) -> R0
    ADDF3 R0,R2,R2
*AR0-- (1) **AR1,R0
;Multiply and add operation.
UPDATE:
    MPYF3 *AR1++(1)%,R4,R1 ;x(n,N-(N-1-i)) * tmuerr -> R1
    STF R1,*AR0++(1) ;R1 }->\mathrm{ ( h(n+1,N-1-(i-1))
```

Example 6-8.Adaptive FIR Filter (LMS Algorithm) (Continued)

| LOOP | ADDF3 | *AR0 + + (1) , R1, R1 | $\begin{aligned} & \text {;h(n,N-1-i) + x(n-(N-1-i)) } \\ & \text {;*tmuerr } \rightarrow \text { R1 } \end{aligned}$ |
| :---: | :---: | :---: | :---: |
| * |  |  |  |
|  | BUD | R11 | ; Delayed return |
| * | ADDF3 | R0, R2, R0 | ; Add last product. |
|  | STF | R1, *-AR0 (1) | $\begin{aligned} & ; h(n, 0)+x(n)^{*} \text { tmuerr }-> \\ & ; h(n+1,0) \end{aligned}$ |
|  | NOP |  |  |
| * end |  |  |  |
|  | . end |  |  |

### 6.3 Lattice Filters

The lattice form is an alternative way of implementing digital filters; it has applications in speech processing, spectral estimation, and other areas. In this discussion, the notation and terminology from speech processing applications are used.

If $H(z)$ is the transfer function of a digital filter that has only poles, $A(z)=1 / H(z)$ will be a filter having only zeros, and it will be called the inverse filter. The inverse lattice filter is shown in Figure 6-4. These equations describe the filter in mathematical terms:
$f(i, n)=f(i-1, n)+k(i) b(i-1, n-1)$
$b(i, n)=b(i-1, n-1)+k(i) f(i-1, n)$
Initial conditions:
$f(0, n)=b(0, n)=x(n)$
Final conditions:
$y(n)=f(p, n)$
In the above equation, $f(i, n)$ is the forward error, $b(i, n)$ is the backward error, $k(i)$ is the $i-h$ reflection coefficient, $x(n)$ is the input, and $y(n)$ is the output signal. The order of the filter (that is, the number of stages) is $p$. In the linear predictive coding (LPC) method of speech processing, the inverse lattice filter is used during analysis, and the (forward) lattice filter is used during speech synthesis.

Figure 6-4. Structure of the Inverse Lattice Filter


Figure 6-5 shows the data memory organization of the inverse lattice filter on the 'C40.

Figure 6-5. Data Memory Organization for Inverse Lattice Filters


## Example 6-9. Inverse Lattice Filter

```
TITLE INVERSE LATTICE FILTER
SUBROUTINE LATINV
LATINV == LATTICE FILTER (LPC INVERSE FILTER - ANALYSIS)
TYPICAL CALLING SEQUENCE:
load R2
LAJU LATINV
load AR0
load AR1
load RC
ARGUMENT ASSIGNMENTS:
    ARGUMENT | FUNCTION
--------- +-----------------------------------------------------------------
    R2 fl0,n) = x(n)
    AR0 ADDRESS OF FILTER COEFFICIENTS (k (1))
    AR1 ADDRESS OF BACKWARD PROPAGATION VALUES (b (0,n-1))
    RC 
REGISTERS USED AS INPUT: R2, AR0, AR1, RC
REGISTERS MODIFIED: R0, R1, R2, R3, RS, RE, RC, AR0, AR1
REGISTER CONTAINING RESULT: R2 (f(p,n))
BENCHMARKS: CYCLES: 3 + 3p (not including subroutine overhead)
PROGRAM SIZE: }9\mathrm{ WORDS (not including subroutine overhead)
    .global LATINV
i = 1
LATINV
\begin{tabular}{|c|c|c|}
\hline RPTBD & LOOP & ; Setup the delayed repeat block loop \\
\hline MPYF3 & *AR0, *AR1, R0 & ; \(\mathrm{k}(1)\) * b (0, n-1) -> R0 \\
\hline & & ; Assume \(\mathrm{f}(0, \mathrm{n})->\mathrm{R} 2\). \\
\hline LDF & R2, R3 & ; Put b \((0, \mathrm{n})=\mathrm{f}(0, \mathrm{n})->\mathrm{R} 3\). \\
\hline MPYF3 & *AR0++ (1) , R2, R1 & ; \(\mathrm{k}(1)\) * \(\mathrm{f}(0, \mathrm{n})->\mathrm{R} 1\) \\
\hline
\end{tabular}
```


## Example 6-9. Inverse Lattice Filter (Continued)



The structure of the forward lattice filter, shown in Figure 6-6, is similar to that of the inverse filter (also shown in the figure). These corresponding equations describe the lattice filter:
$f(i-1, n)=f(i, n)-k(i) b(i-1, n-1)$ $b(i, n)=b(i-1, n-1)+k(i) f(i-1, n)$

Initial conditions:

$$
f(p, n)=x(n), b(i, n-1)=0 \quad \text { for } i=1, \ldots, p
$$

Final conditions:

$$
y(n)=f(0, n) .
$$

The data memory organization is identical to that of the inverse filter shown in Figure 6-5. Example 6-10 shows the implementation of the lattice filter on the 'C4x.

Figure 6-6. Structure of the Forward Lattice Filter


## Example 6-10. Lattice Filter

```
TITLE LATTICE FILTER
SUBROUTINE LATTICE
LAJU LATTICE
LOAD ARO
LOAD AR1
LOA RC
ARGUMENT ASSIGNMENTS:
\begin{tabular}{|c|c|}
\hline ARGUMENT & FUNCTION \\
\hline R2 & \(\mathrm{F}(\mathrm{P}, \mathrm{N})=\mathrm{E}(\mathrm{N})=\) EXCITATION \\
\hline AR0 & ADDRESS OF FILTER COEFFICIENTS (K (P)) \\
\hline AR1 & ADDRESS OF BACKWARD PROPAGATION \\
\hline & VALUES ( \(\mathrm{B}(\mathrm{P}-1, \mathrm{~N}-1)\) ) \\
\hline RC & \(\mathrm{RC}=\mathrm{P}-2\) \\
\hline
\end{tabular}
REGISTERS USED AS INPUT: R2, AR0, AR1, RC
REGISTERS MODIFIED: R0, R1, R2, R3, RS, RE, RC, AR0, AR1
REGISTER CONTAINING RESULT: R2 (f(0,n))
BENCHMARKS: CYCLES: \(1+5 P\) (not including subroutine overhead)
PROGRAM SIZE: 11 words (not including subroutine overhead)
    .global LATTICE
LATTICE RPTBD LOOP ; Setup the delayed repeat block loop
    MPYF3 *AR0, *AR1,R0 \(\quad ; \mathrm{K}(\mathrm{P})\) * \(\mathrm{B}(\mathrm{P}-1, \mathrm{~N}-1) \rightarrow \mathrm{R} 0\)
    SUBF3 R0,R2,R2 ;Assume F (P,N) -> R2
    NOP \(\quad ; F(P, N)-K(P) * B(P-1, N-1)\)
    ; \(=\mathrm{F}(\mathrm{P}-1, \mathrm{~N}) \quad->\mathrm{R} 2\)
\(2<=I<=P\) (Repeat block loop start here)
    MPYF3 *AR0,R2,R1 \(\quad\); K(I) * \(\mathrm{F}(\mathrm{I}-1, \mathrm{~N}) \rightarrow \mathrm{R}\) (
    MPYF3 *--ARO (1) , *-AR1 (1), R0 ; K (I-1) *
    ADDF3 *AR1--(1),R1,R3 \(\quad ; B(I-1, N-1)+K(I) * F(I-1, N)\)
    in \(\quad ;=B(I, N)->\) R3
    STF \(\quad\) R3, * + AR1 (2) \(\quad\) B (I,N) \(\rightarrow B(I, N-1)\)
    SUBF3 R0,R2,R2 ;F(I-1,N)-K (I-1)
    ; *B(I-1-1, N-1)
    ; \(=\mathrm{F}(\mathrm{I}-1-1, \mathrm{~N}) \quad->\mathrm{R} 2\)
    \(I=1\) (CLEANUP)
    \(\begin{array}{ll}\text { BUDR11 } & \text { *AR0,R2,R1 } \\ \text { MPYF } & \text { Delayed return } \\ & ; \mathrm{K}(1) \star \mathrm{F}(0, \mathrm{~N})->\mathrm{R} 1\end{array}\)
    ADDF3 *AR1,R1,R3 \(\quad \mathrm{B}(0, \mathrm{~N}-1)+\mathrm{K}(1) * \mathrm{~F}(0, \mathrm{~N})\)
    \(;=B(1, N)->\) R3
    STF \(\quad\) R3, * + AR1 (1) \(\quad\) B (1,N) \(\rightarrow B(1, N-1)\)
    STF R2,*AR1
    ; \(\mathrm{F}(0, \mathrm{~N}) \quad->\mathrm{B}(0, \mathrm{~N}-1)\)
end
. end
```

* 
* 


### 6.4 Matrix-Vector Multiplication

In matrix-vector multiplication, a $\mathrm{K} \times \mathrm{N}$ matrix of elements $\mathrm{m}(\mathrm{i}, \mathrm{j})$, having K rows and $N$ columns, is multiplied by an $N \times 1$ vector to produce a $K \times 1$ result. The multiplier vector has elements $\mathrm{v}(\mathrm{j})$, and the product vector has elements $p(\mathrm{i})$. Each one of the product-vector elements is computed by the following expression:
$p(i)=m(i, 0) v(0)+m(i, 1) v(1)+\ldots+m(i, N-1) v(N-1) i=0,1, \ldots, K-1$
This is essentially a dot product, and the matrix-vector multiplication contains, as a special case, the dot product presented in Example 2-1 on page 2-3 and Example 2-2 on page 2-5. In pseudo-C format, the computation of the matrix multiplication is expressed by

```
for ( \(\mathrm{i}=0\); \(\mathrm{i}<\mathrm{K}\); \(\mathrm{i}++\) ) \(\{\)
    \(p(i)=0\)
    for ( \(\mathrm{j}=0 ; \mathrm{j}<\mathrm{N} ; \mathrm{j}++\) )
        \(p(i)=p(i)+m(i, j) * v(j)\)
\}
```

Figure 6-7 shows the data memory organization for matrix-vector multiplication, and Example 6-11 shows the 'C4x assembly code that implements it. Note that in Example 6-11, K (number of rows) should be greater than 0, and N (number of columns) should be greater than 1 .

Figure 6-7. Data Memory Organization for Matrix-Vector Multiplication


## Example 6-11. Matrix Times a Vector Multiplication



Example 6-11. Matrix Times a Vector Multiplication (Continued)


### 6.5 Fast Fourier Transforms (FFTs)

Fourier transforms are an important tool often used in digital signal processing systems. The transform converts information from the time domain to the frequency domain. The inverse Fourier transform converts information back to the time domain from the frequency domain. Implementation of Fourier transforms that are computationally efficient are known as fast Fourier transforms (FFTs). The theory of FFTs can be found in books such as DFT/FFT and Convolution Algorithms by C.S. Burrus and T.W. Parks (John Wiley, 1985) and Digital Signal Processing Applications With the TMS320 Family.
'C4x features that increase efficient implementation of numerically intensive algorithms are particularly well-suited for FFTs. The high speed of the 'C4x ( 40 -ns cycle time) makes the implementation of real-time algorithms easier, while the floating-point capability eliminates the problems associated with dynamic range. The powerful indexing scheme in indirect addressing facilitates the access of FFT butterfly legs that have different spans. The repeat block implemented by the RPTB or RPTBD instruction reduces the looping overhead in algorithms heavily dependent on loops (such as the FFTs). This gives the efficiency of in-line coding with the form of a loop. Since the output of the FFT is in scrambled (bit-reversed) order when the input is in regular order, it must be restored to the proper order. This rearrangement does not require extra cycles. The device has a special form of indirect addressing (bit-reversed addressing mode) that can be used when the FFT output is needed.
The 'C4x can implement the bit-reversed addressing mode on either the CPU or DMA. This mode makes it possible to access the FFT output in the proper order. If the DMA transfer with bit-reversed addressing mode is used, there is no overhead for data input and output.
There are several types of FFT examples in this section:

- Radix-2 and radix-4 algorithms, depending on the size of the FFT butterfly
- Decimation in time or frequency (DIT or DIF)
- Complex or real FFTs
$\square$ FFTs of different lengths, etc.
The following C-callable FFT code examples are provided in this section:
$\square$ Complex radix-2 DIF FFT: subsection 6.5.1
- Complex radix-4 DIF FFT: subsection 6.5.2
- Faster Complex radix-2 DIT FFT: subsection 6.5.3
$\square$ Real radix-2 DIF FFT: subsection 6.5.4

Code for these different FFTs can be found in the DSP Bulletin Board Service (under the filename: C40FFT.EXE). This file includes code, input data and sine table examples, and batch files for compiling and linking. For instructions on how to access the BBS, see subsection 10.1.3, The Bulletin Board Service (BBS). To use these FFT codes, you need to perform two steps:
$\square$ Provide a sine table in the format required by the program. This sine table is FFT size specific, with the exception of the sine table required for Complex radix-2 DIT and the real radix-2 DIF FFT programs (as noted in Example 6-18)

- Align the input data buffer on a $\mathrm{n}+1$ memory boundary, i.e the $\mathrm{n}+1$ LSBs of the input buffer base address must be zero. ( $n=\log$ FFT_SIZE).

For most applications, the 'C4x quickly executes FFT lengths of up to 1024 points (complex) or 2048 points (real) because it can do so almost entirely in on-chip memory.

For FFTs larger than 1024 (complex), see the application report, Parallel 1-D FFT Implementation with the TMS320C4x DSPs, in the book Parallel Processing Applications with the TMS320C4x DSP (literature number SPRA031). This application note covers unprocessed partitioned FFT implementation for large FFTs. The source code is also available on the TIDSP Bulletin Board (under the filename: C40PFFT.EXE).

### 6.5.1 Complex Radix-2 DIF FFT

Example 6-12 shows a simple implementation of a complex radix-2, DIF FFT on the ' C 4 x . The code is generic and can be used with any length number. However, for the complete implementation of an FFT, a table of twiddle factors (sines/cosines) is needed, and this table depends on the size of the transform. To retain the generic form of Example 6-12, the table with the twiddle factors (containing 1-1/4 complete cycles of a sine) is presented separately in Example 6-13 for the case of a 64-point FFT. A full cycle of a sine should have a number of points equal to the FFT size. If the table with the twiddle factors and the FFT code are kept in separate files, they should be connected at link time.

Example 6-12. Complex Radix-2 DIF FFT

```
********************************************************************************
*
FILENAME CR2DIF.ASM
DESCRIPTION : COMPLEX, RADIX-2 DIF FFT FOR TMS320C40 (C callable)
* DATE : 6/29/93
* VERSION : 4.0
*
*
* DERSION DATE COMMENTS
* ------- ---- -------
* 1.0 10/87 PANNOS PAPAMICHALIS (TI Houston) Original Release
* 2.0 1/91 DANIEL CHEN (TI Houston): C40 porting
* 3.0 7/1/92 ROSEMARIE PIEDRA (TI Houston): made it C-callable
4.0 6/29/93 ROSEMARIE PIEDRA (TI Houston): added support for
*
*
*
SYNOPSIS: int cr2dif(SOURCE_ADDR,FFT_SIZE,LOGFFT,DST_ADDR)
ar2 r2 r3 rc
float *SOURCE_ADDR ; input address
int FFT_SIZE ;64, 128, 256, 512, 1024, ...
int LOGFFT ;log (base 2) of FFT_SIZE
    float *DST_ADDR ;destination address
    - The computation is done in-place.
    - Sections to be allocated in linker command file: .ffttxt : FFT code
                        .fftdat : FFT data
    If SOURCE_ADDR=DST_ADDR, then in-place bit reversing is performed
******************************************************************************
DESCRIPTION:
Generic program for a radix-2 DIF FFT computation using the TMS320C4x family.
The computation is done in-place and the result is bit-reversed. The program
    is from the Burrus and Parks book, p. 111. The input data array is 2*FFT_SIZE-
    long with real and imaginary data in consecutive memory locations: Re-Im-Re-Im
The twiddle factors are supplied in a table put in a section with a global
label _SINE pointing to the beginning of the table. This data is included in a
separate file to preserve the generic nature of the program. The sine table
size is (5*FFT_SIZE)/4.
Note: Sections needed in the linker command file: .ffttxt : FFT code
                        .fftdat : FFT data
```


## Example 6-12. Complex Radix-2 DIF FFT (Continued)

Example 6-12. Complex Radix-2 DIF FFT (Continued)


## Example 6-12. Complex Radix-2 DIF FFT (Continued)



## Example 6-12. Complex Radix-2 DIF FFT (Continued)



Fast Fourier Transforms (FFTs)

## Example 6-13. Table With Twiddle Factors for a 64-Point FFT



Example 6-13. Table With Twiddle Factors for a 64-Point FFT (Continued)

| .float | -0.956940 |
| :--- | :--- |
| .float | -0.980785 |
| .float | -0.995185 |
| .float | -1.000000 |
| .float | -0.995185 |
| .float | -0.980785 |
| .float | -0.956940 |
| .float | -0.923880 |
| .float | -0.881921 |
| .float | -0.831470 |
| .float | -0.773010 |
| .float | -0.707107 |
| .float | -0.634393 |
| .float | -0.555570 |
| .float | -0.471397 |
| .float | -0.382683 |
| .float | -0.290285 |
| .float | -0.195090 |
| .float | -0.098017 |
| .float | 0.000000 |
| .float | 0.098017 |
| .float | 0.195090 |
| .float | 0.290285 |
| .float | 0.382683 |
| .float | 0.471397 |
| .float | 0.555570 |
| .float | 0.634393 |
| .float | 0.707107 |
| .float | 0.773010 |
| .float | 0.831470 |
| .float | 0.881921 |
| .float | 0.923880 |
| .float | 0.956940 |
| .float | 0.980785 |
| .float | 0.995185 |
|  |  |

### 6.5.2 Complex Radix-4 DIF FFT

The radix-2 algorithm has tutorial value because it is relatively easy to understand how the FFT algorithm functions. However, radix-4 implementations can increase the speed of the execution by reducing the overall arithmetic required. Example 6-14 shows the generic implementation of a complex, DIF FFT in radix-4. A companion table like the one Example 6-13 should be used to provide the twiddle factor.

## Example 6-14. Complex Radix-4 DIF FFT

```
*
FILENAME : CR4DIF.ASM
DESCRIPTION : COMPLEX, RADIX-4 DIF FFT FOR TMS320C40 (C callable)
DATE: 6/29/93
VERSION : 4.0
*
********************************************************************************
*
VERSION 
```



```
********************************************************************************
SYNOPSIS: int cr4dif(SOURCE_ADDR,FFT_SIZE,LOGFFT,DST_ADDR)
    ar2 r2 r3 rc
        float *SOURCE_ADDR ;input address
    int FFT_SIZE ;64, 256, 1024, ...
    int LOGFFT ;log (base 4) of FFT_SIZE
    float *DST_ADDR ;destination address
    - The computation is done in-place.
        - Sections to be allocated in linker command file: .ffttxt : FFT code
                        .fftdat : FFT data
    If SOURCE_ADDR=DST_ADDR, then in-place bit reversing is performed
*******************************************************************************
    DESCRIPTION:
    Generic program for a radix-4 DIF FFT computation using the TMS320C4x
    family. The computation is done in-place and the result is bit-reversed.
    The program is taken from the Burrus and Parks book, p. 117.
    The input data array is 2*FFT_SIZE-long with real and imaginary data
    in consecutive memory locations: Re-Im-Re-Im
    The twiddle factors are supplied in a table put in a section
    with a global label _SINE pointing to the beginning of the table
    This data is included in a separate file to preserve the generic
    nature of the program. The sine table size is (5*FFT_SIZE)/4.
    In order to have the final results in bit-reversed order, the two
    middle branches of the radix-4 butterfly are interchanged during
    storage. Note the difference when comparing with the program in p.117
    of the Burrus and Parks book.
```

Example 6-14. Complex Radix-4 DIF FFT (Continued)


## Example 6-14. Complex Radix-4 DIF FFT (Continued)



Example 6-14. Complex Radix-4 DIF FFT (Continued)


Fast Fourier Transforms (FFTs)

## Example 6-14. Complex Radix-4 DIF FFT (Continued)

| 11 | MPYF | R3, *AR4, R0 | ; R0=R3*SI1 |
| :---: | :---: | :---: | :---: |
|  | ADDF | R0, R6 | ; R6=R1*CO1+R3*SI1 |
|  | MPYF | R4, * + AR6 (IR1) , R6 | ; R6=R4* CO 3 |
|  | STF | R6, *AR2++(IR0) | ; $\mathrm{X}(\mathrm{I} 2)=\mathrm{R} 1 * \mathrm{CO} 1+\mathrm{R} 3 *$ SI1 |
|  | MPYF | R2, *AR6, R0 | ; R0=R2*SI3 |
| \| 1 | SUBF | R0, R6 | ; R6=R1*CO3-R2*SI3 |
|  | MPYF | R2, * +AR6 (IR1) , R6 | ; R6=R2*CO3 |
|  | STF | R6, *+AR3 | ; $\mathrm{Y}(\mathrm{I} 3)=\mathrm{R} 4 * \mathrm{CO} 3-\mathrm{R} 2 * \mathrm{SI} 3$ |
|  | MPYF | R4, *AR6, R0 | ; R0=R4*SI3 |
|  | ADDF | R0, R6 | ; R6=R2* $\mathrm{CO} 3+\mathrm{R} 4 * \mathrm{SI} 3$ |
| BLK2 | STF | R6, *AR3++(IR0) | ; x (i3) $=$ R2* $\mathrm{CO} 3+\mathrm{R} 4 *$ SI3 |
|  | LDF | * +AR2, R 7 | ; Load next Y(I2) |
|  | CMP I | R11, BK |  |
|  | BPD | INLOP | ; LOOP BACK TO THE INNER LOOP |
|  | LDI | R11,AR0 |  |
|  | ADDI | @INPUTP, AR0 | ; (X(I), Y(I)) pointer |
|  | ADDI | 2,R11 | ; Increment inner loop counter |
|  | BRD | CONT |  |
|  | LSH | 2, R8 | ; Increment repeat counter for next time |
|  | LSH | 2, AR7 | ; $\mathrm{IE}=4 * \mathrm{IE}$ |
|  | LDI | BK, IR0 | ; N1=N2 |
| * SPECIAL BUTTERFLY FOR W=J |  |  |  |
| SPCL | RPTBD | BLK3 | ; Setup loop BLK3 |
|  | LSH | -1, IR1, AR4 | ; Point to SIN(45) |
|  | ADDI | @SINTAB, AR4 | ; Create cosine index AR4=CO21 |
|  | LDF | *AR2, R 7 | ; R7=X (I2) |
|  | SPCL LOOP: BLK3 |  |  |
|  | ADDF | R7, *AR0, R1 | ; $\mathrm{R} 1=\mathrm{X}(\mathrm{I})+\mathrm{X}(\mathrm{I} 2)$ |
|  | ADDF | *+AR2, *+AR0, R3 | ; R3 = $\mathrm{Y}(\mathrm{I})+\mathrm{Y}(\mathrm{I} 2)$ |
|  | SUBF | *+AR2, * +AR0, R4 | ; R4=Y(I)-Y(I2) |
|  | ADDF | *AR3, *AR1, R5 | ; R5 = ${ }_{\text {(I1 }}$ ) +X(I3) |
|  | SUBF | R1, R5, R6 | ; R6=R5-R1 |
|  | ADDF | R5, R1 | ; R1 = R1 + R5 |
|  | ADDF | *+AR3, *+AR1, R5 | ; R5 = ${ }^{\text {(I1 }}$ ) +Y (I3) |
|  | SUBF | R5, R3, R0 | ; R0 = R3-R5 |
|  | ADDF | R5, R3 | ; R3 = R3+R5 |
|  | SUBF | R7, *AR0, R2 | ; R2=X (I) - X ( 12 ) |
| 1 | STF | R3, *+AR0 | ; $\mathrm{Y}(\mathrm{I})=\mathrm{R} 3+\mathrm{R} 5$ |
|  | LDF | *AR3, R 7 | ; R7=X (I3) |
| \| | STF | R1, *AR0++ (IR0) | ; $\mathrm{X}(\mathrm{I})=\mathrm{R} 1+\mathrm{R} 5$ |
|  | SUBF | *+AR3, *+AR1, R3 | ; R3=Y(I1) - Y (I3) |
| \| $\mid$ | SUBF | R7, *AR1, R1 | ; R1 = X (I1) -X (I3) |
|  | STF | R6, *+AR1 | ; $\mathrm{Y}(\mathrm{I} 1)=\mathrm{R} 5-\mathrm{R} 1$ |
|  | ADDF | R3, R2, R5 | ; R5 = R $2+\mathrm{R} 3$ |
|  | SUBF | R2, R3, R2 | ; R2=-R2+R3 |
|  | SUBF | R1, R4, R3 | ; R3=R4-R1 |
|  | ADDF | R1, R4 | ; R4=R4+R1 |
|  | SUBF | R5, R3, R1 | ; R1=R3-R5 |
|  | MPYF | R1, *AR4, R1 | ; R1=R1*CO21 |
| \| 1 | STF | R0, *AR1++(IR0) | ; $\mathrm{X}(\mathrm{I} 1)=\mathrm{R} 3-\mathrm{R} 5$ |
|  | ADDF | R5, R3 | ; R3=R3+R5 |
| \| $\mid$ | MPYF | R3, *AR4, R3 | ; R3=R3*CO21 |
|  | STF | R1, *+AR2 | ; $\mathrm{Y}(\mathrm{I} 2)=(\mathrm{R} 3-\mathrm{R} 5) * \mathrm{CO} 21$ |
|  | SUBF | R4, R2, R1 | ; R1=R2-R4 |
|  | MPYF | R1, *AR4, R1 | ; R1=R1*CO21 |

## Example 6-14. Complex Radix-4 DIF FFT (Continued)



Fast Fourier Transforms (FFTs)

## Example 6-14. Complex Radix-4 DIF FFT (Continued)

|  | LDF | *ar1,r0 |  |
| :---: | :---: | :---: | :---: |
| \| | LDF | *ar0,r1 |  |
|  | STF | r0, *ar0 |  |
| \| | STF | r1,*ar1 |  |
|  | LDF | * +ar1 (1), r0 |  |
| \| | LDF | * +ar 0 (1) , r1 |  |
|  | STF | r0,*+ar0 (1) |  |
| \| | STF | r1, * +ar1 (1) |  |
| CONT2 | NOP | *++ar1 (2) |  |
| BITRV2 | NOP | *ar0++(ir0)b |  |
| END: | POP | R8 | ; Restore the register values and return |
|  | POP | AR7 |  |
|  | POP | AR6 |  |
|  | POP | AR5 |  |
|  | POP | AR4 |  |
|  | POP | AR3 |  |
|  | POPF | R7 |  |
|  | POP | R7 |  |
|  | POPF | R6 |  |
|  | POP | R6 |  |
|  | POP | R5 |  |
|  | POP | R4 |  |
|  | POP | DP |  |
|  | RETS <br> .end |  |  |

### 6.5.3 Faster Complex Radix-2 DIT FFT

Example 6-12 and Example 6-14 provide an easy understanding of the FFT algorithm functions. However, those examples are not optimized for fast execution of the FFT. Example 6-15 shows a faster version of a radix-2 DIT FFT algorithm. This program uses a different twiddle factor table than the previous examples. The twiddle factors are stored in bit-reversed order and with a table length of $\mathrm{N} / 2$ ( $\mathrm{N}=\mathrm{FFT}$ length) as shown in Example 6-16. For instance, if the FFT length is 32 , the twiddle factor table should be:

## Address

0

1
2
3

12
13
14
15

## Coefficient

| R\{WN(0) \} | = | COS(2*PI*0/32) |  | 1 |
| :---: | :---: | :---: | :---: | :---: |
| $-\mathrm{I}\{\mathrm{WN}(0)\}$ | = | SIN(2*PI*0/32) |  | 0 |
| R\{WN(4) \} | = | COS(2*Pl*4/32) |  | 0.707 |
| $-\mathrm{l}\{\mathrm{WN}(4)\}$ | = | SIN(2*PI*4/32) |  | 0.707 |


| $\operatorname{R}\{\mathrm{WN}(3)\}$ | $=\operatorname{COS}\left(2^{*} \mathrm{PI} 3 / 32\right)$ |
| ---: | :--- |
| $-\mid\{\mathrm{WN}(3)\}$ | $=0.831$ |
| $\mathrm{R}\{\mathrm{WN}(7)\}$ | $=\operatorname{COS}\left(2^{*} \mathrm{P} I^{*} 3 / 32\right)$ |
| $-\operatorname{CO}\left(2^{*} \mathrm{P}^{*} 7 / 32\right)$ | $=0.556$ |
| $-\{\mathrm{WN}(7)\}$ | $=\operatorname{SIN}\left(2^{*} \mathrm{P}^{*} 7 / 32\right)=0.195$ |
|  | $=0.981$ |

## Example 6-15. Faster Version Complex Radix-2 DIT FFT



Example 6-15. Faster Version Complex Radix-2 DIT FFT (Continued)


## Example 6-15. Faster Version Complex Radix-2 DIT FFT (Continued)

```
;
Initialize C Function.
.sect ".ffttxt
_cr2dit: LDI SP,AR0
    PUSH R4
    PUSH R5
    PUSH R6
    PUSHF R6
    PUSH R7
    PUSHF R7
    PUSH AR3
    PUSH AR4
    PUSH AR5
    PUSH AR6
    PUSH AR7
    PUSH DP
    .if .REGPARM == 0 ; arguments passed in stack
    LDI *-ARO(1),AR2 ; src address
    LDI *-AR0 (2),R2 ; FFT size
    LDI *-AR0 (3),R3 ; dst address
    .endif fg . Initialize DP pointer
    STI R2,@fg ; fg = FFT_SIZE
    LSH -1,R2 ; R2 = FFT_SIZE/2
    STI AR2,@inputp ; inputp = SOURCE_ADDR
    SDDI 2,AR2,R0 R0,@inputp2 ; inputp2= SOURCE_ADDR + 2
    STI R3,@outputp ; output = DST_ADDR
    STI R2,@fg2 ; fg2 = nhalb = (FFT_size/2)
    LSH -1,R2
    SUBI 2,R2,R0 ; fg4m2 = NVIERT-2 . (FFT SIZE/4)
    LSH R0,@Ig
        SUBI 2,R2,R0
        STI R0,@fg8m2
* ar0 : AR + AI
* arl : BR + BI
    ar2 : CR + CI + CR' + CI'
    ar3 : DR + DI
    ar4 : AR' + AI'
    ar5 : BR' + BI'
    ar6 : DR' + DI'
    ar7 : first twiddle factor = 1
```

Example 6-15. Faster Version Complex Radix-2 DIT FFT (Continued)


Example 6-15. Faster Version Complex, Radix-2 DIT FFT (Continued)


Example 6-15. Faster Version Complex Radix-2 DIT FFT (Continued)


Example 6-15. Faster Version Complex Radix-2 DIT FFT (Continued)


## Example 6-15. Faster Version Complex Radix-2 DIT FFT (Continued)



Example 6-15. Faster Version Complex Radix-2 DIT FFT (Continued)


Example 6-15. Faster Version Complex Radix-2 DIT FFT (Continued)


Example 6-15. Faster Version Complex Radix-2 DIT FFT (Continued)


Example 6-15. Faster Version Complex Radix-2 DIT FFT (Continued)


Fast Fourier Transforms (FFTs)

Example 6-15. Faster Version Complex Radix-2 DIT FFT (Continued)


Example 6-16. Bit-Reversed Sine Table


### 6.5.4 Real Radix-2 FFT

Most often, the data to be transformed is a sequence of real numbers. In this case, the FFT demonstrates certain symmetries that permit the reduction of the computational load even further. Example 6-17 and Example 6-18 show the generic implementation of a real-valued radix-2 FFT (forward and inverse). For such an FFT, the total storage required for a length- N transform is only N locations; in a complex FFT, 2 N are necessary. Recovery of the rest of the points is based on the symmetry conditions. A companion table (Example 6-13) should be used to provide the twiddle factors.

Example 6-17. Real Forward Radix-2 FFT

```
********************************************************************************
FILENAME : FFFT_RL.ASM
DESCRIPTION : REAL, RADIX-2 DIF FFT FOR TMS320C40
DATE : 1/19/93
VERSION : 3.0
***************************************************************************************
    VERSION DATE COMMENTS
    1.0 7/18/91 ALEX TESSAROLO(TI Australia):
    Original Release (C30 version)
    ALEX TESSAROLO(TI Australia):
    Most Stages Modified (C30 version)
    Minimum FFT Size increased from 32 to 64.
    Faster in place bit reversing algorithm.
    Program size increased by about }100\mathrm{ words.
    One extra data word required.
    3.0 1/19/93 ROSEMARIE PIEDRA(TI Houston):
    C40 porting started from C30 forward real FFT
    version 2.0. Expanded calling conventions to the use
    of registers for parameter passing.
****************************************************************************
    SYNOPSIS:
    int ffft_rl (FFT_SIZE,LOG_SIZE,SOURCE_ADDR,DEST_ADDR,SINE_TABLE,BIT_REVERSE)
        int FFT_SIZE ; 64, 128, 256, 512, 1024, ...
        int LOG_SIZE ; 6, 7, 8, 9, 10, ...
        float *SOURCE_ADDR ; Points to location of source data.
        float *DEST_ADDR ; Points to where data will be
        float *SINE_TABLE ; Points to the SIN/COS table.
        int BIT_REVERSE ; = 0, Bit Reversing is disabled.
                        ; <> O, Bit Reversing is enabled.
        NOTE: 1) If SOURCE_ADDR = DEST_ADDR, then in place bit reversing
        is performed, if enabled (more processor intensive).
        2) FFT_SIZE must be >= 64 (this is not checked).
```


## Example 6-17. Real Forward Radix-2 FFT (Continued)

```
*
*
    DESCRIPTION:
    Generic function to do a radix-2 FFT computation on the C40.
The input data array is FFT_SIZE-long with only real data. The output is
    stored in the same locations (in-place) with real and imaginary
    points R and I as follows:
    DEST_ADDR[0] -> R(0)
                                R(1)
                                R(2)
                                R(3)
                                -
                R(FFT_SIZE/2)
                I(FFT_SIZE/2 - 1)
                                I (2)
    DEST_ADDR[FFT_SIZE - 1] -> I(1)
    The program is based on the FORTRAN program in the paper by Sorensen et al.,
    June 1987 issue of Trans. on ASSP.
    Bit reversal is optionally implemented at the beginning of the function.
    The sine/cosine table for the twiddle factors is expected to be supplied in
    the following format:
    SINE_TABLE[0] -> sin(0*2*pi/FFT_SIZE)
                                sin(1*2*pi/FFT_SIZE)
                                •
                                sin((FFT_SIZE/2-2)*2*pi/FFT_SIZE)
    SINE_TABLE[FFT_SIZE/2-1] -> sin((FFT_SIZE/2-1)*2*pi/FFT_SIZE)
    NOTE: The table is the first half period of a sine wave.
*
    NOTES: 1. Calling C program can be compiled with large or small model. Both
        calling conventions methods: stack or register for parameter
        passing are supported.
            2. Sections needed in linker command file: .ffttxt : fft code
                        .fftdat : fft data
            3. The DEST_ADDR must be aligned such that the first LOG_SIZE bits
                are zero (this is not checked by the program)
    Caution: DP initialized only once in the program. Be wary with interrupt
        service routines. Make sure interrupt service routines save the DP
        pointer.
```


## Example 6-17. Real Forward Radix-2 FFT (Continued)



Example 6-17. Real Forward Radix-2 FFT (Continued)


Fast Fourier Transforms (FFTs)

Example 6-17. Real Forward Radix-2 FFT (Continued)


Example 6-17. Real Forward Radix-2 FFT (Continued)


## Example 6-17. Real Forward Radix-2 FFT (Continued)

Example 6-17. Real Forward Radix-2 FFT (Continued)


Example 6-17. Real Forward Radix-2 FFT (Continued)


Example 6-17. Real Forward Radix-2 FFT (Continued)


Example 6-17. Real Forward Radix-2 FFT (Continued)


Example 6-17. Real Forward Radix-2 FFT (Continued)

|  | LDI | @FFT_SIZE, RC |  |
| :---: | :---: | :---: | :---: |
|  | LSH | -4, RC |  |
|  | LDA | RC, IR1 |  |
|  | LDA | 2, IRO |  |
|  | SUBI | 3, RC |  |
|  | LDA | @DEST_ADDR,AR0 |  |
|  | LDA | AR0, AR1 |  |
|  | LDA | AR0, AR2 |  |
|  | LDA | AR0, AR3 |  |
|  | LDA | AR0, AR 4 |  |
|  | ADDI | 1, AR0 |  |
|  | ADDI | 7,AR1 |  |
|  | ADDI | 9, AR2 |  |
|  | ADDI | 15, AR3 |  |
|  | ADDI | 11, AR4 |  |
|  | LDA | @SINE_TABLE, AR7 |  |
|  | LDF | *++AR7 (IR1) , R7 | $\begin{aligned} & ; \mathrm{R} 7=\operatorname{SIN}(1 *[2 * \mathrm{pi} / 16]) \\ & ; * \operatorname{AR} 7=\operatorname{COS}(3 *[2 * \mathrm{pi} / 16]) \end{aligned}$ |
|  | LDA | AR7, AR6 |  |
|  | LDF | *++AR6 (IR1) , R6 | $\begin{aligned} & ; \mathrm{R} 6=\operatorname{SIN}(2 *[2 * \mathrm{pi} / 16]) \\ & ; * \operatorname{AR} 6=\operatorname{COS}(2 *[2 * \mathrm{pi} / 16]) \end{aligned}$ |
|  | LDA | AR6, AR5 |  |
|  | LDF | *++AR5 (IR1) , R5 | $\begin{aligned} & ; \mathrm{R} 5=\operatorname{SIN}(3 *[2 * \mathrm{pi} / 16]) \\ & ; * \operatorname{AR} 5=\operatorname{COS}(1 *[2 * \mathrm{pi} / 16]) \end{aligned}$ |
|  | LDA | 16, IR1 |  |
|  | MPYF3 | *AR7, *AR4, R0 | ; $\mathrm{RO}=\mathrm{X}(\mathrm{I} 3) * \cos (3)$ |
|  | MPYF3 | *++AR2 (IR0) , R5, R4 | ;R4 $=\mathrm{X}(\mathrm{I} 3) *$ SIN (3) |
|  | MPYF3 | *--AR3 (IR0) , R5, R1 | ;R1 $=\mathrm{X}(\mathrm{I} 4) *$ SIN(3) |
|  | MPYF3 | *AR7, *AR3, R0 | ; R0 $=\mathrm{X}(\mathrm{I} 4) * \operatorname{COS}(3)$ |
| \| | ADDF 3 | R0, R1, R2 | ; R2 $=[\mathrm{X}(\mathrm{I} 3) * \mathrm{COS}+\mathrm{X}(\mathrm{I} 4) *$ SIN] |
|  | MPYF3 | *AR6, *-AR4, R0 |  |
| \| | SUBF 3 | R4, R0, R3 | ; R3 $=-[\mathrm{X}(\mathrm{I} 3) * S I N-X(I 4) * C O S]$ |
|  | SUBF3 | *--AR1 (IR0) , R3, R4 | ; R4 $=-\mathrm{X}(\mathrm{I} 2)+\mathrm{R} 3--+$ |
|  | ADDF3 | *AR1, R3, R4 | ; R4 = X (I2) + R3 -- --+ |
| 1 | STF | R4, *AR2-- | ; X (I3) <------------+ |
|  | SUBF3 | R2, *++AR0 (IR0) , R 4 | ; R4 = X X (1) - R2 --+ |
| \| | STF | R4, *AR3 | ; X (I4) <------------ |
|  | ADDF 3 | *AR0, R2, R4 | ; R4 = X X 1$)+\mathrm{R} 2--$ |
| \| 1 | STF | R4, *AR1 | ; X (I2) <------------+ |
|  |  |  | ; |
|  | MPYF3 | *++AR3, R6, R1 |  |
| \| | STF | R4, *AR0 | ; X (I1) <----------------+ |
|  | ADDF3 | R0, R1, R2 |  |
|  | MPYF3 | *AR5, *-AR4 (IR0) , R0 |  |
| \| | SUBF3 | R0, R1, R3 |  |
|  | SUBF3 | * + +AR1, R3, R4 |  |
|  | ADDF3 | *AR1, R3, R4 |  |
|  | STF | R4, *AR2 |  |
|  | SUBF3 | R2, *--AR0, R4 |  |
|  | STF | R4, *AR3 |  |
|  | ADDF3 | *AR0, R2, R4 |  |
|  | STF | R4, *AR1 |  |
|  | MPYF3 | *--AR2, R $7, \mathrm{R} 4$ |  |
| \| | STF | R4, *AR0 |  |
|  | MPYF3 | * + +AR3, R7, R1 |  |
|  | MPYF3 | *AR5, *AR3, R0 |  |

Example 6-17. Real Forward Radix-2 FFT (Continued)

| $1 \mid$ | ADDF3 | R0, R1, R2 |
| :---: | :---: | :---: |
|  | MPYF3 | *AR7, *++AR4 (IR1) , R0 |
| \| | SUBF3 | R4, R0, R3 |
|  | SUBF3 | *++AR1, R3, R4 |
|  | RPTBD | LOOP 4_B |
|  | ADDF3 | *AR1, R3, R4 |
| \| | STF | R4, *AR2++ (IR1) |
|  | SUBF3 | R2, *--AR0, R4 |
| 1 | STF | R4, *AR3++(IR1) |
|  | ADDF3 | *AR0, R2, R4 |
| \| | STF | R4, *AR1++(IR1) |
|  | MPYF3 | * + +AR2 (IR0) , R5, R4 |
| \| | STF | R4, *AR0++ (IR1) |
|  | MPYF 3 | * - AR3 (IR0) , R5, R1 |
|  | MPYF 3 | *AR7, *AR3, R0 |
| \| | ADDF 3 | R0, R1, R2 |
|  | MPYF3 | *AR6, *-AR4, R0 |
| \| | SUBF3 | R4, R0, R3 |
|  | SUBF3 | *--AR1 (IR0) , R3, R4 |
|  | ADDF3 | *AR1, R3, R4 |
| \| | STF | R4, *AR2-- |
|  | SUBF3 | R2, *++AR0 (IR0) , R4 |
| 1 | STF | R4, *AR3 |
|  | ADDF3 | *AR0, R2, R4 |
| 1 | STF | R4, *AR1 |
|  | MPYF3 | *++AR3, R6, R1 |
| \| | STF | R4, *AR0 |
|  | ADDF 3 | R0,R1, R2 |
|  | MPYF3 | *AR5, *-AR4 (IR0) , R0 |
| \| | SUBF3 | R0, R1, R3 |
|  | SUBF3 | *++AR1, R3, R4 |
|  | ADDF3 | *AR1, R3, R4 |
| 1 | STF | R4, *AR2 |
|  | SUBF3 | R2, *--AR0, R4 |
| \| | STF | R4, *AR3 |
|  | ADDF3 | *AR0, R2, R4 |
| \| | STF | R4, *AR1 |
|  | MPYF3 | *--AR2, R7, R4 |
| \| | STF | R4, *AR0 |
|  | MPYF3 | * + AR $3, \mathrm{R} 7, \mathrm{R} 1$ |
|  | MPYF3 | *AR5, *AR3, R0 |
| \| | ADDF3 | R0, R1, R2 |
|  | MPYF3 | *AR7, *++AR4 (IR1) , R0 |
| \| | SUBF3 | R4, R0, R3 |
|  | SUBF3 | *++AR1, R3, R4 |
|  | ADDF3 | *AR1, R3, R4 |
| $\dagger$ | STF | R4, *AR2++ (IR1) |
|  | SUBF3 | R2, *--AR0, R4 |
|  | STF | R4, *AR3++(IR1) |
| LOOP 4_B : | ADDF3 | *AR0, R2, R4 |
| \| $\mid$ | STF | R4, *AR1++(IR1) |
|  | MPYF3 | *++AR2 (IR0) , R5, R4 |
| $\dagger$ | STF | R4, *AR0++ (IR1) |
|  | MPYF3 | * - AR3 (IR0) , R5, R1 |
|  | MPYF3 | *AR7, *AR3, R0 |
| \| | ADDF3 | R0, R1, R2 |
|  | MPYF3 | *AR6, *-AR4, R0 |

Example 6-17. Real Forward Radix-2 FFT (Continued)


## Example 6-17. Real Forward Radix-2 FFT (Continued)



Example 6-17. Real Forward Radix-2 FFT (Continued)

|  | MPYF3 | *++AR0 (IR0) , *AR4, R4 | ; R4 $=\mathrm{X}(\mathrm{I} 4) *$ SIN |
| :---: | :---: | :---: | :---: |
|  | MPYF3 | *AR0, * + A AR3, R1 | ; R1 $=\mathrm{X}(\mathrm{I} 3) *$ SIN |
|  | MPYF3 | *++AR0 (IR1) , *AR4, R0 | ; R0 $=\mathrm{X}(\mathrm{I} 4) * \mathrm{COS}$ |
|  | MPYF3 | *AR0, *AR3, R0 | ; R0 $=\mathrm{X}(\mathrm{I} 3) * \mathrm{COS}$ |
| \| 1 | SUBF3 | R1, R0, R3 | ; R3 $=-[\mathrm{X}(\mathrm{I} 3) * S I N-X(I 4) * C O S]$ |
|  | MPYF3 | *++AR0 (IR0) , *-AR4, R0 |  |
| \| $\mid$ | ADDF3 | R0, R4, R2 | ; $\mathrm{R} 2=\mathrm{X}(\mathrm{I} 3) * \mathrm{COS}+\mathrm{X}(\mathrm{I} 4) * S I N$ |
|  | SUBF3 | *AR2, R3, R4 | ; R4 $=$ R3 - X (I2) --* |
|  |  |  | . ${ }^{\text {R }}$ |
|  | RP TBD | IN_BLK |  |
|  | ADDF3 | *AR2, R3, R4 | ; R4 = R3 + X (I2) ----* |
| \| $\mid$ | STF | R4, *AR3++ | ; X (I3) <----------** |
|  | SUBF3 | R2, *AR1, R4 | ; R4 = X (I1) - R2 --* |
| \| | STF | R4, *AR4-- | ; X (I4) <------------ ${ }^{\text {- }}$ - |
|  | ADDF3 | *AR1, R2, R4 | ; R4 $=\mathrm{X}(\mathrm{I} 1)+\mathrm{R} 2--{ }^{-*}$ |
| \| $\mid$ | STF | R4, *AR2-- | ; X (I2) <-----------* |
|  | LDF | *-AR0 (IR1) , R3 | ; |
|  | MPYF3 | *AR4, R3, R4 |  |
| \| $\mid$ | STF | R4, *AR1++ | ; X (I1) <-------------* |
|  | MPYF3 | *AR3, R3, R1 |  |
|  | MPYF3 | *AR0, *AR3, R0 |  |
| \| 1 | SUBF 3 | R1, R0, R3 |  |
|  | MPYF3 | *++AR0 (IR0) , *-AR4, R0 |  |
| \| | ADDF3 | R0, R4, R2 |  |
|  | SUBF3 | *AR2, R3, R4 |  |
|  | ADDF3 | *AR2, R3, R4 |  |
| \| $\mid$ | STF | R4, *AR3++ |  |
|  | SUBF3 | R2, *AR1, R4 |  |
| \| | STF | R4, *AR4 - - |  |
| IN_BLK: | ADDF3 | *AR1, R2, R4 |  |
| \|| | STF | R4, *AR2-- |  |
|  | LDF | *-AR0 (IR1) , R3 |  |
|  | MPYF3 | *AR4, R3, R4 |  |
| $1 \mid$ | STF | R4, *AR1++ |  |
|  | MPYF3 | *AR3, R3, R1 |  |
|  | MPYF3 | *AR0, *AR3, R0 |  |
| \| $\mid$ | SUBF3 | R1, R0, R3 |  |
|  | LDA | R6, IR1 |  |
|  | ADDF 3 | R0, R4, R2 |  |
|  | SUBF3 | *AR2, R3, R4 |  |
|  | ADDF3 | *AR2, R3, R4 |  |
| \| 1 | STF | R4, *AR3++(IR1) |  |
|  | SUBF3 | R2, *AR1, R4 |  |
| \| 1 | STF | R4, *AR4++(IR1) |  |
|  | ADDF3 | *AR1, R2, R4 |  |
| \| $\mid$ | STF | R4, *AR2++(IR1) |  |
|  | STF | R4, *AR1++(IR1) |  |
|  | SUBI3 | AR5, AR1, R0 |  |
|  | CMP I | @FFT_SIZE,R0 |  |
|  | BLTD | INLOP | ; LOOP BACK TO THE INNER LOOP |
|  | LDA | @SINE_TABLE,AR0 | ; ARO POINTS TO SIN/COS TABLE |

Fast Fourier Transforms (FFTs)

Example 6-17. Real Forward Radix-2 FFT (Continued)


## Example 6-18. Real Inverse Radix-2 FFT

```
*****************************************************************************
*
* FILENAME : IFFT_RL.ASM
DESCRIPTION : INVERSE FFT FOR TMS320C40
* DATE : 1/19/93
* VERSION : 2.0
**
*
```



```
2/18/92 OANIEL MAZZOCCO(II Houston):
                                    Started from forward real FFT routine written by Alex
                                    Tessarolo, rev 2.0 .
    2.0 1/19/93 ROSEMARIE PIEDRA(TI Houston): C40 porting started from
                                    C30 inverse real FFT version 1.0 (C30). Expanded calling
                                    conventions to registers for parameter passing.
*****************************************************************************
*
SYNOPSIS:
    int ifft_rl(FFT_SIZE,LOG_SIZE,SOURCE_ADDR,DEST_ADDR,SINE_TABLE,BIT_REVERSE);
        int FFT_SIZE ; 64, 128, 256, 512, 1024, ...
    int LOG_SIZE ; 6, 7, 8, 9, 10, ...
    float *SOURCE_ADDR ; Points to where data is originated
    float *DEST_ADDR ; Points to where data will be stored.
    float *SINE_TABLE ; Points to the SIN/COS table.
    int BIT_REVERSE ; = 0, Bit Reversing is disabled.
    ; <> 0, Bit Reversing is enabled.
    NOTE: 1) If SOURCE_ADDR = DEST_ADDR, then in place bit reversing is
        performed, if enabled (more processor intensive).
            2) FFT_SIZE must be >= 64 (this is not checked).
**
DESCRIPTION:
* Generic function to do an inverse radix-2 FFT computation on the C40.
* The input data array is FFT_SIZE-long with real and imaginary points R and
* I as follows:
```


## Example 6-18. Real Inverse Radix-2 FFT (Continued)

```
-> R(0)
R(1)
R(2)
R(3)
.
R(FFT_SIZE/2)
I(FFT_SIZE/2 - 1)
I (2)
SOURCE ADDR[FFT_SIZE - 1] -> I(1)
The output data array will contain only real values. Bit reversal is
optionally implemented at the end of the function.
The sine/cosine table for the twiddle factors is expected to be supplied in
the following format:
SINE_TABLE[0] -> sin(0*2*pi/FFT_SIZE)
                                    sin(1*2*pi/FFT_SIZE)
                                    sin((FFT_SIZE/2-2)*2*pi/FFT_SIZE)
SINE_TABLE[FFT_SIZE/2-1] -> sin((FFT_SIZE/2-1)*2*pi/FFT_SIZE)
NOTE: The table is the first half period of a sine wave.
NOTE: 1.Calling C program can be compiled using either large or small model.
        Both calling conventions methods: stack or register for parameter
        passing are supported.
    2. Sections needed in linker command file: .ffttxt : fft code
                        .fftdat : fft data
    3.The SOURCE_ADDR must be aligned such that the first LOG_SIZE bits
        are zero (this is not checked by the program).
CAUTION: DP initialized only once in the program. Be wary with interrupt
        service routines.Ensure interrupt service routines save DP pointer.
REGISTERS USED: R0, R1, R2, R3, R4, R5, R6, R7
    AR0, AR1, AR2, AR3, AR4, AR5, AR6, AR7
    IR0, IR1
    RC, RS, RE
    DP
MEMORY REQUIREMENTS: Program = 322 Words (approximately)
    Data = 7 Words
```

Example 6-18. Real Inverse Radix-2 FFT (Continued)


Example 6-18. Real Inverse Radix-2 FFT (Continued)


Example 6-18. Real Inverse Radix-2 FFT (Continued)


Example 6-18. Real Inverse Radix-2 FFT (Continued)

| 11 | SUBF3 | *AR3, R4, R3 | ; R3 $=\mathrm{X}(\mathrm{I} 4)-\mathrm{X}(\mathrm{I} 3) \quad--\mid--+^{-1}$ |
| :---: | :---: | :---: | :---: |
|  | ADDF3 | R4, *AR3, R2 | ; $\mathrm{R} 2=\mathrm{X}(\mathrm{I} 3)+\mathrm{X}(\mathrm{I} 4)$ |
| \| $\mid$ | STF | R2, *AR1++ | ; $\mathrm{X}(\mathrm{I} 1)<-----------+$ |
|  | MPYF3 | R2, *AR0-- (IR1) , R4 | ; R4 = R2*COS |
| $1 \mid$ | STF | R3, *AR2-- | ; X (I2) <----------------+ |
|  | ADDF3 | R4, R1, R3 | ; R3 = R3*SIN + R2*COS -----+ |
|  | MPYF3 | R2, *AR0, R1 | ; R1 = R2*SIN |
| $1 \mid$ | STF | R3, *AR4-- | ; X (I4) <-------------------+ |
| IN_BLK: | SUBF 3 | R1, R0, R4 | ; R4 = R3*COS - R2*SIN |
|  | SUBF3 | *AR2, *AR1, R3 | ; $\mathrm{R} 3=\mathrm{X}(\mathrm{I} 1)-\mathrm{X}(\mathrm{I} 2)$ |
|  | ADDF3 | *AR1, *AR2, R2 | ; R2 $=\mathrm{X}(\mathrm{I} 1)+\mathrm{X}(\mathrm{I} 2)$---+ |
|  | MPYF3 | R3, *++AR0 (IR0) , R1 | ; R1 = R3*SIN |
| $1 \mid$ | STF | R4, *AR3++ | ; $\mathrm{X}(\mathrm{I} 3)$ |
|  | LDF | *AR4, R4 | ; $\mathrm{R} 4=\mathrm{X}(\mathrm{I} 4)$ |
|  | MPYF3 | R3, *++AR0 (IR1) , R0 | ; R0 = R3*COS |
| \| $\mid$ | SUBF3 | *AR3, R4, R3 | ; R3 $=\mathrm{X}(\mathrm{I} 4)-\mathrm{X}(\mathrm{I} 3) \quad----+$ |
|  | ADDF3 | R4, *AR3, R2 | ; $\mathrm{R} 2=\mathrm{X}(\mathrm{I} 3)+\mathrm{X}(\mathrm{I} 4)$ |
| \| | STF | R2, *AR1 | ; $\mathrm{X}(\mathrm{I} 1)$ <-------------+ |
|  | MPYF3 | R2, *AR0-- (IR1) , R4 | ; $\mathrm{R} 4=\mathrm{R} 2 * \mathrm{COS}$ |
| \| | STF | R3, *AR2 | ; X (I2) <---------------+ |
|  | LDA | R6, IR1 | ; Get prepared for the next |
|  | ADDF3 | R4, R1, R3 | ; R3 = R3*SIN + R2*COS -----+ |
|  | MPYF3 | R2, *AR0, R1 | ; R1 = R2*SIN |
| \| $\mid$ | STF | R3, *AR4++(IR1) | ; X (I4) <-------------------+ |
|  | SUBF3 | R1, R0, R4 | ; R4 = R3*COS - R2*SIN |
|  | NEGF | *AR1++(IR1) , R2 | ; DUMMY |
| $1 \mid$ | STF | R4, *AR3++(IR1) | ; X (I3) |
|  | SUBI3 | AR5, AR1, R0 |  |
|  | CMP I | @FFT_SIZE,R0 |  |
|  | BLTD | INLOP | ; LOOP BACK TO THE INNER LOOP |
|  | NOP | *AR2++ (IR1) | ; DUMMY |
|  | LDA | R7, IR1 |  |
|  | LDI | R7, RC |  |
|  | ADDI | 1, R5 |  |
|  | CMP I | @LOG_SIZE,R5 | ; next stage if any left |
|  | BLED | LOOP |  |
|  | LDA | @SOURCE_ADDR, AR1 |  |
|  | LSH | 1, IR0 | ; double step in sine table |
|  | LSH | -1, R7 |  |
| ; Perform Third FFT loop . |  |  |  |
|  |  |  |  |

Example 6-18. Real Inverse Radix-2 FFT (Continued)


Example 6-18. Real Inverse Radix-2 FFT (Continued)


Example 6-18. Real Inverse Radix-2 FFT (Continued)


Fast Fourier Transforms (FFTs)

## Example 6-18. Real Inverse Radix-2 FFT (Continued)



Example 6-18. Real Inverse Radix-2 FFT (Continued)


Example 6-18. Real Inverse Radix-2 FFT (Continued)


Example 6-18. Real Inverse Radix-2 FFT (Continued)


## 6.6 'C4x Benchmarks

Table 6-1 provides benchmarks for common DSP operations. Table 6-2 summarizes the FFT execution time required for FFT lengths between 64 and 1024 points for the four algorithms in Example 6-12, Example 6-14, Example 6-17, Example 6-18, and Example 6-15.

The benchmarks are given in cycles (the H 1 internal processor cycle). To get the benchmark (time), multiply the number of cycles by the processor's internal clock period. For example, for a 50 MHz ' C 4 x , multiply by 40 ns .

Table 6-1. 'C4x Application Benchmarks

| Application | Words | Cycles |
| :--- | :---: | :---: |
| Inverse of a float (32-bit mantissa accuracy) | 7 | 7 |
| Double-precision integer multiply | 2 | 2 |
| Square root (32-bit mantissa accuracy) | 11 | 11 |
| Vector dot product $\dagger$ | 6 | $\mathrm{~N}+4$ |
| Matrix Times a Vector | 10 | $1+\mathrm{R}(\mathrm{C}+7)$ |
| FIR Filter | 6 | $3+\mathrm{N}$ |
| IIR Filter (One Biquad) | 7 | 7 |
| IIR Filter (N>1 Biquads) | 15 | $2+6 \mathrm{~N}$ |
| LMS Lattice Filter | 11 | $1+5 \mathrm{P}$ |
| Inverse LPC Lattice Filter | 9 | $3+3 \mathrm{P}$ |
| Mu-law (A-law) Compression | $15(16)$ | $14(16 / 10)$ |
| Mu-law (A-law) Expansion | $11(15)$ | $11 / 10(15 / 13)$ |

$\dagger$ Based on a modification of the matrix times a vector benchmark

Table 6-2. FFT Timing Benchmarks (Cycles)

|  | Complex |  |  |  |  | Real |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Points | Radix-2 <br> Example 6-12 | Radix-4 <br> Example 6-14 | Radix-2 <br> Example 6-15 |  | Forward <br> Example 6-17 | Inverse <br> Example 6-18 |  |
| 64 | $2290 \dagger$ | $1745 \dagger$ | $1425 \dagger$ | $752 \dagger$ | $1012 \dagger$ |  |  |
| 128 | $5179 \dagger$ | - | $3336 \dagger$ | $1683 \dagger$ | $2269 \dagger$ |  |  |
| 256 | $11588 \dagger$ | $9216 \dagger$ | $7655 \dagger$ | $3814 \dagger$ | $5086 \dagger$ |  |  |
| 512 | $25677 \dagger$ | - | $17302 \dagger$ | $88945 \ddagger$ |  |  |  |
| 1024 | $56411 \ddagger$ | $47237 \ddagger$ |  |  |  |  |  |

## Assumptions:

$\dagger$ The data is in on-chip RAM1. Program (.fftxt) and reserved data (.fftdat) are in on-chip RAM0. The sine/Cosine table is in on-chip RAMO. Bit-reversing is not considered. The cache is enabled
$\ddagger$ The data is in on-chip RAM. Program (.ffttxt) and reserved data (.fftdat) are a in local(global) bus RAM with 0 -wait states. Bit reversing is not considered. The sine/cosine table is on the global(local) bus. The cache is enabled

## Programming the DMA Coprocessor

The 'C4x DMA (Direct Memory Access) coprocessor is a 'C4x peripheral module. With its six channels, the DMA maximizes sustained CPU performance by alleviating the CPU of burdensome I/O. Any of the six DMA channels can transfer data to and from anywhere in the 'C4x's memory map for maximum flexibility.

| Top |  | Page |
| :---: | :---: | :---: |
| 7.1 | Hints for DMA Programming | 7-2 |
| 7.2 | When a DMA Channel Finishes a Transfer | 7-3 |
| 7.3 | DMA Assembly Programming Examples | 7-4 |
| 7.4 | DMA C-Programming Examples |  |

### 7.1 Hints for DMA Programming

The following hints will help you improve your DMA programming and also help you avoid unexpected results:

- Reset the DMA register before starting it. This clears any previously latched interrupt that may no longer exist. Also, set the DIE register (enabling interrupts for sync transfer) after starting the DMA channel.
- Take care in selecting the priority used to arbitrate between the CPU and DMA and also between DMA channels. If a DMA channel fails to finish a block transfer, it may have lower priority in a conflicting environment and and not be granted access to the resource. CPU/DMA rotating priority is considered a safe first choice. Depending on CPU/DMA execution load, selection of other priority schemes could result in faster code. Fine tuning may be needed.
- Ensure that each interrupt is received when you use interrupt synchronization; otherwise, the DMA will never complete the block transfer.
- For faster execution, avoid memory/resource access conflicts between the CPU and DMA. Carefully allocate the different sections of the program in memory. Use the same care with DMA autoinitialization values in memory.
- Try to use read/write synchronization when reading from or writing to communication ports. This avoids a peripheral-bus halt during a read from an empty-input FIFO or a write to a full-output FIFO.

Choose between DMA read and write synchronization when using a DMA channel to transfer from one communication port to another. The 'C4x does not allow synchronization of DMA channel reads/writes with ICRDYi/ OCRDY $j$ signals coming from two different communication ports ( $i \neq j$ )

- When your application requires initializing the primary (or auxiliary) DMA channel while the auxiliary (or primary) channel may still be running, halt the running channel by writing a halt signal to the START or AUX START bits. Before proceeding, check the STATUS or AUX STATUS bits of the running channel to ensure it has halted. This is necessary because the DMA halt takes place in read/write boundaries (depending on the type of halt issued), and the channel must wait for any ongoing read or write cycles to complete. When reinitializing this channel, be especially careful to restore its previous status exactly. For an example of how to deal with this situation, refer to the Designer Notebook Page, split-mode DMA re-initialization, available through the DSP hotline.


### 7.2 When a DMA Channel Finishes a Transfer

Many applications require that you perform certain tasks after a DMA channel has finished a block transfer.

You can program the DMA to interrupt the CPU when this happens (TCC or AUX TCC bits). You can also achieve this by polling if:
$\square$ The corresponding IIF (DMA INTx) bit is set to 1 (interrupt polling). This requires that the DMA control register TCC (or AUX TCC) bit be set first. This method does not cause any extra CPU/DMA access conflict. But its drawback, when using split mode, is that you cannot differentiate whether the primary or auxiliary channel has finished.

The transfer counter has a zero value. This option is sometimes not reliable, because the DMA channel could be in the middle of an autoinitialization sequence.
$\square$ The TCINT (or AUX TCINT flag) is set to 1. This option is reliable, but the CPU is polled via the peripheral bus, potentially causing CPU/DMA access conflict if the DMA is operating to/from the peripheral bus. This is a good option if you do not foresee any problem with the additional access delay.
$\square$ The START (AUX START) bits in the DMA channel control register are set to $\mathbf{1 0}_{2}$. This option can also cause a CPU/DMA access conflict.

### 7.3 DMA Assembly Programming Examples

The DMA coprocessor is a memory-mapped peripheral that you can easily program from C as well as from assembly. Example 7-1 through Example 7-5 provide examples on programming the DMA coprocessor using assembly language. Example 7-6 through Example 7-11 provide examples on programming the DMA coprocessor from C . The source code for examples Example 7-6 through Example 7-11 can be found in the TI BBS (self-extracting file: C4xdmaex.exe).

Example 7-1 shows one way for setting up DMA channel 2 to initialize an array to zero. This DMA transfer is set up to have priority over a CPU operation and to generate an interrupt flag, DMA INT2, after the transfer is completed. The DMA control register is set to 00C4 0007h.

## Example 7-1.Array initialization With DMA



The DMA transfer can be synchronized with external interrupts, communica-tion-port ICRDY/OCRDY signals, and timer interrupts. In order to enable this feature, the SYNCH MODE field, bits 6-7, of the DMA-control register must be
configured to a proper value, and the corresponding bits of the DMA-interrupt enable (DIE) register must be set. Example 7-2 sets up DMA channel 4 read synchronization with the communication-port 4 ICRDY signal. The DMA continuously transfers data from the communication-port input register until the START field, bits 22-23 of the DMA control register, is changed by the CPU.

## Example 7-2.DMA Transfer With Communication-Port ICRDY Synchronization

```
* TITLE DMA TRANSFER WITH COMMUNICATION PORT ICRDY
    SYNCHRONIZATION
    * THIS EXAMPLE SETS UP DMA CHANNEL 4 TO TRANSFER DATA FROM
* COMMUNICATION PORT INPUT REGISTER TO INTERNAL RAM WITH ICRDY
    * SIGNAL READ SYNCHRONIZATION. THE TRANSFER MODE OF THE DMA IS
* SET TO OO. THEREFORE THE TRANSFER WON'T STOP UNTIL THE START
    * BITS OF THE DMA CONTROL REGISTER IS CHANGED.
* .data
DMA4 .word 001000E0H ;DMA channel 4 map address 
SOURCE .word 00100081H a
SRC_IDX .word 0
COUNT .word 0 ;Transfer counter is set to largest value
DESTIN .word 002FF800H
DES_IDX .word 1
START .text
    LDP @DMA4 ;Load data page pointer
    LDA @DMA4,AR0 ;Point to DAM channel 4 registers
    LDI @SOURCE,R0 ;Initialize DMA source register
    STI R0,*+AR0 (1)
    LDI @SRC_IDX,R0
    R0,*+AR0 (2)
    @COUNT, RO
    R0, * +AR0 (3)
    @DESTIN,RO
    R0,*+AR0 (4)
    @DES_IDX,RO ; Initialize DMA destination index register
    R0,*+AR0 (5)
    LDI @CONTROL,R0
    R0, *AR0
    LDHI 010H,DIE
        0
        1
    ;Initialize DMA source index register
    ;Initialize DMA count register
    ;Initialize DMA destination register
    ;Start DMA channel 4 transfer
    STI RO,*ARO
    ; Enable ICRDY 4 read sync.
```

If external interrupt signals are used for DMA transfer synchronization, then pins IIOFO-3 must be configured as interrupt pins.
The 'C4x DMA split mode is another way besides memory-map address to transfer data from/to the communication port. When the split-mode bit of the DMA control register is set, the DMA is separated into primary and auxiliary channels. The primary channel transfers data from memory to the commu-nication-port output register, and the auxiliary channel transfers data from the communication port to memory. The communication-port number is selected in bits15-17 of the DMA control register.

Example 7-3 shows how to set up DMA channel 1 into split mode. The DMA primary channel transfers data from internal RAM to communication port 3
through external interrupt INT2 synchronization and bit-reversed addressing. The DMA auxiliary channel transfers data from communication port 3 to internal RAM via external interrupt INT3 synchronization and linear addressing.

## Example 7-3.DMA Split-Mode Transfer With External-Interrupt Synchronization



An advantage of the 'C4x DMA is the autoinitialization feature. This allows you to set up the DMA transfer in advance and makes the DMA operation completely independent from the CPU. When the DMA operates in autoinitialization mode, the link pointer and auxiliary link pointer initialize the registers that control the DMA operation. The link pointer can be incremented (AUTOINIT STATIC $=0$ ) during autoinitialization or held constant (AUTOINIT STATIC $=1$ ) during autoinitialization. This option allows autoinitialization values to be stored in sequential memory locations or in stream-oriented devices such as the on-chip communication ports or external FIFOs. When DMA SYNC MODE is enabled, The DMA autoinitialization operation can be configured to synchronize with the same signal. Example 7-4 sets up DMA channel 0 to wait for the communication port to input the initialization value. After DMA autoinitializa-
tion is complete, the DMA channel starts transferring data from the communication port input register to internal RAM.

## Example 7-4.DMA Autoinitialization With Communication Port ICRDY



The DMA autoinitialization and transfer continues executing if the DMA autoinitialization is still enabled. Therefore, a DMA setup like the one in Example 7-4 can make it possible for an external device to control the DMA operation through the communication port.

With the autoinitialization feature, the 'C4x DMA coprocessor can support a variety of DMA operations without slowing down CPU computation. A good example is a DMA transfer triggered by one interrupt signal. Usually, this is implemented by starting a DMA activity with a CPU interrupt service routine, but this utilizes CPU time. However, as shown in Example 7-5, you can set up a single interrupt-driven dummy DMA transfer with autoinitialization. When the inter-
rupt signal is set, the DMA will complete the dummy DMA transfer and start the autoinitialization for the desired DMA transfer.

## Example 7-5.Single-Interrupt-Driven DMA Transfer

| * |  |  |  |
| :---: | :---: | :---: | :---: |
| * TITLE SINGLE INTERRUPT-DRIVEN DMA TRANSFER |  |  |  |
|  |  |  |  |
| * THIS EXAMPLE SETS UP A DUMMY DMA TRANSFER FROM INTERNAL RAM |  |  |  |
| * TO THE SAME MEMORY WITH EXTERNAL INT 0 SYNCHRONIZATION AND |  |  |  |
| * AUTOINITIALIZATION FOR TRANSFERRING 64 DATA FROM LOCAL MEMORY |  |  |  |
| * TO INTERNAL RAM. AFTER THE SECOND TRANSFER IS COMPLETED, THE |  |  |  |
| * DMA IS RE-INITIALIZED TO FIRST DMA TRANSFER SETUP |  |  |  |
|  |  |  |  |
| * .data |  |  |  |
| DMA5 | . word | 001000 FOH | ;DMA channel 5 map address |
| DMA_INIT | . word | 0000004 BH | ;DMA initialization control word |
| LINK | . word | DMA1 | ;1st DMA link list address |
| DMA_START | . word | OOCOOO4BH | ; DMA start control word |
| DMA1 | . word | OOCOOO4BH | ;1st dummy DMA transfer link list |
|  | . word | 002FF800H |  |
|  | . word | 00000000 H |  |
|  | . word | 00000001 H |  |
|  | . word | 002FF800H |  |
|  | . word | O0000000H |  |
|  | . word | DMA2 |  |
| DMA 2 | . word | 00C4000BH | ; The desired DMA transfer link |
|  | . word | 00400000 H | ; list |
|  | . word | 00000001 H |  |
|  | . word | 00000040 H |  |
|  | . word | 002FF800H |  |
|  | . word | 00000001 H |  |
|  | . word | DMA1 |  |
|  | .text |  |  |
| START | LDP | @DMA5 | ; Load data page pointer |
|  | LDA | @DMA5, AR0 | ; Point to DMA channel 5 registers |
|  | LDI | @DMA_INIT, R0 | ; Initialize DMA control register |
|  | STI | R0, *AR0 |  |
|  | LDI | @LINK, R0 | ; Initialize DMA link pointer |
|  | STI | R0, * +AR0 (6) |  |
|  | LDI | @DMA_START,R0 | ; Start DMA channel 5 transfer |
|  | STI | R0, *AR0 |  |
|  | LDI | 01H, IIF | ; Configure INTO as interrupt pins |
|  | LDHI | 0800H, DIE | ; Enable INT 0 read sync. for <br> ;DMA channel 5 |
|  | . end |  |  |

### 7.4 DMA C-Programming Examples

Example 7-6 to Example 7-11 includes DMA programing examples from C.
These examples cover unified and Split mode, DMA autoinitialization and DMA synchronization operations. Descriptions of the examples presented are as follows:

- Example 7-6: Unified-mode DMA transfers data between commports using read sync.
$\square$ Example 7-7: Unified-mode DMA uses autoinitialization (method 1) to transfer 2 data blocks.
- Example 7-8: Unified-mode DMA uses autoinitialization (method 2) to transfer 2 data blocks.
- Example 7-9: Split-mode auxiliary DMA transfers data between commports using read sync.
- Example 7-10: Split-mode auxiliary and primary channel send/receive data to and from commport
- Example 7-11: Split-mode DMA autoinitializes both auxiliary and primary channels (auxiliary transfers 1 block and primary transfers 2 blocks)

Example 7-12 is the include file for all examples (dma.h).

## Example 7-6.Unified-Mode DMA Using Read Sync

```
/***********************************************************************************
    EXAMPLE: Unified-mode
            Commport-to-commport transfer:
            DMA3 in unified mode transfers }8\mathrm{ words from commport 3 to commport 0.
            DMA3 source sync with ICRDY3 is used.
            Note: Writes cannot be synchronized with OCRDYO, because a DMA i can
            only be synchronized with signals coming commport i. You could sync
            on ICRDY3 or on OCRDYO, not both (the choice depends on the specific
            application to avoid deadlock).
            In this program, DMA3 expects data in commport 3 being sent by
            another processor/device. Otherwise no transfer will occur.
******************************************************************************************)
#include "dma.h"
#define DMAADDR 0x001000d0
#define CTRLREG 0x00c40045 /* DMA sends interrupt to CPU when transfer
                                    finishes(TC=1),DMA-CPU rotating priority */
#define SRC 0x00100071 /* src = commport 0 input fifo */
#define SRC_IDX 0x0 /* src address does not increment */
#define COUNTER 0x08 /* number of words to transfer */
#define DST 0x00100042 /* dst = commport 3 output fifo */
#define DST_IDX 0x0 /* dst address does not increment */
#define DIEVAL 0x4000 /* set ICRDY3 read sync */
DMAUNIF *dma = (DMAUNIF *)DMAADDR;
int dieval = DIEVAL;
main() {
dma->src = (void *)SRC;
dma->src_idx = SRC_IDX;
dma->counter = COUNTER;
dma->dst = (void *)DST;
dma->dst_idx = DST_IDX;
dma->ctrl = (void *)CTRLREG;
asm(" ldi @_dieval,die");
PRIM_WAIT_DMA((volatile int *)dma);
}
```

Example 7-7.Unified-Mode DMA Using Autoinitialization (Method 1)


## Example 7-8.Unified-Mode DMA Using Autoinitialization (Method 2)

```
/********************
    Autoinitialization method 2:
    DMAO in unified mode transfers 8 words from 0x02ffC00 (index 1)
    to 0x02ffd00 (index 1) and then it transfer 4 words from 0x02ffe00
    (index 4) to to 0x02fff00 (index 1). No DMA sync transfer is used
    Autonitialization method 2 requires (N-1) autoinitialization memory
    blocks to transfer N blocks and starts with a DMA transfer counter
    different from 0.
*********************************************************************************
#include "dma.h"
#define DMAADDR 0x001000a0
/* 1st transfer settings */
#define CTRLREG1 0x00c00009 /* DMA-CPU rotating priority and DMA
    autoinitializes when transfer counter = 0 */
#define SRC1 0x002ffc00 /* src address */
#define SRC1_IDX 0x1 /* src address increment */
#define COUNTER1 0x08 /* number of words to transfer */
#define DST1 0x002ffd00 /* dst address rt 3 output fifo */
#define DST1_IDX 0x1 /* dst address increment */
/* 2nd transfer settings */
#define CTRLREG2 0x00c40005 /* DMA sends interrupt to CPU when transfer
        finishes(TC=1),DMA-CPU rotating priority
        and DMA stops after transfer completes */
#define SRC2 0x002ffe00 /* src address */
#define SRC2_IDX 0x4 /* src address increment */
#define COUNTER2 0x4 /* number of words to transfer */
#define DST2 0x002fff00 /* dst address */
#define DST2_IDX 0x1 /* dst address increment */
DMAUNIF *dma = (DMAUNIF *) DMAADDR;
DMAUNIF autoini2;
main() {
/* initialize 2nd set of autoinitialization values */
autoini2.src = (void *)SRC2;
autoini2.src_idx = SRC2_IDX;
autoini2.counter = COUNTER2;
autoini2.dst = (void *)DST2;
autoini2.dst_idx = DST2_IDX;
autoini2.ctrl = (void *)CTRLREG2;
/* initialize DMA with lst set of autoinitialization values */
dma->src = (void *)SRC1;
dma->src_idx = SRC1_IDX;
dma->counter = COUNTER1;
dma->dst = (void *)DST1;
dma->dst_idx = DST1_IDX;
dma->linkp = &autoini2;
dma->ctrl = (void *)CTRLREG1;
/* wait for DMA to finish transfer */
PRIM_WAIT_DMA((volatile int *)dma);
```


## Example 7-9. Split-Mode Auxiliary DMA Using Read Sync

```
/**************************************************************************************
EXAMPLE: Split-mode (AUX only)
    Commport-to-commport transfer:
    DMA 3 Auxiliary channel transfers 8 words from commport 3 to
    commport 0. DMA3 source sync with ICRDY3 is used.
    This example is functionally equivalent to Example 7-7.
    In this program, DMA3 expects data in commport 3 being sent by
    another processor/device. Otherwise no transfer will occur.
***************************************************************************************
/
#include "dma.h"
#define DMAADDR 0x001000d0
#define CTRLREG 0x0309c091 /* DMA Aux sends interrupt to CPU when
        transfer finishes(TC=1),DMA-CPU rotating
        priority */
#define DST 0x00100042 /* dst = commport 3 output fifo */
#define DST_IDX 0x0 /* dst address does not increment */
#define DIEVAL 0x4000 /* set ICRDY3 Auxiliar read sync */
#define ACOUNTER 0x08 /* auxiliar channle counter */
DMASPLIT *dma = (DMASPLIT *)DMAADDR;
int dieval = DIEVAL;
main() {
dma->dst = (void *)DST;
dma->dst_idx = DST_IDX;
dma->acounter = ACOUNTER;
dma->ctrl = (void *)CTRLREG;
asm(" ldi @_dieval,die");
AUX_WAIT_DMA((volatile int *)dma);
}
```


## Example 7-10. Split-Mode Auxiliary and Primary Channel DMA

```
/******************************************************************************
EXAMPLE: Split-mode (AUX and PRIMARY both running)
    Commport-to-commport transfer:
    DMA3 prim. channel sends 4 words from memory (0x02ffc00) to
    commport 3 (output FIFO).
    DMA3 aux.channel receives 8 words from commport 3 (input FIFO)
    to memory (0x02ffd00)
    DMA3 prim. channel uses OCRDY3 write sync.
    DMA3 aux. channel uses ICRDY3 read sync.
    In this program, DMA3 aux channel expects data in commport 3 being
    sent by another processor/device. Otherwise no aux channel transfer
    will occur.
*******************************************************************************/
#include "dma.h"
#define DMAADDR 0x001000d0
#define CTRLREG 0x03cdc0d5 /* DMA Aux/prim send interrupt to CPU when
                        transfer finishes(TC=1), DMA-CPU rotating
                        priority, read/write sync transfer */
#define DIEVAL 0x24000 /* set ICRDY3/OCRDY read/write sync */
#define DST 0x02ffd00 /* auxiliary channel settings */
#define DST_IDX 0x1
#define ACOUNNTER 0x08
#define SRC 0x02ffc00 /* primary channel settings */
#define SRC_IDX 0x1
#define COUNTER 0x04
DMASPLIT *dma = (DMASPLIT *) DMAADDR;
int dieval = DIEVAL;
main() {
dma->src = (void *)SRC; /* primary channel */
dma->src_idx = SRC_IDX;
dma->counter = COUNTER;
dma->dst = (void *)DST; /* auxiliary channel */
dma->dst_idx = DST_IDX;
dma->acounter = ACOUNTER;
dma->ctrl = (void *)CTRLREG;
asm(" ldi @_dieval,die");
SPLIT_WAIT_DMA((volatile int *)dma);
}
```


## Example 7-11. Split-Mode DMA Using Autoinitialization

```
/******************************************************************************
EXAMPLE : Split-mode (AUX and PRIMARY both running)
    Autoinitialization example:
    DMA3 aux .channel autoinitializes and THEN receives 4 words from
    commport 3 (input FIFO) to memory (0x02ffd00).
    DMA3 pri.channel sends 4 words from memory (0x02ffc00) to
    commport 3 (output FIFO) and THEN other 2 words from memory
    (0x02ffc10) with index=2 to commport 3 (output FIFO).
    DMA3 prim. channel uses OCRDY3 write sync.
    DMA3 aux. channel uses ICRDY3 read sync.
    Autoinitialization method 1 is used in all cases.
    In this program, DMA3 aux channel expects data in commport 3 being
    sent by another processor/device. Otherwise no aux channel transfer
    will occur.
*********************************************************************************
#include "dma.h"
#define DMAADDR 0x001000d0
#define CTRLREG1 0x03cdc0e9 /* DMA aux/prim send interrupt to CPU when
    transfer finishes(TC=1),DMA-CPU rotating
    priority, read/write sync transfer */
#define CTRLREG2 0x03cdc0d5 /* same as above but transfer finishes */
#define DIEVAL 0x24000 /* set ICRDY3/OCRDY read/write sync */
/* Primary Channel */
#define SRC1
    0x02ffc00 /* autoinitialization 1 */
#define SRC1_IDX 0x1
#define COUNTER1 0x04
#define SRC2 0x02ffc10 /* autoinitialization 2 */
#define SRC2_IDX 0x2
#define COUNTER2 0x02
/* Auxiliary channel */
#define DST1 0x02ffd00 /* autoinitialization 1 */
#define DST1_IDX 0x1
#define ACOUNTER1 0x04
DMASPLIT *dma = (DMASPLIT *)DMAADDR;
int dieval = DIEVAL;
DMAPRIM autoini1, autoini2;
DMAAUX autoiniaux;
main() {
/* PRIMARY CHANNEL : 1st autoinitialization values */
autoini1.ctrl = (void *)CTRLREG1;
autoinil.src = (void *)SRC1;
autoini1.src_idx = SRC1_IDX;
autoini1.counter = COUNTER1;
autoini1.linkp = &autoini2;
```


## Example 7-11. Split-Mode DMA Using Autoinitialization (Continued)

```
/* PRIMARY CHANNEL : 2nd autoinitialization values */
autoini2.ctrl = (void *)CTRLREG2;
autoini2.src = (void *)SRC2;
autoini2.src_idx = SRC2_IDX;
autoini2.counter = COUNTER2;
/* AUXILIARY CHANNEL : 1st autoinitialization values */
autoiniaux.ctrl = (void *)CTRLREG2;
autoiniaux.dst = (void *)DST1;
autoiniaux.dst_idx = DST1_IDX;
autoiniaux.acounter = ACOUNTER1;
/* initialize DMA */
dma->linkp = &autoini1;
dma->alinkp = &autoiniaux;
dma->counter = 0;
dma->acounter = 0;
dma->ctrl = (void *)CTRLREG1;
asm(" ldi @_dieval,die");
/* wait for DMA to finish transfer */
SPLIT_WAIT_DMA((volatile int *)dma);
```

Example 7-12. Include File for All C Examples (dma.h)


## Using the Communication Ports

The 'C4x communication ports are very high-speed data transmission circuits. Their speed and the close proximity of multiple data lines create special challenges. General design rules that are applicable to high-speed (<10ns) memory interface design are appropriate for ' C 4 x communication-port interconnections. This chapter provides guidelines for designing communicationport interfaces.
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8.1 Communication Ports ..... 8-2
8.2 Signal Considerations ..... 8-5
8.3 Interfacing With a Non-'C4x Device ..... 8-7
8.4 Terminating Unused Communication Ports ..... 8-8
8.5 Design Tips ..... 8-9
8.6 Commport to Host Interface ..... 8-10
8.7 An I/O Coprocessor 'C4x Interface ..... 8-14
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### 8.1 Communication Ports

To provide simple processor-to-processor communication, the 'C4x has six parallel bidirectional communication ports. Because these ports have port arbitration units to handle the ownership of the communication-port data bus between the processors, you should concentrate only on the internal operation of the communication ports. For software, these communication ports can be treated as 32-bit on-chip data I/O FIFO buffers. Processor read data from/write data to communication is simple:

LDI @comm_port0_input,R0 ;Read data from comm. port 0

Or

STI R0,@comm_port0_output ; Write data to comm. port 1
If the CPU or DMA reads from or writes to the communication-port I/O FIFO and the I/O-FIFO is either empty (on a read) or full (on a write), the read/write execution will be extended either until the data is available in the input FIFO for a read, or until the space is available in the output FIFO for a write. Sometimes, you can use this feature to synchronize the devices. However, this can slow down the processing speed and even hang up the processor. Avoid such situations by synchronizing the CPU/DMA accesses with the following flags that indicate the status of the port:

ICRDY (input channel ready)
$=0$, the input channel is empty and not ready to be read.
$=1$, the input channel contains data and is ready to read.
ICFULL (input channel full)
$=0$, the input channel is not full.
$=1$, the input channel is full.
OCRDY (output channel ready)
$=0$, the output channel is full and not ready to be written.
$=1$, the output channel is not full and ready to be written.
OCEMPTY (output channel empty)
$=0$, the output channel is not empty.
$=1$, the output channel is empty.
Example 8-1 shows the reading of data from the communication port, eight data at a time using the CPU ICFULL interrupt. Example 8-2 shows the writing of data to a communication port, one datum at a time using the polling method. Both examples show DMA reads/writes. (DMA is discussed in subsection 7.3, DMA Assembly Programming Examples on page 7-4.

Example 8-1.Read Data from Communication Port With CPU ICFULL Interrupt


## Example 8-2.Write Data to Communication Port With Polling Method



### 8.2 Signal Considerations

Because of the bidirectional high-speed protocol used in the 'C4x communication ports, signal quality is extremely important. Poor quality signals can potentially cause both ends of a communication-port link to become a master. If this occurs and one communication port drives a signal request, no response is received from the other communication port, and the link hangs. This condition remains until both ' C 4 x devices are reset. If this is not corrected, the commu-nication-port drivers can be damaged.

If poor quality signals are a problem, use circuits to improve impedance matching. Because the 'C4x communication-port output buffer impedance can change during signal switching, a conventional parallel termination does not help. Serial matching resistors can be added at each end of all communication port lines (see Figure 8-1). Serial resistors help match the output buffer impedance to the line impedance and protect against signal contention caused by any potential fault condition. The resistor value, plus buffer output impedance, should match the line impedance. Results have shown that a lower than optimal serial resistor value provides better performance. A resistor value of $22-33 \Omega$ is usually a reasonable start. Some experimentation may be needed to reduce ringing effects. A good received signal should have an undershoot of 0.5 to 1.0 V or less. A resistor value that is too high results in an underdamped falling edge that does not cross the zero logic level and should be avoided.

Figure 8-1. Impedance Matching for 'C4x Communication-Port Design


Even though pullup resistors do not help for impedance matching, they are recommended at each end to avoid unintended triggering after reset, when $\overline{R E S E T}$ going low is not received on all ' C 4 x devices at the same time.

A pulldown resistor is not desirable, because it increases power consumption, does not protect the device from a fault condition, and can cause token loss and byte slippage on reset.

For jumps to other boards or for long distances, a unidirectional data flow with buffering is the preferred method. In this case, use buffers with hysteresis for $\overline{\mathrm{CSTRB}}$ and $\overline{\mathrm{CRDY}}$ at each end with delays greater than those in the data bus. This has two advantages: it cleans up the signals and helps eliminate glitches that can be erroneously perceived as valid control; it also allows the data bits to settle before the receiver sees $\overline{\text { CSTRB }}$ going low.

### 8.3 Interfacing With a Non-'C4x Device

To guarantee a correct word transfer operation between a 'C4x communication port and a non-'C4x device, the non-'C4x device should mimic the handshaking operation between CSTRB and CRDY (word transfer), CREQ and CACK (token transfer). The token transfer operation is more complex than the word transfer operation. It requires tri-stating of pins after different events. Sections 8.6 and 8.7 offer examples on how to handle token transfers with non-' C 4 x devices. The word transfer operation is much simpler. The following sequence describes the word transfer operation:

## Word transfer operation

CASE I: The non-'C4x has the token and transmits data. The ' C 4 x receives data.

1) The non-'C4x device drives the first byte (byte 0 ) into the CD data lines and then drops $\overline{\text { CSTRB }}$ low, indicating new data. There is no need to meet the maximum timing requirements, but the data should be valid before $\overline{\text { CSTRB }}$ goes low.
2) The non-' C 4 x device waits for the ' C 4 x to respond with $\overline{\mathrm{CRDY}}$ low and then can immediately drive the next data byte and bring $\overline{\text { CSTRB }}$ high.
3) The non-'C4x device waits for $\overline{\mathrm{CRDY}}$ to be high; then, steps 1,2 , and 3 repeat for bytes $1-3$.
4) After byte 3 is transmitted, the non-'C4x device can leave the byte 3 value in the CD lines until a new word is sent.
5) In 'C4x device revisions lower than 3.0, $\overline{\text { CSTRB }}$ should go high after receiving CRDY low no later than one 'C4x H1/H3 cycle between word boundaries. See Section 8.9, Implementing a CSTRB Shortener Circuiton page 8-17, for an implementation of a CSTRB shortener circuit. In 'C4x device revisions 3.0 or higher, no $\overline{\text { CSTRB }}$ width restriction exists.
6) The non-'C4x device can drive $\overline{\mathrm{CSTRB}}$ low for the next word at any time after receiving $\overline{\mathrm{CRDY}}$ high from the last byte. There is no reason to wait for the internal ' $\mathrm{C} 4 x$ synchronizer between $\overline{\mathrm{CRDY}}$ low and $\overline{\mathrm{CSTRB}}$ low for the next word to finish.
CASE II: The 'C4x has the token and transmits data. The non-'C4x device receives data.
7) After receiving $\overline{\text { CRSTB }}$ low from the ' C 4 x , indicating new data valid, the non-'C4x device can immediately read the data byte and then drive $\overline{\text { CRDY }}$ low, indicating that the byte has been read. There is no maximum time limit between these two events.
8) The non-'C4x device then waits to receive CSTRB high and can immediately drive $\overline{\mathrm{CRDY}}$ high, ending the byte transfer operation.

### 8.4 Terminating Unused Communication Ports

To avoid unintended communication port triggering, you can terminate unused communication-port control lines in one of the following ways:

- Use pullup resistors in all the communication-port control lines. Pullups in data lines of input communication ports are optional, but they lower power consumption. Pullups in data lines of output communication ports are not required; if used, they increase power consumption.
- Tie the control lines together on the same communication port, that is, $\overline{\mathrm{CSTRB}}$ to $\overline{\mathrm{CRDY}}$ and $\overline{\mathrm{CREQ}}$ to $\overline{\mathrm{CACK}}$. This holds the control inputs high without using external pullup resistors.


### 8.5 Design Tips

- Be careful with different voltage levels when running multiple ' C 4 x devices (or any other CMOS device) from different power supplies. This can create a CMOS latch-up that can permanently damage your device. Adding serial resistors to 'C4x communication ports connecting devices in different boards marginally helps to protect communication-port drivers. It is recommended that all 'C4x devices in the system remain in reset until power supplies are stable.
- Sometimes, it is beneficial to keep the line impedance as high as possible. This helps when interfacing to external cables. Typical ribbon cable impedance is about $100 \Omega$.
Because it is sometimes difficult to route high-impedance lines (especially long ones) in a circuit board, use an external ribbon cable to jump over the length of a board. In this case, only two headers should be installed in the circuit board.
$\square$ Use an alternating signal and ground scheme. This helps control differential signal coupling and impedance variation. For quality signals, use a 26 -wire ribbon (( 4 control +8 data +1 shield) ${ }^{*} 2=26$ ). The shield is needed for the signal that is otherwise on the edge.

Do not route signals on top of each other. When it is necessary to cross traces on adjacent layers, cross them at right angles to reduce coupling.

## Note:

Because the ' C 4 x communication ports are very high-speed data transmission circuits, signal quality is very important. A poor quality signal can cause the missing or slipping of a byte. If this happens, the only solution is a ' C 4 x reset. Because at reset communication ports 0,1 , and 2 are transmitters and 3,4 , and 5 are receivers, a safe reset requires resetting of every ' C 4 x connected to the ' C 4 x with the faulty condition. Global reset becomes a necessity.

### 8.6 Commport to Host Interface

A host interface between a 'C4x comport and a PC's bidirectional printer port has many advantages including freeing up the DSP bus and treating the host $P C$ as a virtual ' C 4 x node within a system of ' C 4 x devices.

This interface uses a bidirectional PC printer port interface. Logic circuits, buffers and resistors convert logic control levels driven from the printer port into 'C4x commport control signals. Signals driven from the 'C4x are converted into status signals, which can be polled in software by the PC. In addition, the PC's printer port provides the byte-wide data path into and out of the PC.

You can use this I/O interface for host-data communication, bootloading, and debug operations. With proper buffering and software control, it is also possible to build long and reliable links. The speed is primarily dependent on the speed of the host. When using a PC as the host, the speed is limited by the PC's I/O channel speed. If higher rates are needed, use a memory-mapped version of the printer port in the PC.

The printer port used to test this circuit was the DSP-550 from STB Systems, but there are other bidirectional printer ports on the market. Using the STB card in the bidirectional mode requires that a jumper be set (see your manual). Then, if a 1 is written to bits 5 or 7 of the control register (this depends on your printer port), data can be read back from the data register.

### 8.6.1 Simplified Hardware Interface for ' $\mathrm{C} 40 \mathrm{PG} \geq 3.3$, or ' C 44 devices

Figure 8-2 shows a simplified commport signal splitter that splits each commport control signal into a simple drive and sense pair of signals. Simplified, in this case, means that, though the circuit is easy to follow functionally and will operate, it is not the preferred solution (see the improved driver in Figure 8-3). The signals in this circuit can be easily buffered without risk of driver conflicts. However, keep a few things in mind about the simplified design:

- Due to commport-control signal restrictions in earlier silicon revisions this circuit will not work with the TMS320C40 PG 3.0 or lower.
- This circuit requires a bidirectional printer port.
- Standard printer-port cables often do not provide 'clean' signals
$\square$ A high value is needed for the isolation resistor in order to keep the current levels during signal opposition to a minimum. But, a low value is needed for the isolation resistor in order to insure reasonably fast rise and fall times of the commport control signals when they are inputs. This conflict can be overcome by carefully picking the correct resistor values or by adding additional biasing.

Figure 8-2. Better Commport Signal Splitter


Legend: $\quad R_{p}=470$ ohms
$R_{s}=470 \mathrm{oms}$
$R_{x}=180$ ohms
$R_{y}=220$ ohms

### 8.6.2 Improved Drive and Sense Amplifiers

Two improvements are suggested for the interface described above. The improvements are described in Figure 8-3.

Figure 8-3. Improved Interface Circuit


Legend: $\quad \begin{aligned} & R_{p}=470 \text { ohms } \\ & \\ & R_{1}=1 \mathrm{~K} \text { ohms }\end{aligned}$
$\mathrm{R}_{2}=10 \mathrm{~K}$ ohms
$C_{1}=100 \mathrm{pF}$
$\mathrm{R}_{3}=50 \mathrm{ohms}$

The first improvement is that the signals going to and from the printer port are synchronized using a clock and a simple data latch. By taking samples in time, noise which may be able to corrupt the first sample of a transistion will probably not be enough to corrupt the next sample. By adding a hysteris loop made from resistors R1 and R2, the noise immunity is improved more. Capacitor C1 is an additional analog filter that rejects high-frequency noise.

The next major improvement is the use of a current driver in place of the isolation resistor. In this case, an RS232 driver is used; this driver can drive beyond the supply rails of the DSP and has a built-in current limit of about 20 mA . Diodes D1 and D2, along with R3, clamp the resulting signal to the supply rails of the DSP and latch to prevent excessive overdrive. The DSP and latch both have internal clamping diodes, but it is not recommended that you rely on them as the internal clamp diodes are not intended for this purpose.

### 8.6.3 How the Circuit Works

The PC can drive any value on the control lines, independent from the returned status. If a logic 1 is driven into the drive side of the isolation resistor and a logic 0 is observed on the sense side, the ' C 4 x commport signal under question is without a doubt an output.

By then driving levels and polling the returned status, it is possible to synchronize a host processor to the state machine of the ' C 4 x commport. The advantage of this design is that it can be easily ported to any smart processor with any basic I/O capability. For example, TMS320C31/32 devices have been used as slave devices that are bootloaded from a commport and then used as serial ports with internal memory and additional processing capabilities. Complicated and risky ASIC designs are not required and the solution is fully programmable.

You must include current limiting circuitry when designing any 'C4x interface. If the current is not limited, it can exceed 100 mA per pin, which can damage a device.

### 8.6.4 The Interface Software

The interface software for this host interface is available through the TI BBS (filename: M4x_2.exe). This file contains not only the low-level software drivers, but also extra code for the M4x (a multiprocessor 'C4x communication kernel) applications note. The following files are contained in this application:

- M4X Debugger (no source code)
- MEMVIEW memory and communications matrix view and edit utility
- MANDEL40 multiprocessor Mandelbrot demonstration program
- M4X.ASM multiprocessor TMS320C4x communications kernel

D DRIVER.CPP higher level system functions
TARGET.CPP getmem, putmem, run, stop and singlestep commands
$\square$ OBJECT.CPP source code for using the printer port interface

### 8.7 An I/O Coprocessor-'C4x Interface

This section presents a software-based interface that provides a ' C 4 x with a flexible bidirectional interface to a TMS320C32. The 'C32 acts as a smart I/O coprocessor that can provide AIC interfacing and data preprocessing among others. The 'C32 is an inexpensive and flexible solution.

Some of the advantages of using an I/O coprocessor include:

- An I/O coprocessor can provide with data-processing.
$\square$ An I/O coprocessor allows for error correction and recovery from 'C4x commport interface problems.
$\square$ An I/O coprocessor can buffer data, allowing faster 'C4x data throughput.
Figure 8-4 shows the 'C32-to-'C4x interface. Through the interface, a 'C4x commport is memory-mapped to the 'C32 external memory bus. The interface uses four 'C32 I/O pins to drive the commport control signals.

Figure 8-4. A 'C32 to 'C4x Interface


Pullup resistors in the XF0, XF1, TCLK0 and TCLK1 lines are used to prevent undesired glitches due to temporary high-impedance conditions. Serial resistors are also used on the same pins for better impedance matching.

The interface software drivers and a more detailed explanation of the interface can be obtained from our TI BBS (filename 4xaic.exe). Token transfer and word transfer drivers are included with the software.

### 8.8 Implementing a Token Forcer

After system reset, half of the communication channels associated with a particular 'C4x have token ownership (communication ports $0,1,2$ ), and the other half (communication ports $3,4,5$ ) do not.

If, because of system configuration requirements, communication port direction must to be changed, the circuits shown in Figure 8-5 and Figure 8-6 can be used. The circuits force the token to be passed and communication port direction to remain changed.

Even though these circuits are intended to force a change of the original communication port direction after reset, they can be used also to maintain the original direction. However, this can be more conveniently achieved using pullups in $\overline{\mathrm{CACK}}$ and $\overline{\mathrm{CREQ}}$. The pullups prevent any damage to the communication ports in the event of a program error that writes into a port configured as an input.

## Forcing a communication port to become an output port

Figure 8-5 shows a circuit that forces a communication port to become an output port. In this circuit, driving the $\overline{\mathrm{CACK}}$ line with the $\overline{\mathrm{CREQ}}$ line reconfigures an input port as an output port. When a word is written to the FIFO, $\overline{\mathrm{CREQ}}$ is driven low, indicating a token request. After a synchronizer delay of 1 to 2 cycles (U1 and U2), $\overline{\mathrm{CACK}}$ is driven low, indicating a token acknowledge. $\overline{\text { CREQ }}$ then goes active high and then is held high by $R_{p}$ as the line switches to an input. The CLK signal can be any clock with a frequency equal to or lower than the $\mathrm{H} 1 / \mathrm{H} 3$ clock.

The synchronizer delay is important. If no delay is provided, the $\overline{C R E Q}$ line will not be ready to change to an input high condition. As a result, the $\overline{\mathrm{CACK}}$ line, which, at this point, is a delayed version of $\overline{\mathrm{CREQ}}$, is inverted and applied to the $\overline{\mathrm{CREQ}}$ line. This results in an oscillation until the synchronizer period has timed out.

Figure 8-5. A Token Forcer Circuit (Output)


## Forcing a communication port to become an input port

Figure 8-6 shows a circuit that forces a communication port to become an input port. In this circuit, driving the $\overline{\mathrm{CREQ}}$ line with an inverted $\overline{\mathrm{CACK}}$ reconfigures an input port as an output. If $\overline{\mathrm{CREQ}}$ is an input, it is held low through $R_{S}$ whenever $\overline{\mathrm{CACK}}$ is high or floating high because of $R_{p}$. The port then responds to this request by driving $\overline{\mathrm{CACK}}$ low, which, in turn, drives $\overline{\mathrm{CREQ}}$ high, finishing the token acknowledge. As in Figure 8-5, synchronizer delays mimic the response of another ' C 4 x communication port to prevent oscillation.

Figure 8-6. Communication-Port Driver Circuit (Input)


Note that after the port has been reconfigured as an input port, the $\overline{\mathrm{CREQ}}$ line is active high while the output of the inverter is low. This causes a constant current flow from $\overline{\mathrm{CREQ}}$ to the inverter.

### 8.9 Implementing a CSTRB Shortener Circuit

In 'C40 device revisions lower than 3.0, the width of the $\overline{\text { CSTRB }}$ low pulse between word boundaries should not exceed $1.0 \mathrm{H} 1 / \mathrm{H} 3$ at the receiving end. A $\overline{\text { CSTRB }}$ low beyond the synchronization period on a word boundary can be recognized as a new valid $\overline{C S T R B}$, resulting in an extra byte reception (byte slippage). For a short distance between two communicating 'C4x devices, byte slippage is not a problem. In 'C40 device revisions 3.0 or higher, or in any revision of the 'C44, no $\overline{\mathrm{CSTRB}}$ width restriction exists.

The circuit shown in Figure 8-7 can reduce the width of $\overline{\text { CSTRB }}$ for very long distances when you are using 'C4x device revisions lower than 3.0. The circuit has buffers for $\overline{\text { CSTRB }}$ and $\overline{\text { CRDY }}$ on the transmitting end and two S-R flipflops on the receiving end. On the receiving end, a low STRB incoming signal causes the Q signal of S-R flip-flop U1 to go low, forcing the $\overline{\text { CSTRB }}$ pin to go low. When $\overline{\mathrm{CRDY}}$ responds with a low signal, S-R flip-flop U2 drives the RDY signal low. Because RDY is also tied to the $\bar{S}$ input of U1, and $\bar{S}$ has precedence over $\bar{R}$ in an S-R flip-flop, Q in U1 goes high. Also, STRB is inverted and drives the $\overline{\mathrm{S}}$ input of U2. In this way, the width of the local $\overline{\mathrm{CSTRB}}$ is shortened, regardless of the channel length. When the STRB signal goes back high, the S-R flip-flop pair is ready to receive another $\overline{C S T R B}$.

Figure 8-7. $\overline{C S T R B}$ Shortener Circuit


### 8.10 Parallel Processing Through Communication Ports

The 'C4x communication ports are key to parallel processing design flexibility. Many processors can be linked together in a wide variety of network configurations. In this section, Figure 8-8 illustrates 'C4x parallel processing connectivity networks that are used to fulfill many signal processing system needs.

Figure 8-8. 'C4x Parallel Connectivity Networks


Pipelined Linear Array
For convolution and correlation and other pipelined operations in graphics and modem applications.


## Tree Structures

Supports broadcasting and data searches for speech and image recognition applications.


Bidirectional Ring
Clockwise and counterclockwise data flow. Group port for more I/O. Very effective for neural networks.

Figure 8-8. 'C4x Parallel Connectivity Networks (Continued)



6 nearest neighbors connection. Useful in numerical analysis and image processing.


Fully-Connected Network


4-D Hypercube
A more general-purpose structure.

According to memory interface, 'C4x parallel system architecture can be classified in three basic groups:
$\square$ Shared-Memory Architecture: shares global memory among processors.
$\square$ Distributed-Memory Architecture: each processor has its own private local memory. Interprocessor communication is via ' C 4 x communication ports.
$\square$ Shared- and Distributed-Memory Architecture: each processor has its own local memory but also shares a global memory with other processors.

Figure 8-8 shows examples of these basic groups.

### 8.11 Broadcasting Messages From One 'C4x to Many 'C4x Devices

Message broadcasting from one 'C4x to many 'C4x devices requires a simple interface. However, try to avoid signal analog delays caused by distance differences between the 'C4x master and the 'C4x slave processor. These delays could create bus contention in the $\overline{\text { CSTRB }}$ and $\overline{\text { CRDY }}$ lines. Figure $8-9$ shows the block diagram of a multiple processor system. In this design, one 'C4x is the dedicated transmitter, and three 'C4x devices are dedicated receivers. No reset circuitry is needed, because the transmitter is communication port 0, and the receivers are communication ports 3, 4, and 5 . At reset, ' $\mathrm{C} 4 x$ communication ports 0,1 , and 2 are output ports, and communication ports 3,4 , and 5 , are input ports.

Because the communications configuration is fixed, no token transfer is needed; this allows the $\overline{\mathrm{CREQ}}$ and $\overline{\mathrm{CACK}}$ pins of all processors to be individually pulled up to 5 volts through $22-\mathrm{k} \Omega$ resistors.

In all cases, each $\overline{\mathrm{CSTRB}}$ should be individually buffered to ensure that line reflections do not corrupt each received $\overline{\text { CSTRB }}$ signal. The data pins CD7-0 of intercommunicating 'C4x devices can be tied together. In general, for fewer than three receivers and distances shorter than six inches, data skew relative to $\overline{\text { CSTRB }}$ is not a problem, and data buffering is not needed. However, if more than three receivers must be driven by a single transmitter or the distance is more than six inches, both the $\overline{\text { CSTRB }}$ and CD7-0 lines must be buffered.

The $\overline{\text { CRDY }}$ signal input is generated by ORing the $\overline{\operatorname{RDY}}$ outputs of all of the receiver communication ports. The transmitter should not receive a $\overline{R D Y}$ signal until the receiver has received all data.

In addition, to ensure that the dedicated receiver 'C4x devices do not try to arbitrate for the communication-port bus, you should halt the output ports of the receiver 'C4x devices by setting bit four of their communication-port control registers to one.

Figure 8-9. Message Broadcasting by One 'C4x to Many 'C4x Devices


## 'C4x Power Dissipation

The power-supply current requirement (IDD) of the 'C4x vary with the specific application and the device program activity. The maximum power dissipation of a device can be calculated by multiplying $l_{D D}$ with $V_{D D}$ (power supply voltage requirement). Both parameters are provided in the 'C4x data sheet. Additionally, due to the inherent characteristics of CMOS technology, the current requirements depend on clock rates, output loadings, and data patterns.

This chapter presents the information you need to determine power-supply current requirements for the 'C4x under various operating conditions. After you make this determination, you can then calculate the device power dissipation, and, in turn, thermal management requirements.

## Topic

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### 9.1 Capacitive and Resistive Loading

In CMOS devices, the internal gates swing completely from one supply rail to the other. The voltage change on the gate capacitance requires a charge transfer, and therefore causes power consumption.

The required charge for a gate's capacitance is calculated by the following equation:
$Q_{\text {gate }}=V_{D D} \times C_{\text {gate }}$ (coulombs)
where:
$Q_{g a t e}$ is the gate's charge,
$V_{D D}$ is the supply voltage, and
$C_{\text {gate }}$ is the gate's capacitance.
Since current is coulombs per second, the current can then be obtained from:
$I=\operatorname{coul} / s=V_{D D} \times C_{\text {gate }} \times$ Frequency
where:
I is the current.
For example, the current consumed by an $80-\mathrm{pF}$ capacitor being driven by a $10-\mathrm{MHz}$ CMOS level square wave is calculated as follows:

$$
\begin{aligned}
I & \left.=5(\text { volts }) \times 80 \times 10^{-12} \text { (farads) } \times 10 \times 10^{6} \text { (charges } / \mathrm{s}\right) \\
& =4 \mathrm{~mA} @ 10 \mathrm{MHz}
\end{aligned}
$$

Furthermore, if the total number of gates in a device is known, the effective total capacitance can be used to calculate the current for any voltage and frequency. For a given CMOS device, the total number of gates is probably not known, but you can solve for a current at a particular frequency and supply voltage and later use this current to calculate for any supply voltage and operating frequency.
$I_{\text {device }}=V_{D D} \times C_{\text {total }} \times f_{C L K}$
where:
Idevice is the current consumed by the device,
$C_{\text {total }}$ is the total capacitance, and
$f_{C L K}$ is the clock cycle.

Solving for power ( $P=V \times I$ ), the equation becomes:
$P_{\text {device }}=V_{D D^{2}} \times C_{\text {total }} \times f_{C L K}$
where:
$P_{\text {device }}$ is the power consumed by the device.
In this case, $C_{\text {total }}$ includes both internal and external capacitances. $C_{\text {total }}$ can be effectively reduced by minimizing power-consuming internal operation and external bus cycles. Bipolar devices, pullup resistors and other devices consume DC power that adds a constant offset unaffected by $f_{C L K}$. The effect of these DC losses depends on data, not frequency. This document assumes an all-CMOS approach in which these effects are minimal.

Another source of power consumption is the current consumed by a CMOS gate when it is biased in the linear region. Typically, if a gate is allowed to float, it can consume current. Pullups and pulldowns of unused pins are therefore recommended.

### 9.2 Basic Current Consumption

Generally, power supply current requirements are related to the system-for example, operating frequency, supply voltage, temperature, and output load. In addition, because the current requirement for a CMOS device depends on the charging and discharging of node capacitance, factors such as clocking rate, output load capacitance, and data values can be important.

### 9.2.1 Current Components

The power supply current has four basic components:

- Quiescent
- Internal operations
- Internal bus operations
- External bus operations


### 9.2.2 Current Dependency

The power supply current consumption depends on many factors. Four are system related:

- Operation frequency

Supply voltage

- Operating temperature
- Output load

Several others are related to TMS320C4x operation:

- Duty cycle of operations
- Number of buses used
- Wait states
- Cache usage
- Data value

You can calculate the total power supply current requirement for a 'C4x device by using the equation below, which comprises the four basic power supply current components and three system-related dependencies described above.
$I_{\text {total }}=\left(I_{q}+l_{\text {iops }}+l_{\text {ibus }}+l_{\text {xbus }}\right) \times F \times V \times T$
where:
Iotal is the total supply current,
$I_{q}$ is the quiescent current component,
$l_{\text {lops }}$ is the current component due to internal operations,
$l_{\text {ibus }}$ is the current component due to internal bus usage, including data value and cycle time dependency,
$I_{\text {xbus }}$ is the current component due to external bus usage, including data value wait state, cycle time, and capacitive load dependency,
$F$ is a scale factor for frequency,
$V$ is a scale factor for supply voltage, and
$T$ is a scale factor for operating temperature.
This report describes in detail the application of this equation and determination of all the dependencies. The power dissipation measurements in this report were taken using a 'C40 PG 3.X running at speeds up to 50 MHz and at a voltage level of 5 V .

The minimum power supply current requirement is 130 mA . The typical current consumption for most algorithms is 350 mA , as described in the TMS320C4x data sheet, unless excessive data output is being performed.

The maximum current requirement for a ' C 4 x running at 50 MHz is 850 mA and occurs only under worst case conditions: writing alternating data (AAAA AAAA to 5555 5555) out of both external buses simultaneously, every cycle, with 80 pF loads.

### 9.2.3 Algorithm Partitioning

Each part of an algorithm has its own pattern with respect to internal and external bus usage. To analyze the power supply current requirement, you must partition an algorithm into segments with distinct concentrations of internal or external bus usage. Analyze each program segment to determine its powersupply current requirement. You can then calculate the average power supply current requirement from the requirements of each segment of the algorithm.

### 9.2.4 Test Setup Description

All TMS320C4x supply current measurements were performed on the test setup shown in Figure 9-1. The test setup consists of a TMS320C40, capacitive loads on all data and address lines, but no resistive loads. A Tektronix digital multimeter measures the power supply current. Unless otherwise specified, all measurements are made at a supply voltage of 5 V , an input clock frequency of 50 MHz , a capacitive load of 80 pF , and an operating temperature of $25^{\circ} \mathrm{C}$. Note that the current consumed by the oscillator and pullup resistors does not flow through the current meter. This current is considered part of the system's resistive loss (see section 9.1, Capacitive and Resistive Loading).

Figure 9-1. Test Setup


### 9.3 Current Requirement of Internal Components

The power-supply current requirement for internal circuitry consists of three components: quiescent, internal operations, and internal bus operations. Quiescent and internal operations are constants, whereas the internal bus operations component varies with the rate of internal bus usage and the data values being transferred.

### 9.3.1 Quiescent

The quiescent requirement for the TMS320C4x is 130 mA while in IDLE. Quiescent refers to the baseline supply current drawn by the TMS320C4x during minimal internal activity. Examples of quiescent current include:

- Maintaining timer and oscillator
- Executing the IDLE instruction
- Holding the TMS320C4x in reset


### 9.3.2 Internal Operations

Internal operations include register-to-register multiplication, ALU operations, and branches, but not external bus usage or significant internal bus usage. Internal operations add a constant 60 mA above the quiescent requirement, so that the total contribution of quiescent and internal operation is 190 mA . Note, however, that internal and/or external program operations executed via an RPTS instruction do not contribute an internal operations power supply current component. During an RPTS instruction, program fetch activity other than the instruction being repeated is suspended; therefore, power-supply current is related only to the data operations performed by the instruction being executed.

Figure 9-2. Internal and Quiescent Current Components


### 9.3.3 Internal Bus Operations

The internal bus operations include all operations that utilize the internal buses extensively, such as internal RAM accesses every cycle. No distinction is made between internal reads or writes, such as instruction or operand fetches from internal memory, because internally they are equal. Significant use of internal buses adds a data-dependent term to the equation for the power supply current requirement. Recall that switching requires more current. Hence, changing data at high rates requires higher power-supply current.

Pipeline conflicts, use of cache, fetches from external wait-state memory, and writes to external wait-state memory all affect the internal and external bus cycles of an algorithm executing on the TMS320C4x. Therefore, you must determine the algorithm's internal bus usage in order to accurately calculate power supply current requirements. The TMS320C4x software simulator and XDS emulator both provide benchmarking and timing capabilities that help you determine bus usage.

Figure 9-3. Internal Bus Current Versus Transfer Rate


The current resulting from internal bus usage varies linearly with transfer rates. Figure 9-3 shows internal bus-current requirements for transferring alternating data (AAAA AAAAh to 55555555 h ) at several frequencies. Note that transfer rates greater than the TMS320C4x's MIPS rating are possible because of internal parallelism.

The data set AAAA AAAAh to 55555555 h exhibits the maximum internal bus current for data transfer operations. The current required for transferring other data patterns may be derated accordingly, as described later in this subsection.

As the transfer rate decreases (that is, transfer-cycle time increases) the incremental $I_{D D}$ approaches 0 mA . This figure represents the incremental $I_{D D}$ due to internal bus operations and is added to quiescent and internal operations current values.

For example, the maximum transfer rate corresponds to three accesses every cycle (one program fetch and two data transfers) or an effective one-third H1 transfer cycle time. At this rate, 178 mA is added to the quiescent ( 130 mA ) and internal operation ( 60 mA ) current values for a total of 368 mA .

Figure 9-3 shows the internal bus current requirement when transferring As followed by 5 s for various transfer rates. Figure 9-4 shows the data dependence of the internal bus-current requirement when the data is other than As followed by 5 s . The trapezoidal region bounds all possible data values transferred. The lower line represents the scale factor for transferring the same data. The upper line represents the scale factor for transferring alternating data (all 0 s to all Fs or all As to all 5 s , etc.).

The possible permutation of data values is quite large. The term relative data complexity refers to a relative measure of the extent to which data values are changing and the extent to which the number of bits are changing state. Therefore, relative data complexity ranges from 0 , signifying minimal variation of data, to a normalized value of 1 , signifying greatest data variation.

Figure 9-4. Internal Bus Current Versus Data Complexity Derating Curve


If a statistical knowledge of the data exists, Figure 9-4 can be used to determine the exact power supply requirement on the basis of internal bus usage. For example, Figure 9-4 indicates a $89.5 \%$ scale factor when all Fs (FFFF FFFFh) are moved internally every cycle with two accesses per cycle ( 80 Mbytes per second). Multiplying this scale factor by 178 mA (from

Figure 9-3) yields 159 mA due to internal bus usage. Therefore, an algorithm running under these conditions requires about 349 mA of power supply current ( $130+60+159$ ).

Since a statistical knowledge of the data may not be readily available, a nominal scale factor may be used. The median between the minimum and maximum values at $50 \%$ relative data complexity yields a value of 0.93 and can be used as an estimate of a nominal scale factor. Therefore, this nominal data scale factor of $93 \%$ can be used for internal bus data dependency, adding 165.5 mA to 130 mA (quiescent) and 60 mA (internal operations) to yield 355.5 mA . As an upper bound, assume worst case conditions of three accesses of alternating data every cycle, adding 178 mA to 130 mA (quiescent) and 60 mA (internal operations) to yield 368 mA .

### 9.4 Current Requirement of Output Driver Components

The output driver circuits on the TMS320C4x are required to drive significantly higher DC and capacitive loads than internal device logic drivers. Because of this, output drivers impose higher supply current requirements than other sections of circuitry in the device.

Accordingly, the highest values of supply current are exhibited when external writes are being performed at high speed. During read cycles, or when the external buses are not being used, the TMS320C4x is not driving the data bus; this eliminates a significant component of the output buffer current. Furthermore, in many typical cases, only a few address lines are changing, or the whole address bus is static. Under these conditions, an insignificant amount of supply current is consumed. Therefore, when no external writes are being performed or when writes are performed infrequently, current due to output buffer circuitry can be ignored.

When external writes are being performed, the current required to supply the output buffers depends on several considerations:

- Data pattern being transferred
- Rate at which transfers are being made
- Number of wait states implemented (because wait states affect rates at which bus signals switch)
- External bus DC and capacitive loading

External bus operations involve external writes to the device and constitute a major power-supply current component. The power supply current for the external buses, made up of four components, is summarized in the following equation:
$I_{\text {xbus }}=\left(I_{\text {base }}\right.$ local $\left.+I_{\text {local }}\right)+\left(I_{\text {base }}\right.$ global $\left.+I_{\text {global }}\right)$
where:
Ibase local/global is the current consumed by the internal driver and pin capacitance,

I/ocal is the local bus current component, and
Iglobal is the global bus current component.
The remainder of this section describes in detail the calculation of external bus current requirements.

## Note:

The DMA current component (IDMA) and communication port current component ( $I_{C P}$ ) should be included in the calculation of $I_{x b u s}$ if they are used in the operations.

### 9.4.1 Local or Global Bus

The current due to bus writes varies with write cycle time. As discussed in the previous section, to obtain accurate current values, you must first determine the rate and timing for write cycles to external buses by analyzing program activity, including any pipeline conflicts that may exist. To do this, you can use information from the TMS320C4x emulator or simulator as well as the TMS320C4x User's Guide. In your analysis, you must account for effects from the use of cache, because use of cache can affect whether or not instructions are fetched from external memory.

When evaluating external write activity in a given program segment, you must consider whether or not a particular level of external write activity constitutes significant activity. If writes are being performed at a slow enough rate, they do not impact supply current requirements significantly and can be ignored. This is the case, however, only if writes are being performed at very slow rates on either the local or global bus.

When bus-write cycle timing has been established, Figure 9-5 can be used to determine the contribution to supply current due to bus activity. Figure 9-5 shows values of current contribution from the local or global bus for various transfer rates. This data was gathered when alternating values of 555555555 h and AAAAAAAAh were written at a capacitive load of 80 pF per output signal line. This condition exhibits the highest current values on the device. The values presented in the figure represent the incremental current contributed by the local or global bus output driver circuitry under the given conditions. Current values obtained from this graph are later scaled and added to several other current terms to calculate the total current for the device. As indicated in the figure, the lower limit $l_{\text {base }}=I_{q}+l_{\text {iops }}+l_{\text {ibus }}$ is essentially $l_{\text {total }}$ for transfer rates less than 1 Mword/second.

Figure 9-5. Local/Global Bus Current Versus Transfer Rate and Wait States


Figure 9-5 demonstrates a feature of the 'C4x's external bus architecture known as a posted write. In general, data is written to a latch (or a one deep FIFO) and held by the bus until the bus cycle is complete. Since the CPU may not require that bus again for some time, the CPU is free to perform operations on other buses until a conflict occurs. Conflicts include DMA, a second write, or a read to the bus.

In Figure 9-5, the upper line is applicable when STI || STI is not dominated by execution of internal NOPs and the external wait state is equal to zero. The lower line shows when STI || STI is internally stalled while waiting for the external bus to go ready because of wait states. The addition of NOPs between successive STI || STI operations contributes to internal bus current and therefore does not result in the lowest possible current.

Figure 9-6. Local/Global Bus Current Versus Transfer Rate at Zero Wait States


To further illustrate the relationship of current and write cycle time, Figure 9-6 shows the characteristics of current for various numbers of cycles between writes for zero wait states. The information on this graph can be used to obtain more precise values of current whenever zero wait states are used. Table 9-1 lists the number of cycles used for software generated wait states.

Table 9-1. Wait State Timing Table

| Wait State | Read Cycles | Write Cycles |
| :---: | :---: | :---: |
| 0 | 1 | 2 |
| 1 | 2 | 3 |
| 2 | 3 | 4 |
| 3 | 4 | 5 |

Once a current value has been obtained from Figure 9-5 or Figure 9-6, this value can be scaled by a data dependency factor if necessary, as described on page 9-16. This scaled value is then summed along with several other current terms to determine the total supply current.

### 9.4.2 DMA

Using DMA to transfer data consumes power that is data dependent. The current resulting from DMA bus usage (IDMA) varies linearly with the transfer rate. Figure 9-7 shows DMA bus current requirements for transferring alternating data (AAAA AAAAh to 55555555 h ) at several transfer rates; it also shows that current consumption increases when more DMA channels are used. However, as more DMA channels are used, the incremental change in current diminishes as the internal DMA bus becomes saturated. Note that DMA current is superimposed over $l_{i b u s}$ (internal bus) value.

Figure 9-7. DMA Bus Current Versus Clock Rate


### 9.4.3 Communication Port

Communication port operations add a data-dependent term to the equation for the current requirement. The current resulting from communication port operation (ICP) varies linearly with the transfer rate. Figure 9-8 shows communication port operation current requirements for transferring alternating data (AAAA AAAAh to 55555555 h ) at several transfer rates; it also shows that current consumption increases when more communication port channels are
used. Similar to the DMA bus current consumption, adding communication ports eventually saturates the peripheral bus as more channels are added.

Figure 9-8. Communication Port Current Versus Clock Rate


Note that since the communication ports are intended to communicate with other TMS320C4x communication ports over short distances, no additional capacitive loading was added. In this case, the transmission distance is about 6 inches without additional $80-\mathrm{pF}$ loads. Note that communication port current is superimposed over libus value.

### 9.4.4 Data Dependency

Data dependency of the current for the local and global buses is expressed as a scale factor that is a percentage of the maximum current exhibited by either of the two buses.

Figure 9-9. Local/Global Bus Current Versus Data Complexity


Figure 9-9 shows normalized weighting factors that can be used to scale current requirements on the basis of patterns in data being written on the external buses. The range of possible weighting factors forms a trapezoidal pattern bounded by extremes of data values. As the figure shows, the minimum current occurs when all zeros are written, while the maximum current occurs when alternating 55555555 h and AAAA AAAAh are written. This condition results in a weighting factor of 1 , which corresponds to using the values from Figure 9-5 and/or Figure 9-6 directly.

As with internal bus operations, data dependencies for the external buses are well defined, but accurate prediction of data patterns is often either impossible or impractical. Therefore, unless you have precise knowledge of data patterns, you should use an estimate of a median or average value for the scale factor. Assuming that data will be neither 5 s and As nor all 0 s and will be varying randomly, then a value of 0.80 is appropriate. Otherwise, if you prefer a conservative approach, you can use a value of 1.0 as an upper bound.

Regardless of the approach taken for scaling, once you determine the scale factor for the buses, apply this factor to the current values you determined with the graphs in section 9.4.1, Local or Global Bus.

For example, if a nominal scale factor of 0.80 for the buses is assumed, the current contribution from the two buses is as follows:

Local or Global : $0.80 \times 133 \mathrm{~mA}=106.4 \mathrm{~mA}$

### 9.4.5 Capacitive Loading Dependence

Once cycle timing and data dependencies have been accounted for, capacitive loading effects should be calculated and applied. Figure $9-10$ shows the current values obtained above as a function of actual load capacitance if the load capacitance presented to the buses is less than 80 pF .

In the previous example, if the load capacitance is 20 pF instead of 80 pF , the actual pin current would be 1.66 mA .

While the slope of the line in Figure $9-10$ can be used to interpolate scale factors for loads greater than 80 pF , the TMS320C4x is specified to drive output loads less than 80 pF ; interface timings cannot be guaranteed at higher loads. With data dependency and capacitive load scale factors applied to the current values for local and global buses, the total supply current required for the device for a particular application can be calculated, as described in the next section.

Figure 9-10. Pin Current Versus Output Load Capacitance (10 MHz)


### 9.5 Calculation of Total Supply Current

The previous sections have discussed currents contributed by different sources on the TMS320C4x. Because determinations of actual current values are unique and independent for each source, each current source was discussed separately. In an actual application, however, the sum of the independent contributions determines the total current requirement for the device. This total current value is exhibited as the total current supplied to the device through all of the $\mathrm{V}_{\mathrm{DD}}$ inputs and returned through the $\mathrm{V}_{\mathrm{SS}}$ connections.

Note that numerous $\mathrm{V}_{\mathrm{DD}}$ and $\mathrm{V}_{\mathrm{SS}}$ pins on the device are routed to a variety of internal connections, not all of which are common. Externally, however, all of these pins should be connected in parallel to 5 V and ground planes, providing very low impedance.

As mentioned previously, because of the inherent differences in operations between program segments, it is usually appropriate to consider current for each of the segments independently. In this way, peak current requirements are readily obtained. Further, you can make average current calculations to use in determining heating effects of power dissipation. These effects, in turn, can be used to determine thermal management considerations.

### 9.5.1 Combining Supply Current Due to All Components

To determine the total supply current requirements for any given program activity, calculate each of the appropriate components and combine them in the following sequence:

1) Start with 130 mA quiescent current requirement.
2) Add 60 mA for internal operations unless the device is dormant, such as when executing IDLE or using an RPTS instruction to perform internal and/or external bus operations (see Internal Operations section on page 9-7). Internal or external bus operations executed via RPTS do not contribute an internal operations power supply current component. Therefore, current components in the next two steps may still be required, even though the 60 mA is omitted.
3) If significant internal bus operations are being performed (see subsection 9.3.2, Internal Bus Operations on page 9-8), add the calculated current value.
4) If external writes are being performed at high speed (see Section 9.4, Current Requirements of Output Driver Components on page 9-12), then add the values calculated for local and global bus current components.
5) Add DMA and communication port current requirements if they are used.

The current value resulting from summing these components is the total device current requirement for a given program activity.

### 9.5.2 Supply Voltage, Operating Frequency, and Temperature Dependencies

Three additional factors that affect current requirements are supply voltage level, operating temperature, and operating frequency. However, these considerations affect total supply current, not specific components (that is, internal or external bus operations). Note that supply voltages, operating temperature, and operating frequency must be maintained within required device specifications.

The scale factor for these dependencies is applied in the same manner as discussed in previous sections, once the total current for a particular program segment has been determined. Figure $9-11$ shows the relative scale factors to be applied to the supply current values as a function of both $\mathrm{V}_{\mathrm{DD}}$ and operating frequency.

Figure 9-11. Current Versus Frequency and Supply Voltage


Power-supply current consumption does not vary significantly with operating temperature. However, you can use a scale factor of $2 \%$ normalized IDD per $50^{\circ} \mathrm{C}$ change in operating temperature to derate current within the specified range noted in the TMS320C4x data sheet.

Figure 9-12. Change in Operating Temperature $\left({ }^{\circ} \mathrm{C}\right)$


This temperature dependence is shown graphically in Figure 9-12. Note that a temperature scale factor of 1.0 corresponds to current values at $25^{\circ} \mathrm{C}$, which is the temperature at which all other references in the document are made.

### 9.5.3 Design Equation

The procedure for determining the power-supply current requirement can be summarized in the following equation:
$I_{\text {total }}=\left(I_{\text {qidle }}+I_{\text {iops }}+I_{\text {ibus }}+I_{\text {xbusglobal }}+I_{\text {xbuslocal }}+I_{\text {DMA }}+I_{\text {cp }}\right) \times F \times V \times T$ where:
$F$ is a scale factor for frequency
$V$ is a scale factor for supply voltage
$T$ is a scale factor for operating temperature
Table 9-2 describes the symbols used in the power-supply current equation and gives the value and the number from which the value is obtained.

Table 9-2. Current Equation Typical Values ( $F_{C L K}=40 \mathrm{MHz}$ )

| Symbol | Value |  |  | Note | Reference |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  | Min | Typical | Max |  |  |
| $\mathrm{I}_{\text {qidle2 }}$ | - | $20 \mu \mathrm{~A}$ | $50 \mu \mathrm{~A}$ | Idle2 shutdown | Figure 9-2 |
| ${ }^{\text {qidle }}$ | 130 mA | 130 mA | 130 mA | Internal idle | Figure 9-2 |
| $\mathrm{l}_{\text {iops }}$ | 60 mA | 60 mA | 60 mA | Branch to self internal | Figure 9-2 |
| $\mathrm{l}_{\text {ibus }}$ | 0 mA | 50 mA | 190 mA | Data dependent | Figure 9-3, Figure 9-4 |
| Ixbusglobal (max) | 0 mA | 50 mA | 280 mA | Data and $\mathrm{C}_{\text {load }}$ dependent | Figure 9-5, Figure 9-6, Figure 9-9 |
| $I_{\text {xbuslocal }}(\mathrm{max})$ | 0 mA | 50 mA | 280 mA | Data and $\mathrm{C}_{\text {load }}$ dependent | Figure 9-5, Figure 9-6, Figure 9-9 |
| ${ }^{\text {DMA }}$ | 0 mA | 50 mA | 300 mA | Data and source/ destination dependent | Figure 9-7 |
| $\mathrm{I}_{\mathrm{CP}}$ | 0 mA | 50 mA | 250 mA | Data dependent | Figure 9-8 |

Notes: 1) All values are scaled by frequency and supply voltage. The nominal tested frequency is 40 MHz .
2) Externally-driven signals are capacitive-load dependent.
3) It is unrealistic to add all of the maximum values, since it is impossible to run at those levels.

### 9.5.4 Average Current

Over the course of an entire program, some segments typically exhibit significantly different levels of current for different durations. For example, a program may spend $80 \%$ of its time performing internal operations and draw a current of 250 mA ; it may spend the remaining $20 \%$ of its time performing writes at full speed to both buses and drawing 790 mA .
While knowledge of peak current levels is important in order to establish power supply requirements, some applications require information about average current. This is particularly significant if periods o
f high peak current are short in duration. You can obtain average current by performing a weighted sum of the current due to the various independent program segments over time. You can calculate the average current for the example in the previous paragraph as follows:
$\mathrm{I}=0.8 \times 250 \mathrm{~mA}+0.2 \times 790 \mathrm{~mA}=358 \mathrm{~mA}$
Using this approach, you can calculate average current for any number of program segments.

### 9.5.5 Thermal Management Considerations

Heating characteristics of the TMS320C4x are dependent upon power dissipation, which, in turn, is dependent upon power supply current. When mak-
ing thermal management calculations, you must consider the manner in which power supply current contributes to power dissipation and to the TMS320C4x package thermal characteristics' time constant.

Depending on the sources and destinations of current on the device, some current contributions to $I_{D D}$ do not constitute a component of power dissipation at 5 volts. That is to say, the TMS320C4x may be acting only as a switch, in which case, the voltage drop is across a load and not across the 'C4x. If the total current flowing into $V_{D D}$ is used to calculate power dissipation at 5 volts, erroneously large values for package power dissipation will be obtained. The error occurs because the current resulting from driving a logic high level into a DC load appears only as a portion of the current used to calculate system power dissipation due to $V_{D D}$ at 5 volts. Power dissipation is defined as:
$\mathrm{P}=\mathrm{V} \times \mathrm{I}$
where $P$ is power, $V$ is voltage, and $/$ is current. If device outputs are driving any DC load to a logic high level, only a minor contribution is made to power dissipation because CMOS outputs typically drive to a level within a few tenths of a volt of the power supply rails. If this is the case, subtract these current components out of the TMS320C4x supply current value and calculate their contribution to system power dissipation separately (see Figure 9-13).

Figure 9-13. Load Currents


Furthermore, external loads draw supply current (IDD) only when outputs are driven high, because when outputs are in the logic zero state, the device is sinking current through $V_{S S}$, which is supplied from an external source. Therefore, the power dissipation due to this component will not contribute through $I_{D}$ but will contribute to power dissipation with a magnitude of:
$\mathrm{P}=\mathrm{V}_{\mathrm{OL}} \times{ }_{\mathrm{OL}}$
where $V_{O L}$ is the low-level output voltage and $I_{O L}$ is the current being sunk by the output, as shown in Figure 9-13. The power dissipation component due to outputs being driven low should be calculated and added to the total power dissipation.

When outputs with DC loads are being switched, the power dissipation components from outputs being driven high and outputs being driven low should be averaged and added to the total device power dissipation. Power components due to DC loading of the outputs should be calculated separately for each program segment before average power is calculated.

Note that unused inputs that are left unconnected may float to a voltage level that will cause the input buffer circuits to remain in the linear region, and therefore contribute a significant component to power supply current. Accordingly, if you want absolute minimum power dissipation, you should make any unused inputs inactive by either grounding or pulling them high. If several unused inputs must be pulled high, they can be pulled high together through one resistor to minimize component count and board space.

When you use power dissipation values to determine thermal management considerations, use the average power unless the time duration of individual program segments is long. The thermal characteristics of the TMS320C40 in the 325 -pin PGA package are exponential in nature with a time constant on the order of minutes. Therefore, when subjected to a change in power, the temperature of the device package will require several minutes or more to reach thermal equilibrium.

If the duration of program segments exhibiting high power dissipation values is short (on the order of a few seconds) in comparison to the package thermal characteristics' time constant, use average power calculated in the same manner as average current described in the previous section. Otherwise, calculate maximum device temperature on the basis of the actual time required for the program segments involved. For example, if a particular program segment lasts for 7 minutes, the device essentially reaches thermal equilibrium due to the total power dissipation during the period of device activity.

Note that the average power should be determined by calculating the power for each program segment (including all considerations described above) and performing a time average of these values, rather than simply multiplying the average current by $V_{D D}$, as determined in the previous subsection.

Calculate specific device temperature by using the TMS320C4x thermal impedance characteristics included in the TMS320C4x data sheet.

### 9.6 Example Supply Current Calculations

An FFT represents a typical DSP algorithm. The FFT code used in this calculation processes data in the RAM blocks. The entire algorithm consists mainly of internal bus operations and hence includes quiescent and, in general, internal operations. At the end of the processing, the results are written out on the global and local bus. Therefore, the algorithm exhibits a higher current requirement during the write portion where the external bus is being used significantly.

### 9.6.1 Processing

The processing portion of the algorithm is $95 \%$ of the total algorithm. During this portion, the power-supply current is required for the internal circuitry only. Data is processed in several loops that make up the majority of the algorithm. During these loops, two operands are transferred on every cycle. The current required for internal bus usage, then, is 60 mA (from Figure 9-3). The data is assumed to be random. A data value scale factor of 0.93 is used (from Figure 9-4). This value scales 60 mA , yielding 55.8 mA for internal bus operations. Adding 55.8 mA to the quiescent current requirement and internal operations current requirement yields a current requirement of 245.8 mA for the major portion of the algorithm.

$$
\begin{aligned}
I & =I_{q}+I_{\text {iops }}+I_{\text {ibus }} \\
I & =130 \mathrm{~mA}+60 \mathrm{~mA}+(60 \mathrm{~mA})(0.93) \\
& =245.8 \mathrm{~mA}
\end{aligned}
$$

### 9.6.2 Data Output

The portion of the algorithm corresponding to writing out data is approximately $5 \%$ of the total algorithm. Again, the data that is being written is assumed to be random. From Figure 9-4 and Figure 9-10, scale factors of 0.93 and 0.8 are used for derating due to data value dependency for internal and local buses, respectively. During the data dump portion of the code, a load and a store are performed every cycle; however, the parallel load/store instruction is in an RPTS loop. Therefore, there is no contribution due to internal operations, because the instruction is fetched only once. The only internal contributions are due to quiescent and internal bus operations. Figure 9-5 indicates a $23-m A$ current contribution due to writes every available cycle. Therefore, the total contribution due to this portion of the code is:
$I=I_{q}+I_{\text {ibus }}+I_{\text {xbus }}$
or
$\mathrm{I}=130 \mathrm{~mA}+(60 \mathrm{~mA})(0.93)+85 \mathrm{~mA}+(23 \mathrm{~mA})(0.8)$ $=289.2 \mathrm{~mA}$

### 9.6.3 Average Current

The average current is derived from the two portions of the algorithm. The processing portion took $95 \%$ of the time and required about 245.8 mA ; the data dump portion took the other $5 \%$ and required about 411.6 mA . The average is calculated as:

$$
\begin{aligned}
\mathrm{I}_{\mathrm{avg}} & =(0.95)(245.8 \mathrm{~mA})+(0.05)(289.2 \mathrm{~mA}) \\
& =247.97 \mathrm{~mA}
\end{aligned}
$$

From the thermal characteristics specified in the TMS320C4x User's Guide, it can be shown that this current level corresponds to a case temperature of $28^{\circ} \mathrm{C}$. This temperature meets the maximum device specification of $85^{\circ} \mathrm{C}$ and hence requires no forced air cooling.

### 9.6.4 Experimental Results

A photograph of the power-supply current for the FFT, using a $40-\mathrm{MHz}$ system clock, is shown in Appendix A. During the FFT processing, the current varied between 190 and 220 mA . The current during external writes had a peak of 230 mA , and the average current requirement as measured on a digital multimeter was 205 mA . Scaling those results to the $50-\mathrm{MHz}$ calculations yielded results that were close to the actual measured power-supply current.

### 9.7 Design Considerations

Designing systems for minimum power dissipation involves reducing device operating current requirements due to signal switching rate, capacitive loading, and other effects. Selective consideration of these effects makes it possible to optimize system performance while minimizing power consumption. This section describes current reduction techniques based on operating current dependencies of the device as discussed in previous sections of this document.

### 9.7.1 System Clock and Signal Switching Rates

Since current (and therefore, power) requirements of CMOS devices are directly proportional to switching frequency, one potential approach to minimizing operating power is to minimize system clock frequency and signal switching rates. Although performance is often directly proportional to system clock and signal switching rates, tradeoffs can be made in both areas to achieve an optimal balance between power usage and performance in the design of a system.

If reducing power is a primary goal, and a given system design does not have particularly demanding performance requirements, the system clock rate can be reduced with the corresponding savings in power. Minimum power is realized when system clock rates are only as fast as necessary to achieve required system performance. Additionally, if overall system clock rates cannot be reduced, an alternative approach to power reduction is to reduce clock speed wherever possible during periods of inactivity.

Also, the appropriate choice of clock generation approach will ensure minimum system power dissipation. The use of an external oscillator rather than the on-chip oscillator can result in lower power device and system power dissipation levels. As described previously, the internal oscillator can require as much as 10 mA when operating at 40 MHz . If you use an external oscillator that requires less than 10 mA for clock generation, overall system power is reduced.

When considering switching rates of signals other than the system clock, the main consideration is to minimize switching. Specifically, any unnecessary switching should be avoided. Outputs or inputs that are unused should either be disabled, tied high, or grounded, whichever is appropriate. Additionally, outputs connected to external circuitry should drive other power dissipation elements only when absolutely necessary.

### 9.7.2 Capacitive Loading of Signals

Current requirements are also directly proportional to capacitive loading. Therefore, all capacitive loading should be minimized. This is especially significant for device outputs.

The approaches to minimize capacitive loading are consistent with efficient PC board layout and construction practices. Specifically, signal runs should be as short as possible, especially for signals with high switching rates. Also, signals should not run long distances across PC boards to edge connectors unless absolutely necessary.

Note that the buffering of device outputs that must drive high capacitive loads reduces supply current for the TMS320C40, but this current is translated to the buffering device. Whether or not this is a valid tradeoff must be determined at the system level. The two main considerations are: 1) whether the power required by the buffers is more or less than the power required from the 'C40 to drive the load in question, and 2) whether or not off-loading the power to the buffers has any implications with respect to system power-down modes. It may be desirable to use buffers to drive high capacitive loads, even though they may require more current than the TMS320C40, especially in cases where part of the system may be powered down but the TMS320C40 is still required to interface to other low capacitance loads.

### 9.7.3 DC Component of Signal Loading

In order to achieve lowest device current requirements, the internal and external DC load component of device input and output signal loading must also be minimized.

Any device inputs that are unused and left floating may cause excessively high DC current to be drawn by their input buffer circuitry. This occurs because if an input is left unconnected, the voltage on the input may float to a level that causes the input buffer to be biased at a point within its range of linear operation. This can cause the input buffer circuit to draw a significant DC current directly from $V_{D D}$ to ground. Therefore, any unused device inputs should be pulled up to $\mathrm{V}_{\mathrm{DD}}$ via a resistor pullup of nominally $20 \mathrm{k} \Omega$, or driven high with an unused gate. Input-only pins that are not used can be pulled up in parallel with other inputs of the same type with a single gate or resistor to minimize system component count. In this case, up to 15 or more standard device inputs can be pulled up with a single resistor.

Any device I/O pins that are unused should be selected as outputs. This avoids the requirement for pull-ups (to ensure that the I/O input stage is not biased in the linear region) and therefore eliminates an unnecessary current component.

For any device output, any DC load present is directly reflected in the system's power-supply current. Therefore, DC loading of outputs should be reduced to a minimum. If DC currents are being sourced from the address bus outputs, the address bus should be set to a level that minimizes the current through the external load. This can be accomplished by performing a dummy read from an external address.

For I/O pins that must be used in both the input and output modes, individual pullup resistors of nominally $20 \mathrm{k} \Omega$ should be used to ensure minimum power dissipation if these pins are not always driven to a valid logic state. This is particularly true of the data-bus pins. When the bus is not being driven explicitly, it is left floating, which can cause excessively high currents to be drawn on the input buffer section of all 64 bits of the bus. In this case, because all 64 data bus bits are normally used independently in most applications, each data-bus pin should be pulled up with a separate resistor for minimum power.

## Development Support and Part Order Information

This chapter provides development support information, socket descriptions, device part numbers, and support tool ordering information for the ' C 4 x .

Each 'C4x support product is described in the TMS320 Family Development Support Reference Guide (literature number SPRU011). In addition, more than 100 third-party developers offer products that support the TI TMS320 family. For more information, refer to the TMS320 Third-Party Reference Guide (literature number SPRU052).

For information on pricing and availability, contact the nearest TI Field Sales Office or authorized distributor. See the list at the back of this book.

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### 10.1 Development Support

Texas Instruments offers an extensive line of development tools for the TMS320C4x generation of DSPs, including tools to evaluate the performance of the processors, generate code, develop algorithm implementations, and fully integrate and debug software and hardware modules.

The following products support the development of 'C4x applications:

## Code Generation Tools

$\square$ The optimizing ANSI C compiler translates ANSI C language directly into highly optimized assembly code. You can then assemble and link this code with the TI assembler/ linker, which is shipped with the compiler. It supports both ' C 3 x and ' C 4 x assembly code. This product is currently available for PCs (DOS, DOS extended memory, OS/2), VAX/VMS and SPARC workstations. See the TMS320 Floating-Point DSP Optimizing C Compiler User's Guide (SPRU034) for detailed information about this tool.

- The assembler/linker converts source mnemonics to executable object code. It supports both ' C 3 x and ' C 4 x assembly code. This product is currently available for PCs (DOS, DOS extended memory, OS/2). The 'C3x/'C4x assembler for the VAX/VMS and SPARC workstations is only available as part of the optimizing 'C3x/'C4x compiler. See the TMS320 Floating-Point DSP Assembly Language Tools User's Guide (SPRU035) for detailed information about available assembly-language tools.
$\square$ The digital filter design package helps you design digital filters.


## System Integration and Debug Tools

- The simulator simulates (via software) the operation of the ' C 4 x and can be used in C and assembly software development. This product is currently available for PCs (DOS, Windows) and SPARC workstations. See the TMS320C4x C Source Debugger User's Guide (SPRU054) for detailed information about the debugger.
- The XDS510 emulator performs full-speed in-circuit emulation with the 'C4x, providing access to all registers as well as to internal and external memory of the device. It can be used in C and assembly software development and has the capability to debug multiple processors. This product is currently available for PCs (DOS, Windows, OS/2) and SPARC workstations. This product includes the emulator board (emulator box, power supply, and SCSI connector cables in the SPARC version), the 'C4x C Source Debugger and the JTAG cable.

Because 'C3x and 'C5x XDS510 emulators also come with the same emulator board (or box) as the 'C4x, you can buy the 'C4x C Source Debugger

Software as a separate product called 'C4x C Source Debugger Conversion Software. This enables you to debug 'C3x/'C4x applications with the same emulator board. The emulator cable that comes with the 'C3x XDS510 emulator cannot be used with the 'C4x. A JTAG emulation conversion cable (see Section 10.3) is needed instead. The emulator cable that comes with the 'C5x XDS510 emulator can also be used for the 'C4x without any restriction. See the TMS320C4x C Source Debugger User's Guide (SPRU054) for detailed information about the 'C4x emulator.
$\square$ The parallel processing development system (PPDS) is a stand-alone board with four ' $\mathrm{C} 4 x s$ directly connected to each other via their communication ports. Each 'C4x has 64K-words SRAM and 8K-byte EPROM as local memory, and they all share a 128K-word global SRAM. See the TMS320C4x Parallel Processing Development System Technical Reference (SPRU075) for detailed information about the PPDS.

The emulation porting kit (EPK) enables you to integrate emulation technology directly into your system without the need of an XDS510 board. This product is intended to be used by third parties and high-volume board manufacturers and requires a licensing agreement with Texas Instruments

### 10.1.1 Third-Party Support

The TMS320 family is supported by products and services from more than 100 independent third-party vendors and consultants. These support products take various forms (both as software and hardware), from cross-assemblers, simulators, and DSP utility packages to logic analyzers and emulators. The expertise of those involved in support services ranges from speech encoding and vector quantization to software/hardware design and system analysis.

See the TMS320 Third-Party Support Reference Guide (literature number SPRU052) for a more detailed description of services and products offered by third parties.

### 10.1.2 The DSP Hotline

For answers to TMS320 technical questions on device problems, development tools, documentation, upgrades, and new products, you can contact the DSP hotline via:
$\square$ Phone: (713)274-2320 Monday through Friday from 8:30 a.m. to 5:00 p.m. central time

- Fax: (713)274-2324. (US DSP Hotline), +33-1-3070-1032 (European DSP hotline)


## - Electronic Mail: 4389750@mcimail.com

To ask about third-party applications and algorithm development packages, contact the third party directly. Refer to the TMS320 Third-Party Support Reference Guide (SPRU052) for addresses and phone numbers.

Extensive DSP documentation is available; this includes data sheets, user's guides, and application reports. Contact the hotline for information on literature that you can request from the Literature Response Center, (800)477-8924.

The DSP hotline does not provide pricing information. Contact the nearest TI Field Sales Office for prices and availability of TMS320 devices and support tools.

### 10.1.3 The Bulletin Board Service (BBS)

The TMS320 DSP Bulletin Board Service (BBS) is a telephone-line computer service that provides information on TMS320 devices, specification updates for current or new devices and development tools, silicon and development tool revisions and enhancements, new DSP application software as it becomes available, and source code for programs from any TMS320 user's guide.

You can access the BBS via:

- Modem: (300-, 1200-, or 2400-bps) dial (713)274-2323. Set your modem to 8 data bits, 1 stop bit, no parity.

To find out more about the BBS, refer to the TMS320 Family Development Support Reference Guide (literature number SPRU011).

### 10.1.4 Internet Services

Texas Instruments offers two Internet-accessible services for DSP support: an ftp site, and a www site.

- World-wide web: Point your browser at http://www.ti.com to access Tl's web site. At the site, you can follow links to find product information, online literature, an online lab, and the 320 Hotline online.
$\square$ FTP: Use anonymous ftp to ti.com (Internet port address 192.94.94.1) to access copies of the files found on the BBS. The BBS files are located in the subdirectory called mirrors.


### 10.1.5 Technical Training Organization (TTO) TMS320 Workshops

'C4x DSP Design Workshop. This workshop is tailored for hardware and software design engineers and decision-makers who will be designing and utilizing the 'C4x generation of DSP devices. Hands-on exercises throughout the course give participants a rapid start in developing 'C4x design skills. Microprocessor/assembly language experience is required. Experience with digital design techniques and C language programming experience is desirable.

These topics are covered in the 'C4x workshop:

- 'C4x architecture/instruction set
- Use of the PC-based software simulator
- Use of the ' $\mathrm{C} 3 \mathrm{x} /{ }^{\prime} \mathrm{C} 4 \mathrm{x}$ assembler/linker
- C programming environment
- System architecture considerations
- Memory and I/O interfacing
] Development support
For registration information, pricing, or to enroll, call (800)336-5236, ext. 3904.


### 10.2 Sockets

Table 10-1 contains available sockets that accept the 325 -pin 'C40 pin grid array (PGA) and the 304-pin 'C44 Plastic Quad Flatpack (PQF). Table 10-2 lists the phone numbers of the manufacturers listed in Table 10-1.

Table 10-1. Sockets that Accept the 325-pin 'C40 and the 304-pin 'C44

| Manufacturer | Type | Part Number |
| :--- | :--- | :--- |
| Advanced Interconnections | C40-wire-wrap socket | 3919 |
| AMP | C40-tool-activated ZIF socket | AMP 382533-9 |
| AMP | Actuation tool for AMP382533-9 | AMP 854234-1 |
| AMP | C40-handle-activated ZIF socket | AMP 382320-9 |
| AMP | C40-PGA ZIF | AMP 55291-2 |
| Emulation Technology | C40-logic analyzer socket | BZ6-325-H6A35-TMS320C40Z |
| Emulation Technology | C40-wire-wrap socket | AB-325-H6A35Z-P13-M |
| Mark Eyelet | C40-wire-wrap socket | MP325-73311D16 |
| Yamaichi | TMS320C44 PDB Socket (304 pins) | ic201-3044-004 |

Table 10-2. Manufacturer Phone Numbers

| Manufacturer | Phone Number |
| :--- | :--- |
| AMP | $(717) 564-0100$ |
| Advanced Interconnections | $(401) 823-5200$ |
| Emulation Technology | $(408) 982-0660$ |
| Mark Eyelet | $(203) 756-8847$ |
| Yamaichi | $(408) 456-0797$ |

The remainder of this section describes two available sockets that accept the 'C4x pin grid array (PGA). Both sockets feature zero insertion force (ZIF):

- A tool-activated ZIF socket (TAZ)
- A handle-activated ZIF socket (HAZ)

The sockets described herein are manufactured by AMP Incorporated.

### 10.2.1 Tool-Activated ZIF PGA Socket (TAZ)

Figure 10-1. Tool-Activated ZIF Socket


## Description:

AMP part number:
Pin positions:
Soldertail length:

Actuator tool

382533-9
325
0.170 in. for PC boards 0.125 in. thick (other tail lengths available)

354234-1

## Features:

- Slightly larger than a PGA device
$\square$ Easy package loading because of large funnel entry
Z Zero insertion force
- Contact wiping action during insertion ensures clean contact points
- Spring-loaded cover ensures proper loading
- Can be used with robotic insertion and removal
- Horizontal vs. vertical socket forces prevent damage to the device


### 10.2.2 Handle-Activated ZIF PGA Socket (HAZ)

Figure 10-2. Handle-Activated ZIF Socket


Features:

- Can be used for test and burn-in
- Spring contacts are normally closed

Easy package loading because of large funnel entry

- Zero insertion force
- Contact wiping action during socket closing ensures clean contact points
- Maximum Operating temperature is $160^{\circ} \mathrm{C}$ (to allow burn-in capability)


### 10.3 Part Order Information

This section describes the part numbers of 'C4x devices, development support hardware, and software tools.

### 10.3.1 Nomenclature

To designate the stages in the product development cycle, Texas Instruments assigns prefixes to the part numbers of all TMS320 devices and support tools. Each TMS320 device has one of three prefixes: TMX, TMP, or TMS. Each support tool has one of two possible prefix designators: TMDX or TMDS. These prefixes represent evolutionary stages of product development from engineering prototypes (TMX/TMDX) through fully qualified production devices and tools (TMS/TMDS). This development flow is defined below.

## Device Development Evolutionary Flow:

TMX The part is an experimental device that is not necessarily representative of the final device's electrical specifications.
TMP The part is a device from a final silicon die that conforms to the device's electrical specifications but has not completed quality and reliability verification.
TMS The part is a fully qualified production device.

## Support Tool Development Evolutionary Flow:

TMDX The development-support product that has not yet completed Texas Instruments internal qualification testing.
TMDS The development-support product is a fully qualified development support product.
TMX and TMP devices and TMDX development support tools are shipped with the following disclaimer:
"Developmental product is intended for internal evaluation purposes."
TMS devices and TMDS development support tools have been fully characterized, and the quality and reliability of the device has been fully demonstrated. Texas Instruments standard warranty applies to these products.

## Note:

It is expected that prototype devices (TMX or TMP) have a greater failure rate than standard production devices. Texas Instruments recommends that these devices notbe used in any production system, because their expected end-use failure rate is still undefined. Only qualified production devices should be used.

TI device nomenclature also includes the device family name and a suffix. This suffix indicates the package type (for example, N, FN, or GB) and temperature range (for example, L). Figure 10-3 provides a legend for reading the complete device name for any TMS320 family member.

Figure 10-3. Device Nomenclature


### 10.3.2 Device and Development Support Tools

Table 10-3 lists ' C 4 x device part numbers. Table 10-4 lists the development support tools available for the 'C4x DSP, their part numbers, and the platform on which they run.

Table 10-3. Device Part Numbers

| Device Part Number | Voltage | Operating Frequency | Comm Ports | Package |
| :---: | :---: | :---: | :---: | :---: |
| TMS320C40GFL | 5 V | $50 \mathrm{MHz} / 40 \mathrm{~ns}$ | 6 | 325-pin ceramic PGA |
| TMS320C40GFL60 | 5 V | $60 \mathrm{MHz} / 33 \mathrm{~ns}$ | 6 | 325-pin ceramic PGA |
| TMS320C44PDB50 | 5 V | $50 \mathrm{MHz} / 40 \mathrm{~ns}$ | 4 | 304-pin PQFP |
| TMS320C44PDB60 | 5 V | $60 \mathrm{MHz} / 33 \mathrm{~ns}$ | 4 | 304-pin PQFP |
| SMJ320C40GFM40 | 5 V | $40 \mathrm{MHz} / 50 \mathrm{~ns}$ | 6 | 325-pin ceramic PGA |
| SMJ320C40GFM50 | 5 V | $50 \mathrm{MHz} / 40 \mathrm{~ns}$ | 6 | 325-pin ceramic PGA |
| SMJ320C40HFHM40 | 5 V | $40 \mathrm{MHz} / 50 \mathrm{~ns}$ | 6 | 352-lead ceramic PGA |
| SMJ320C40HFHM50 | 5 V | $50 \mathrm{MHz} / 40 \mathrm{~ns}$ | 6 | 352-lead ceramic PGA |
| SMJ320C40TAM40 | 5 V | $40 \mathrm{MHz} / 50 \mathrm{~ns}$ | 6 | 324 pad TAB tape (encapsulated) |
| SMJ320C40TBM40 | 5 V | $40 \mathrm{MHz} / 50 \mathrm{~ns}$ | 6 | 324 pad TAB tape (bare die) |
| TMS320C40TAL50 | 5 V | $50 \mathrm{MHz} / 40 \mathrm{~ns}$ | 6 | 324 pad TAB tape (encapsulated) |
| SMJ320C40TAM50 | 5 V | $50 \mathrm{MHz} / 40 \mathrm{~ns}$ | 6 | 324 pad TAB tape (encapsulated) |
| SMJ320C40TBM50 | 5 V | $50 \mathrm{MHz} / 40 \mathrm{~ns}$ | 6 | 324 pad TAB tape (bare die) |
| TMS320C40TAL60 | 5 V | $60 \mathrm{MHz} / 33 \mathrm{~ns}$ | 6 | 324 pad TAB tape (encapsulated) |
| SMJ320C40KGDM40 | 5 V | $40 \mathrm{MHz} / 50 \mathrm{~ns}$ | 6 | Known Good Die |
| SMJ320C40KGDM50 | 5 V | $50 \mathrm{MHz} / 40 \mathrm{~ns}$ | 6 | Known Good Die |
| TMS320C40KGDL50 | 5 V | $50 \mathrm{MHz} / 40 \mathrm{~ns}$ | 6 | Known Good Die |
| TMS320C40KGDL60 | 5 V | $60 \mathrm{MHz} / 33 \mathrm{~ns}$ | 6 | Known Good Die |

## Table 10-4. Development Support Tools Part Numbers

| Development Tool | Part Number | Platform |
| :---: | :---: | :---: |
| C Compiler/Assembler/Linker | TMDS3243855-02 | PC (DOS, OS/2) |
| C Compiler/Assembler/Linker | TMDS3243255-08 | VAX (VMS) |
| C Compiler/Assembler/Linker | TMDS3243555-08 | SPARC (Sun OS) |
| Assembler/Linker | TMDS3243850-02 | PC (DOS) |
| Simulator (C language) | TMDS3244851-02 | PC (DOS, Windows) |
| Simulator (C language) | TMDS3244551-09 | SPARC (Sun OS) |
| Tartan Floating Point Library | 320FLO-PC-C40 | PC (DOS) |
| Tartan Floating Point Library | 320FLO-SUN-C40 | SPARC (Sun OS) |
| Digital Filter Design Package | DFDP | PC (DOS) |
| C Source Debugger Conversion Software | TMDS3240140 | PC (XDS510) |
| C Source Debugger Conversion Software | TMDS3240640 | Sun (XDS510WS) |
| Emulation Porting Kit | TMDX3240040† | - |
| 'C3x/'C4x Tartan C/C++ Compiler/Assembler/Linker | TAR-CCM-PC | PC (DOS) |
| 'C3x/'C4x Tartan C/C++ Compiler/Assembler/Linker | TAR-CCM-SP | SPARC |
| 'C3x/'C4x Tartan C/C++ Compiler/Assembler/Linker/ Simulator | TAR-SIM-PC | PC (DOS) |
| 'C3x/'C4x Tartan C/C++ Compiler/Assembler/Linker/ Simulator | TAR-SIM-SP | SPARC |
| 'C3x/'C4x Tartan C/C++ XDS510 Debugger | TAR-DEG-XDS-PC | PC (DOS, Windows) |
| 'C3x/'C4x Tartan C/C++ XDS510 Debugger | TAR-DEG-XDS-SP | SPARC (Sun OS) |
| XDS510 Emulator $\ddagger$ | TMDS3260140 | PC (DOS, OS/2, Windows) |
| XDS510WS Emulator§ | TMDS3260640 | Sun (SPARC SCSI) |
| PC/Sparc JTAG Emulation Cable | TMDS3080001 | XDS510/XDS510WS |
| Parallel Processing Development System | TMDX3261040 | XDS510/XDS510WS |

$\dagger$ Requires licensing agreement.
$\ddagger$ Includes XDS510WS box, SCSI cable, power supply, and JTAG cable. TMDS3240640 C-source debugger software not included.
§ Includes XDS510 board and JTAG cable. TMDS3240140 C-source debugger software not included.

# XDS510 Emulator Design Considerations 

This chapter explains the design requirements of the XDS510 emulator with respect to JTAG designs, and discusses the XDS510 cable (manufacturing part number 2617698-0001). This cable is identified by a label on the cable pod marked JTAG $3 / 5 \mathrm{~V}$ and supports both standard 3 -volt and 5 -volt target system power inputs.

The term JTAG, as used in this book, refers to TI scan-based emulation, which is based on the IEEE 1149.1 standard.
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### 11.1 Designing Your Target System's Emulator Connector (14-Pin Header)

JTAG target devices support emulation through a dedicated emulation port. This port is a superset of the IEEE 1149.1 standard and is accessed by the emulator. To communicate with the emulator, your target system must have a 14-pin header (two rows of seven pins) with the connections that are shown in Figure 11-1. Table 11-1 describes the emulation signals.

Figure 11-1. 14-Pin Header Signals and Header Dimensions

| TMS | 1 | 2 | TRST |  |
| :---: | :---: | :---: | :---: | :---: |
| TDI | 3 | 4 | GND | Header Dimensions: |
| TDI | 3 | 4 | GND | Pin-to-pin spacing, 0.100 in ( $\mathrm{X}, \mathrm{Y}$ ) |
| PD ( $\mathrm{V}_{\mathrm{Cc}}$ ) | 5 | 6 | no pin (key) ${ }^{\dagger}$ | Pin width, 0.025-in. square post |
| TDO | 7 | 8 | GND | Pin length, 0.235-in. nominal |
| TCK_RET | 9 | 10 | GND |  |
| TCK | 11 | 12 | GND |  |
| EMU0 | 13 | 14 | EMU1 |  |

$\dagger$ While the corresponding female position on the cable connector is plugged to prevent improper connection, the cable lead for pin 6 is present in the cable and is grounded, as shown in the schematics and wiring diagrams in this document.
Table 11-1. 14-Pin Header Signal Descriptions

| Signal | Description | Emulator ${ }^{\dagger}$ State | Target ${ }^{\dagger}$ State |
| :---: | :---: | :---: | :---: |
| TMS | Test mode select | 0 | 1 |
| TDI | Test data input | 0 | 1 |
| TDO | Test data output | 1 | 0 |
| TCK | Test clock. TCK is a $10.368-\mathrm{MHz}$ clock source from the emulation cable pod. This signal can be used to drive the system test clock | 0 | 1 |
| TRST $\ddagger$ | Test reset | 0 | 1 |
| EMU0 | Emulation pin 0 | 1 | I/O |
| EMU1 | Emulation pin 1 | 1 | I/O |
| $\mathrm{PD}\left(\mathrm{V}_{\mathrm{CC}}\right)$ | Presence detect. Indicates that the emulation cable is connected and that the target is powered up. PD should be tied to $\mathrm{V}_{\mathrm{CC}}$ in the target system. | I | 0 |
| TCK_RET | Test clock return. Test clock input to the emulator. May be a buffered or unbuffered version of TCK. | I | 0 |
| GND | Ground |  |  |

$\dagger$ I = input; $O=$ output
$\ddagger$ Do not use pullup resistors on TRST: it has an internal pulldown device. In a low-noise environment, TRST can be left floating. In a high-noise environment, an additional pulldown resistor may be needed. (The size of this resistor should be based on electrical current considerations.)

Although you can use other headers, recommended parts include:
straight header, unshrouded DuPont Connector Systems part numbers: 65610-114

65611-114
67996-114
67997-114

### 11.2 Bus Protocol

The IEEE 1149.1 specification covers the requirements for the test access port (TAP) bus slave devices and provides certain rules, summarized as follows:
$\square$ The TMS/TDI inputs are sampled on the rising edge of the TCK signal of the device.

- The TDO output is clocked from the falling edge of the TCK signal of the device.

When these devices are daisy-chained together, the TDO of one device has approximately a half TCK cycle setup to the next device's TDI signal. This type of timing scheme minimizes race conditions that would occur if both TDO and TDI were timed from the same TCK edge. The penalty for this timing scheme is a reduced TCK frequency.

The IEEE 1149.1 specification does not provide rules for bus master (emulator) devices. Instead, it states that it expects a bus master to provide bus slave compatible timings. The XDS510 provides timings that meet the bus slave rules.

### 11.3 IEEE 1149.1 Standard

For more information concerning the IEEE 1149.1 standard, contact IEEE Customer Service:

Address: IEEE Customer Service
445 Hoes Lane, PO Box 1331
Piscataway, NJ 08855-1331
Phone: (800) 678-IEEE in the US and Canada
(908) 981-1393 outside the US and Canada

FAX: (908) 981-9667 Telex: 833233

### 11.4 JTAG Emulator Cable Pod Logic

Figure 11-2 shows a portion of the emulator cable pod. These are the functional features of the pod:

- Signals TDO and TCK_RET can be parallel-terminated inside the pod if required by the application. By default, these signals are not terminated.
- Signal TCK is driven with a 74LVT240 device. Because of the high-current drive ( $32 \mathrm{~mA} \mathrm{I}_{\mathrm{OL}} / \mathrm{I}_{\mathrm{OH}}$ ), this signal can be parallel-terminated. If TCK is tied to TCK_RET, then you can use the parallel terminator in the pod.
- Signals TMS and TDI can be generated from the falling edge of TCK_RET, according to the IEEE 1149.1 bus slave device timing rules.
$\square$ Signals TMS and TDI are series-terminated to reduce signal reflections.
- A $10.368-\mathrm{MHz}$ test clock source is provided. You may also provide your own test clock for greater flexibility.

Figure 11-2. JTAG Emulator Cable Pod Interface

$\dagger$ The emulator pod uses TCK_RET as its clock source for internal synchronization. TCK is provided as an optional target system test clock source.

### 11.5 JTAG Emulator Cable Pod Signal Timing

Figure 11-3 shows the signal timings for the emulator cable pod. Table 11-2 defines the timing parameters. These timing parameters are calculated from values specified in the standard data sheets for the emulator and cable pod and are for reference only. Texas Instruments does not test or guarantee these timings.

The emulator pod uses TCK_RET as its clock source for internal synchronization. TCK is provided as an optional target system test clock source.

Figure 11-3. JTAG Emulator Cable Pod Timings


Table 11-2. Emulator Cable Pod Timing Parameters

| No. | Reference | Description | Min | Max | Units |
| :---: | :--- | :--- | ---: | :---: | :---: |
| 1 | $\mathrm{t}_{\mathrm{c}(\mathrm{TCK})}$ | TCK_RET period | 35 | 200 | ns |
| 2 | $\mathrm{t}_{\mathrm{w}(\text { TCKH })}$ | TCK_RET high-pulse duration | 15 | ns |  |
| 3 | $\mathrm{t}_{\mathrm{w}(\text { TCKL })}$ | TCK_RET low-pulse duration | 15 | ns |  |
| 4 | $\mathrm{t}_{\mathrm{d}(\text { TMS })}$ | Delay time, TMS/TDI valid from TCK_RET low | 6 | 20 | ns |
| 5 | $\mathrm{t}_{\text {su(TDO })}$ | TDO setup time to TCK_RET high | 3 | ns |  |
| 6 | $\mathrm{t}_{\mathrm{h}(\text { TDO })}$ | TDO hold time from TCK_RET high | 12 | ns |  |

### 11.6 Emulation Timing Calculations

The following examples help you calculate emulation timings in your system. For actual target timing parameters, see the appropriate device data sheets.

## Assumptions:

| $\mathrm{t}_{\text {su(TTMS }}$ | Target TMS/TDI setup to TCK high | 10 ns |
| :---: | :---: | :---: |
| $t_{d}$ (TTDO) | Target TDO delay from TCK low | 15 ns |
| $\mathrm{t}_{\mathrm{d} \text { (bufmax) }}$ | Target buffer delay, maximum | 10 ns |
| $\mathrm{t}_{\mathrm{d} \text { (bufmin) }}$ | Target buffer delay, minimum | 1 ns |
| ${ }^{\text {t }}$ (bufskew) | Target buffer skew between two devices in the same package: <br> $\left[\mathrm{t}_{\mathrm{d}(\text { bufmax })}-\mathrm{t}_{\mathrm{d}(\text { bufmin) })}\right] \times 0.15$ | 1.35 ns |
| ${ }^{\text {t }}$ (TCKfactor) | Assume a 40/60 duty cycle clock | 0.4 |

## Given in Table 11-2 ( on page 11-5):

| $\mathrm{t}_{\mathrm{d} \text { (TMSmax) }}$ | Emulator TMS/TDI delay from TCK_RET <br> low, maximum | 20 ns |
| :--- | :--- | ---: |
| $\mathrm{t}_{\text {su(TDOmin) }}$ | TDO setup time to emulator TCK_RET <br> high, minimum | 3 ns |
|  |  |  |

There are two key timing paths to consider in the emulation design:

- The TCK_RET-to-TMS/TDI path, called $t_{\text {pd(TCK_RET-TMS/TDI) }}$

The TCK_RET-to-TDO path, called $\mathrm{t}_{\text {pd }}$ (TCK_RET-TDO)
Of the following two cases, the worst-case path delay is calculated to determine the maximum system test clock frequency.
Case 1: $\quad$ Single processor, direct connection, TMS/TDI timed from TCK_RET low.

$$
\begin{aligned}
\mathrm{t}_{\text {pd (TCK_RET-TMS/TDI) }} & =\frac{\left[\mathrm{t}_{\mathrm{d}(\text { TMSmax }}+\mathrm{t}_{\text {su }} \text { (TTMS }\right)}{} \mathrm{t}_{\text {(TCKfactor) }} \\
& =\frac{[20 \mathrm{~ns}+10 \mathrm{~ns}]}{0.4} \\
& =75 \mathrm{~ns}(13.3 \mathrm{MHz}) \\
\mathrm{t}_{\text {pd (TCK_RET-TDO })} & =\frac{\left[\mathrm{t}_{\mathrm{d}(\text { TTDO })}+\mathrm{t}_{\text {su (TDOmin })}\right]}{\mathrm{t}_{(\text {TCKfactor })}} \\
& =\frac{[15 \mathrm{~ns}+3 \mathrm{~ns}]}{0.4} \\
& =45 \mathrm{~ns}(22.2 \mathrm{MHz})
\end{aligned}
$$

In this case, the TCK_RET-to-TMS/TDI path is the limiting factor.

Case 2: Single/multiprocessor, TMS/TDI/TCK buffered input, TDO buffered output, TMS/TDI timed from TCK_RET low.

$$
\begin{aligned}
\mathrm{t}_{\text {pd (TCK_RET-TMS/TDI) }} & =\frac{\left\lfloor\mathrm{t}_{\mathrm{d}(\text { TMSmax })}+\mathrm{t}_{\text {su (TTMS) }}+\mathrm{t}_{\text {(bufskew) }}\right\rfloor}{\mathrm{t}_{\text {(TCKfactor) }}} \\
& =\frac{[20 \mathrm{~ns}+10 \mathrm{~ns}+1.35 \mathrm{~ns}]}{0.4} \\
& =78.4 \mathrm{~ns}(12.7 \mathrm{MHz}) \\
\mathrm{t}_{\text {pd (TCK_RET-TDO) }} & =\frac{\left[\mathrm{t}_{\mathrm{d} \text { (TTDO) }}+\mathrm{t}_{\text {su (TDOmin) }}+\mathrm{t}_{\mathrm{d} \text { (bufmax) }}\right]}{\mathrm{t}_{\text {(TCKfactor) }}} \\
& =\frac{[15 \mathrm{~ns}+3 \mathrm{~ns}+10 \mathrm{~ns}]}{0.4} \\
& =70 \mathrm{~ns}(14.3 \mathrm{MHz})
\end{aligned}
$$

In this case, the TCK_RET-to-TMS/TDI path is the limiting factor.
In a multiprocessor application, it is necessary to ensure that the EMU0-1 lines can go from a logic low level to a logic high level in less than $10 \mu \mathrm{~s}$. This can be calculated as follows:
$t_{r}$

$$
\begin{aligned}
& =5\left(R_{\text {pullup }} \times N_{\text {devices }} \times \text { Cload_per_device }\right) \\
& =5(4.7 \mathrm{k} \Omega \times 16 \times 15 \mathrm{pF}) \\
& =5.64 \mu \mathrm{~s}
\end{aligned}
$$

### 11.7 Connections Between the Emulator and the Target System

It is extremely important to provide high-quality signals between the emulator and the JTAG target system. Depending upon the situation, you must supply the correct signal buffering, test clock inputs, and multiple processor interconnections to ensure proper emulator and target system operation.

Signals applied to the EMU0 and EMU1 pins on the JTAG target device can be either input or output (I/O). In general, these two pins are used as both input and output in multiprocessor systems to handle global run/stop operations. EMU0 and EMU1 signals are applied only as inputs to the XDS510 emulator header.

### 11.7.1 Buffering Signals

If the distance between the emulation header and the JTAG target device is greater than six inches, the emulation signals must be buffered. If the distance is less than six inches, no buffering is necessary. The following illustrations depict these two situations.
$\square$ No signal buffering. In this situation, the distance between the header and the JTAG target device should be no more than six inches.


The EMU0 and EMU1 signals must have pullup resistors connected to $\mathrm{V}_{\mathrm{CC}}$ to provide a signal rise time of less than $10 \mu \mathrm{~s}$. A $4.7-\mathrm{k} \Omega$ resistor is suggested for most applications.

Buffered transmission signals. In this situation, the distance between the emulation header and the processor is greater than six inches. Emulation signals TMS, TDI, TDO, and TCK_RET are buffered through the same package.


- The EMU0 and EMU1 signals must have pullup resistors connected to $V_{C C}$ to provide a signal rise time of less than $10 \mu \mathrm{~s}$. A $4.7-\mathrm{k} \Omega$ resistor is suggested for most applications.
- The input buffers for TMS and TDI should have pullup resistors connected to $\mathrm{V}_{\mathrm{CC}}$ to hold these signals at a known value when the emulator is not connected. A resistor value of $4.7 \mathrm{k} \Omega$ or greater is suggested.

■ To have high-quality signals (especially the processor TCK and the emulator TCK_RET signals), you may have to employ special care when routing the PWB trace. You also may have to use termination resistors to match the trace impedance. The emulator pod provides optional internal parallel terminators on the TCK_RET and TDO. TMS and TDI provide fixed series termination.

■ Since TRST is an asynchronous signal, it should be buffered as needed to insure sufficient current to all target devices.

### 11.7.2 Using a Target-System Clock

Figure 11-4 shows an application with the system test clock generated in the target system. In this application, the TCK signal is left unconnected.

Figure 11-4. Target-System-Generated Test Clock


Note: When the TMS/TDI lines are buffered, pullup resistors should be used to hold the buffer inputs at a known level when the emulator cable is not connected.

There are two benefits to having the target system generate the test clock:

- The emulator provides only a single $10.368-\mathrm{MHz}$ test clock. If you allow the target system to generate your test clock, you can set the frequency to match your system requirements.
- In some cases, you may have other devices in your system that require a test clock when the emulator is not connected. The system test clock also serves this purpose.


### 11.7.3 Configuring Multiple Processors

Figure 11-5 shows a typical daisy-chained multiprocessor configuration, which meets the minimum requirements of the IEEE 1149.1 specification. The emulation signals in this example are buffered to isolate the processors from the emulator and provide adequate signal drive for the target system. One of the benefits of this type of interface is that you can generally slow down the test clock to eliminate timing problems. You should follow these guidelines for multiprocessor support:
$\square$ The processor TMS, TDI, TDO, and TCK signals should be buffered through the same physical package for better control of timing skew.
$\square$ The input buffers for TMS, TDI, and TCK should have pullup resistors connected to $\mathrm{V}_{\mathrm{CC}}$ to hold these signals at a known value when the emulator is not connected. A resistor value of $4.7 \mathrm{k} \Omega$ or greater is suggested.
$\square$ Buffering EMU0 and EMU1 is optional but highly recommended to provide isolation. These are not critical signals and do not have to be buffered through the same physical package as TMS, TCK, TDI, and TDO. Unbuffered and buffered signals are shown in this section (page 11-8 and page 11-9).

Figure 11-5. Multiprocessor Connections


### 11.8 Mechanical Dimensions for the 14-Pin Emulator Connector

The JTAG emulator target cable consists of a 3-foot section of jacketed cable, an active cable pod, and a short section of jacketed cable that connects to the target system. The overall cable length is approximately 3 feet 10 inches. Figure 11-6 and Figure 11-7 (page 11-13) show the mechanical dimensions for the target cable pod and short cable. Note that the pin-to-pin spacing on the connector is 0.100 inches in both the $X$ and $Y$ planes. The cable pod box is nonconductive plastic with four recessed metal screws.

Figure 11-6. Pod/Connector Dimensions


Note: All dimensions are in inches and are nominal dimensions, unless otherwise specified.

Figure 11-7. 14-Pin Connector Dimensions


Note: All dimensions are in inches and are nominal dimensions, unless otherwise specified.

### 11.9 Emulation Design Considerations

This section describes the scan path linker (SPL), which can simultaneously add all four secondary JTAG scan paths to the main scan path. It also describes how to use the emulation pins and configure multiple processors.

### 11.9.1 Using Scan Path Linkers

You can use the TI ACT8997 scan path linker (SPL) to divide the JTAG emulation scan path into smaller, logically connected groups of 4 to 16 devices. As described in the Advanced Logic and Bus Interface Logic Data Book (literature number SCYD001), the SPL is compatible with the JTAG emulation scanning. The SPL is capable of adding any combination of its four secondary scan paths into the main scan path.

A system of multiple, secondary JTAG scan paths has better fault tolerance and isolation than a single scan path. Since an SPL has the capability of adding all secondary scan paths to the main scan path simultaneously, it can support global emulation operations, such as starting or stopping a selected group of processors.

TI emulators do not support the nesting of SPLs (for example, an SPL connected to the secondary scan path of another SPL). However, you can have multiple SPLs on the main scan path.

Although the ACT8999 scan path selector is similar to the SPL, it can add only one of its secondary scan paths at a time to the main JTAG scan path. Thus, global emulation operations are not assured with the scan path selector. For this reason, scan path selectors are not supported.

You can insert an SPL on a backplane so that you can add up to four device boards to the system without the jumper wiring required with nonbackplane devices. You connect an SPL to the main JTAG scan path in the same way you connect any other device. Figure 11-8 shows you how to connect a secondary scan path to an SPL.

Figure 11-8. Connecting a Secondary JTAG Scan Path to an SPL


The TRST signal from the main scan path drives all devices, even those on the secondary scan paths of the SPL. The TCK signal on each target device on the secondary scan path of an SPL is driven by the SPL's DTCK signal. The TMS signal on each device on the secondary scan path is driven by the respective DTMS signals on the SPL.

DTDO on the SPL is connected to the TDI signal of the first device on the secondary scan path. DTDI on the SPL is connected to the TDO signal of the last device in the secondary scan path. Within each secondary scan path, the TDI signal of a device is connected to the TDO signal of the device before it. If the SPL is on a backplane, its secondary JTAG scan paths are on add-on boards; if signal degradation is a problem, you may need to buffer both the TRST and DTCK signals. Although less likely, you may also need to buffer the DTMSn signals for the same reasons.

### 11.9.2 Emulation Timing Calculations for SPL

The following examples help you to calculate the emulation timings in the SPL secondary scan path of your system. For actual target timing parameters, see the appropriate device data sheets.

## Assumptions:

| $\mathrm{t}_{\text {su(TTMS) }}$ | Target TMS/TDI setup to TCK high | 10 ns |
| :--- | :--- | ---: |
| $\mathrm{t}_{\mathrm{d} \text { (TTDO) }}$ | Target TDO delay from TCK low | 15 ns |
| $\mathrm{t}_{\mathrm{d} \text { (bufmax) }}$ | Target buffer delay, maximum | 10 ns |
| $\mathrm{t}_{\mathrm{d} \text { (bufmin) }}$ | Target buffer delay, minimum | 1 ns |
| $\mathrm{t}_{\text {(bufskew) }}$ | Target buffer skew between two devices <br> in the same package: | 1.35 ns |
|  | $\left[\mathrm{t}_{\mathrm{d}(\text { bufmax })}-\mathrm{t}_{\mathrm{d}(\text { bufmin) })}\right] \times 0.15$ |  |
| $\mathrm{t}_{\text {(TCKfactor) }}$ | Assume a 40/60 duty cycle clock |  |
|  |  | 0.4 |

## Given in the SPL data sheet:

| $t_{d(D T M S m a x)}$ | SPL DTMS/DTDO delay from TCK <br> low, maximum | 31 ns |
| :--- | :--- | :---: |
| $t_{\text {su(DTDLmin) }}$ | DTDI setup time to SPL TCK <br> high, minimum | 7 ns |
| $\mathrm{t}_{\mathrm{d}(\text { (DTCKHmin) }}$ | SPL DTCK delay from TCK <br> high, minimum | 2 ns |
| $\mathrm{t}_{\mathrm{d}(\text { (DTCKLmax })}$ | SPL DTCK delay from TCK <br> low, maximum | 16 ns |

There are two key timing paths to consider in the emulation design:
The TCK-to-DTMS/DTDO path, called $\mathrm{t}_{\text {pd(TCK-DTMS }}$

- The TCK-to-DTDI path, called $\mathrm{t}_{\mathrm{pd}}$ (TCK-DTDI)

Of the following two cases, the worst-case path delay is calculated to determine the maximum system test clock frequency.

Case 1: Single processor, direct connection, DTMS/DTDO timed from TCK low.

$$
\begin{aligned}
\mathrm{t}_{\text {pd (TCK-DTMS })} & =\frac{\left[\mathrm{t}_{\mathrm{d}(\text { DTMSmax })}+\mathrm{t}_{\mathrm{d}(\text { DTCKHmin })}+\mathrm{t}_{\mathrm{su}(\text { TTMS })}\right]}{\mathrm{t}_{(\text {TCKfactor })}} \\
& =\frac{[31 \mathrm{~ns}+2 \mathrm{~ns}+10 \mathrm{~ns}]}{0.4} \\
& =107.5 \mathrm{~ns}(9.3 \mathrm{MHz}) \\
\mathrm{t}_{\text {pd (TCK-DTDI })} & =\frac{\left[\mathrm{t}_{\mathrm{d}(\text { TTDO })}+\mathrm{t}_{\mathrm{d}(\text { DTCKLmax })}+\mathrm{t}_{\text {su (DTDLmin })}\right]}{\mathrm{t}_{(\text {TCKfactor })}} \\
& =\frac{[15 \mathrm{~ns}+16 \mathrm{~ns}+7 \mathrm{~ns}]}{0.4} \\
& =9.5 \mathrm{~ns}(10.5 \mathrm{MHz})
\end{aligned}
$$

In this case, the TCK-to-DTMS/DTDL path is the limiting factor.
Case 2: Single/multiprocessor, DTMS/DTDO/TCK buffered input, DTDI buffered output, DTMS/DTDO timed from TCK low.

$$
\begin{aligned}
\mathrm{t}_{\text {pd (TCK-TDMS) }} & =\frac{\left[\mathrm{t}_{\mathrm{d}(\text { DTMSmax })}+\mathrm{t}_{(\text {DTCKHmin })}+\mathrm{t}_{\text {su (TTMS) }}+\mathrm{t}_{\text {(bufskew) }}\right]}{\mathrm{t}_{(\text {TCKfactor })}} \\
& =\frac{[31 \mathrm{~ns}+2 \mathrm{~ns}+10 \mathrm{~ns}+1.35 \mathrm{~ns}]}{0.4} \\
& =110.9 \mathrm{~ns}(9.0 \mathrm{MHz}) \\
\mathrm{t}_{\text {pd (TCK-DTDI) }} & =\frac{\left[\mathrm{t}_{\mathrm{d}(\text { TTDO })}+\mathrm{t}_{\mathrm{d}(\text { DTCKLmax }}+\mathrm{t}_{\text {su (DTDLmin) }}+\mathrm{t}_{\mathrm{d} \text { (bufskew) }}\right.}{\mathrm{t}_{\text {(TCKfactor) }}} \\
& =\frac{[15 \mathrm{~ns}+15 \mathrm{~ns}+7 \mathrm{~ns}+10 \mathrm{~ns}]}{0.4} \\
& =120 \mathrm{~ns}(8.3 \mathrm{MHz)}
\end{aligned}
$$

In this case, the TCK-to-DTDI path is the limiting factor.

### 11.9.3 Using Emulation Pins

The EMU0/1 pins of TI devices are bidirectional, three-state output pins. When in an inactive state, these pins are at high impedance. When the pins are active, they function in one of the two following output modes:

## - Signal Event

The EMU0/1 pins can be configured via software to signal internal events. In this mode, driving one of these pins low can cause devices to signal such events. To enable this operation, the EMU0/1 pins function as opencollector sources. External devices such as logic analyzers can also be connected to the EMUO/1 signals in this manner. If such an external source is used, it must also be connected via an open-collector source.

## - External Count

The EMUO/1 pins can be configured via software as totem-pole outputs for driving an external counter. These devices can be damaged if the output of more than one device is configured for totem-pole operation. The emulation software detects and prevents this condition. However, the emulation software has no control over external sources on the EMU0/1 signal. Therefore, all external sources must be inactive when any device is in the external count mode.

TI devices can be configured by software to halt processing if their EMU0/1 pins are driven low. This feature, in combination with the use of the signal event output mode, allows one TI device to halt all other TI devices on a given event for system-level debugging.

If you route the EMU0/1 signals between boards, they require special handling because these signals are more complex than normal emulation signals. Figure 11-9 shows an example configuration that allows any processor in the system to stop any other processor in the system. Do not tie the EMU0/1 pins of more than 16 processors together in a single group without using buffers. Buffers provide the crisp signals that are required during a RUNB (run benchmark) debugger command or when the external analysis counter feature is used.

Figure 11-9. EMUO/1 Configuration


Notes: 1) The low time on EMUx-IN should be at least one TCK cycle and less than $10 \mu$ s. Software will set the EMUx-OUT pin to a high state.
2) To enable the open-collector driver and pullup resistor on EMU1 to provide rising/falling edges of less than 25 ns , the modification shown in this figure is suggested. Rising edges slower than 25 ns can cause the emulator to detect false edges during the RUNB command or when the external counter selected from the debugger analysis menu is used.

These seven important points apply to the circuitry shown in Figure 11-9 and the timing shown in Figure 11-10:

- Open-collector drivers isolate each board. The EMU0/1 pins are tied together on each board.
$\square$ At the board edge, the EMU0/1 signals are split to provide IN/OUT. This is required to prevent the open-collector drivers from acting as a latch that can be set only once.
- The EMU0/1 signals are bused down the backplane. Pullup resistors are installed as required.
- The bused EMUO/1 signals go into a PAL ${ }^{\circledR}$ device whose function is to generate a low pulse on the EMU0/1-IN signal when a low level is detected
on the EMU0/1-OUT signal. This pulse must be longer than one TCK period to affect the devices, but less than $10 \mu$ s to avoid possible conflicts or retriggering, once the emulation software clears the device's pins.
- During a RUNB debugger command or other external analysis count, the EMU0/1 pins on the target device become totem-pole outputs. The EMU1 pin is a ripple carry-out of the internal counter. EMUO becomes a processor-halted signal. During a RUNB or other external analysis count, the EMU0/1-IN signal to all boards must remain in the high (disabled) state. You must provide some type of external input (XCNT_ENABLE) to the PAL to disable the PAL from driving EMU0/1-IN to a low state.
- If sources other than TI processors (such as logic analyzers) are used to drive EMU0/1, their signal lines must be isolated by open-collector drivers and be inactive during RUNB and other external analysis counts.
- You must connect the EMU0/1-OUT signals to the emulation header or directly to a test bus controller.

Figure 11-10. Suggested Timings for the EMUO and EMU1 Signals
TCK
EMU0/1-OUT

EMU0/1-IN


Figure 11-11. EMUO/1 Configuration With Additional AND Gate to Meet Timing Requirements


Notes: 1) The low time on EMUx-IN should be at least one TCK cycle and less than $10 \mu \mathrm{~s}$. Software will set the EMUx-OUT pin to a high state.
2) To enable the open-collector driver and pullup resistor on EMU1 to provide rising/falling edges of less than 25 ns , the modification shown in this figure is suggested. Rising edges slower than 25 ns can cause the emulator to detect false edges during the RUNB command or when the external counter selected from the debugger analysis menu is used.

If it is not important that the devices on one target board are stopped by devices on another target board via the EM0/1, then the circuit in Figure 11-12 can be used. In this configuration, the global-stop capability is lost. It is important not to overload EMU0/1 with more than 16 devices.

Figure 11-12.EMU0/1 Configuration Without Global Stop


Note: The open-collector driver and pullup resistor on EMU1 must be able to provide rising/falling edges of less than 25 ns . Rising edges slower than 25 ns can cause the emulator to detect false edges during the RUNB command or when the external counter selected from the debugger analysis menu is used. If this condition cannot be met, then the EMU0/1 signals from the individual boards should be ANDed together (as shown in Figure 1-11) to produce an EMU0/1 signal for the emulator.

### 11.9.4 Performing Diagnostic Applications

For systems that require built-in diagnostics, it is possible to connect the emulation scan path directly to a TI ACT8990 test bus controller (TBC) instead of the emulation header. The TBC is described in the Texas Instruments Advanced Logic and Bus Interface Logic Data Book (literature number SCYD001). Figure 11-13 shows the scan path connections of $n$ devices to the TBC.

Figure 11-13. TBC Emulation Connections for $n$ JTAG Scan Paths


In the system design shown in Figure 1-13, the TBC emulation signals TCKI, TDO, TMS0, TMS2/EVNT0, TMS3/EVNT1, TMS5/EVNT3, TCKO, and TDIO are used, and TMS1, TMS4/EVNT2, and TDI1 are not connected. The target devices' EMU0 and EMU1 signals are connected to $\mathrm{V}_{\mathrm{CC}}$ through pullup resistors and tied to the TBC's TMS2/EVNT0 and TMS3/EVNT1 pins, respectively. The TBC's TCKI pin is connected to a clock generator. The TCK signal for the main JTAG scan path is driven by the TBC's TCKO pin.

On the TBC, the TMSO pin drives the TMS pins on each device on the main JTAG scan path. TDO on the TBC connects to TDI on the first device on the main JTAG scan path. TDIO on the TBC is connected to the TDO signal of the last device on the main JTAG scan path. Within the main JTAG scan path, the TDI signal of a device is connected to the TDO signal of the device before it. TRST for the devices can be generated either by inverting the TBC's TMS5/EVNT3 signal for software control or by logic on the board itself.

## Glossary

## A

A0-A30: External address pins for data/program memory or I/O devices. These pins are on the global bus. See also LAO-LA3O.
address: The location of program code or data stored in memory.
addressing mode: The method by which an instruction interprets its operands to acquire the data it needs.

## ALU: See Arithmetic logic unit.

analog-to-digital (A/D) converter: A successive-approximation converter with internal sample-and-hold circuitry used to translate an analog signal to a digital signal.

ARAU: See auxiliary register arithmetic unit.
arithmetic logic unit (ALU): The part of the CPU that performs arithmetic and logic operations.
auxiliary registers (ARn): A set of registers used primarily in address generation.
auxiliary register arithmetic unit (ARAU): Auxiliary register arithmetic unit. A16-bit arithmetic logic unit (ALU) used to calculate indirect addresses using the auxiliary registers as inputs and outputs.

B
bit-reversed addressing: Addressing in which several bits of an address are reversed in order to speed processing of algorithms, such as Fourier transforms.

BK: See block-size register.
block-size register: A register used for defining the length of a program block to be repeated in repeat mode.
bootloader: A built-in segment of code that transfers code from an external memory or from a communication port to RAM at power-up.
carry bit: A bit in status register ST1 used by the ALU for extended arithmetic operations and accumulator shifts and rotates. The carry bit can be tested by conditional instructions.
circular addressing: An addressing mode in which an auxiliary register is used to cycle through a range of addresses to create a circular buffer in memory.
context save/restore: A save/restore of system status (status registers, accumulator, product register, temporary register, hardware stack, and auxiliary registers, etc.) when the device enters/exits a subroutine such as an interrupt service routine.

CPU: Central processing unit. The unit that coordinates the functions of a processor.

CPU cycle: The time it takes the CPU to go through one logic phase (during which internal values are changed) and one latch phase (during which the values are held constant).
cycle: See CPU cycle.

D0-D31: External data bus pins that transfer data between the processor and external data/program memory or I/O devices. See also LDO-LD31.
data-address generation logic: Logic circuitry that generates the addresses for data memory reads and writes. This circuitry can generate one address per machine cycle. See also program-address generation logic.
data-page pointer: A seven-bit register used as the seven MSBs in addresses generated using direct addressing.
decode phase: The phase of the pipeline in which the instruction is decoded.

DIE: See DMA interrupt enable register.

DMA coprocessor: A peripheral that transfers the contents of memory locations independently of the processor (except for initialization).

DMA controller: See DMA coprocessor.
DMA interrupt enable register (DIE): A register (in the CPU register file) that controls which interrupts the DMA coprocessor responds to.

DP: See data-page pointer.
dual-access RAM: Memory that can be accessed twice in a single clock cycle. For example, your code can read from and write to a dual-access RAM in one clock cycle.
external interrupt: A hardware interrupt triggered by a pin.
extended-precision floating-point format: A 40-bit representation of a floating-point number with a 32-bit mantissa and an 8-bit exponent.
extended-precision register: A 40-bit register used primarily for extendedprecision floating-point calculations. Floating-point operations use bits 39-0 of an extended-precision register. Integer operations, however, use only bits 31-0.

FIFO buffer: First-in, first-out buffer. A portion of memory in which data is stored and then retrieved in the same order in which it was stored. Thus, the first word stored in this buffer is retrieved first. The 'C4x's communication ports each have two FIFOs: one for transmit operations and one for receive operations.
hardware interrupt: An interrupt triggered through physical connections with on-chip peripherals or external devices.
hit: A condition in which, when the processor fetches an instruction, the instruction is available in the cache.

IACK: Interrupt acknowledge signal. An output signal that indicates that an interrupt has been received and that the program counter is fetching the interrupt vector that will force the processor into an interrupt service routine.

IIE: See internal interrupt enable register.
IIF: See IIOF flag register.
IIOF flag register (IIF): Controls the function (general-purpose I/O or interrupt) of the four external pins ( $\overline{\mathrm{IOFO}}$ to $\overline{\mathrm{IOF}}$ ). It also contains timer/DMA interrupt flags.
index registers: Two registers (IR0 and IR1) that are used by the ARAU for indexing an address.
internal interrupt: A hardware interrupt caused by an on-chip peripheral.
internal interrupt enable register: A register (in the CPU register file) that determines whether or not the CPU will respond to interrupts from the communication ports, the timers, and the DMA coprocessor.
interrupt: A signal sent to the CPU that (when not masked) forces the CPU into a subroutine called an interrupt service routine. This signal can be triggered by an external device, an on-chip peripheral, or an instruction (TRAP, for example).
interrupt acknowledge ( $\overline{\mathrm{IACK}})$ : A signal that indicates that an interrupt has been received, and that the program counter is fetching the interrupt vector location.
interrupt vector table (IVT): An ordered list of addresses which each correspond to an interrupt; when an interrupt occurs and is enabled, the processor executes a branch to the address stored in the corresponding location in the interrupt vector table.
interrupt vector table pointer (IVTP): A register (in the CPU expansion register file) that contains the address of the beginning of the interrupt vector table.

ISR: Interrupt service routine. A module of code that is executed in response to a hardware or software interrupt.

IVTP: See interrupt vector table pointer.

LA0-LA30: External address pins for data/program memory or I/O devices. These pins are on the local bus. See also A0-A30.

LD0-LD31: External data-bus pins that transfer data between the processor and external data/program memory or I/O devices. See also D0-D31.

LSB: Least significant bit. The lowest order bit in a word.
machine cycle: See CPU cycle.
mantissa: A component of a floating-point number consisting of a fraction and a sign bit. The mantissa represents a normalized fraction whose binary point is shifted by the exponent.
maskable interrupt: A hardware interrupt that can be enabled or disabled through software.
memory-mapped register: One of the on-chip registers mapped to addresses in memory. Some of the memory-mapped registers are mapped to data memory, and some are mapped to input/output memory.

MFLOPS: Millions of floating-point operations per second. A measure of floating-point processor speed that counts of the number of floating-point operations made per second.
microcomputer mode: A mode in which the on-chip ROM is enabled. This mode is selected via the MP/ $\overline{M C}$ pin. See also MP/MC pin; microprocessor mode.
microprocessor mode: A mode in which the on-chip ROM is disabled. This mode is selected via the MP/ $\overline{M C}$ pin. See also MP $\overline{M C}$ pin; microcomputer mode.

MIPS: Million instructions-per-second.
miss: A condition in which, when the processor fetches an instruction, it is not available in the cache.

MSB: Most significant bit. The highest order bit in a word.
multiplier: A device that generates the product of two numbers.

## NMI: See Nonmaskable interrupt.

nonmaskable interrupt (NMI): A hardware interrupt that uses the same logic as the maskable interrupts, but cannot be masked. It is often used as a soft reset.
overflow flag (OV) bit: A status bit that indicates whether or not an arithmetic operation has exceeded the capacity of the corresponding register.

P
PC: See program counter.
peripheral bus: A bus that the CPU uses to communicate the DMA coprocessor, communication ports, and timers.
pipeline: A method of executing instructions in an assembly-line fashion.
program counter: A register that contains the address of the next instruction to be fetched.

R
RC: See repeat counter register.
read/write ( $\mathrm{R} / \overline{\mathrm{W}}$ ) pin: This memory-control signal indicates the direction of transfer when communicating to an external device.
register file: A bank of registers.
repeat counter register: A register (in the CPU register file) that specifies the number of times minus one that a block of code is to be repeated when a block repeat is performed.
repeat mode: A zero-overhead method for repeating the execution of a block of code.
reset: A means to bring the central processing unit (CPU) to a known state by setting the registers and control bits to predetermined values and signaling execution to fetch the reset vector.
reset pin: This pin causes the device to reset.
ROMEN: ROM enable. An external pin that determines whether or not the the on-chip ROM is enabled.

## R/W: See read/write pin.

## S

short-floating-point format: A 16-bit representation of a floating-point number with a 12-bit mantissa and a 4-bit exponent.
short-integer format: A twos-complement 16-bit format for integer data.
short-unsigned-integer format: A 16-bit unsigned format for integer data.
sign extend: Fill the high order bits of a number with the sign bit.
single-access RAM: SARAM. Memory that can be read from or written to only once in a single CPU cycle.
single-precision floating-point format: A 32-bit representation of a floating point number with a 24 -bit mantissa and an 8 -bit exponent.
single-precision integer format: A twos-complement 32-bit format for integer data.
single-precision unsigned-integer format: A 32-bit unsigned format for integer data.
software interrupt: An interrupt caused by the execution of a TRAP instruction.
split mode: A mode of operation of the DMA coprocessor. This mode allows one DMA channel to service both the receive and transmit portions of a communication port.

ST: See status register.
stack: A block of memory reserved for storing and retrieving data on a first-in last-out basis. It is usually used for storing return addresses and for preserving register values.
status register: A register (in the CPU register file) that contains global information related to the CPU.

Timer: A programmable peripheral that can be used to generate pulses or to time events.

Timer-Period Register: Timer-period register. A 32-bit memory-mapped register that specifies the period for the on-chip timer.
trap vector table (TVT): An ordered list of addresses which each correspond to an interrupt; when a trap is executed, the processor executes a branch to the address stored in the corresponding location in the trap vector table.
trap vector table pointer (TVTP): A register (in the CPU expansion-register file) that contains the address of the beginning of the trap vector table.

TVTP: See trap vector table pointer.
U
unified mode: A mode of operation of the DMA coprocessor. The mode is used mainly for memory-to-memory transfers. This is the default mode of operation for a DMA channel. See also split mode.
wait state: A period of time that the CPU must wait for external program, data, or I/O memory to respond when reading from or writing to that external memory. The CPU waits one extra cycle for every wait state.
wait-state generator: A program that can be modified to generate a limited number of wait states for a given off-chip memory space (lower program, upper program, data, or I/O).
zero fill: Fill the low or high order bits with zeros when loading a number into a larger field.

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[^0]:    $\dagger$ This corresponds to the 32-bit address that the processor accesses. However, in the 'C44 only the 24-LSBs of the reset address are driven on pins A0-A23 and pins LA0-LA23. The corresponding LSTRBx pins are also activated.

